

Winery CALPELLA N11M-GE Schematics

Mobile Arrandale

Intel Ixex Peak-M

2010-01-18

REV : X-build

DY : Nopop Component

UMA : Pop when schematic is UMA

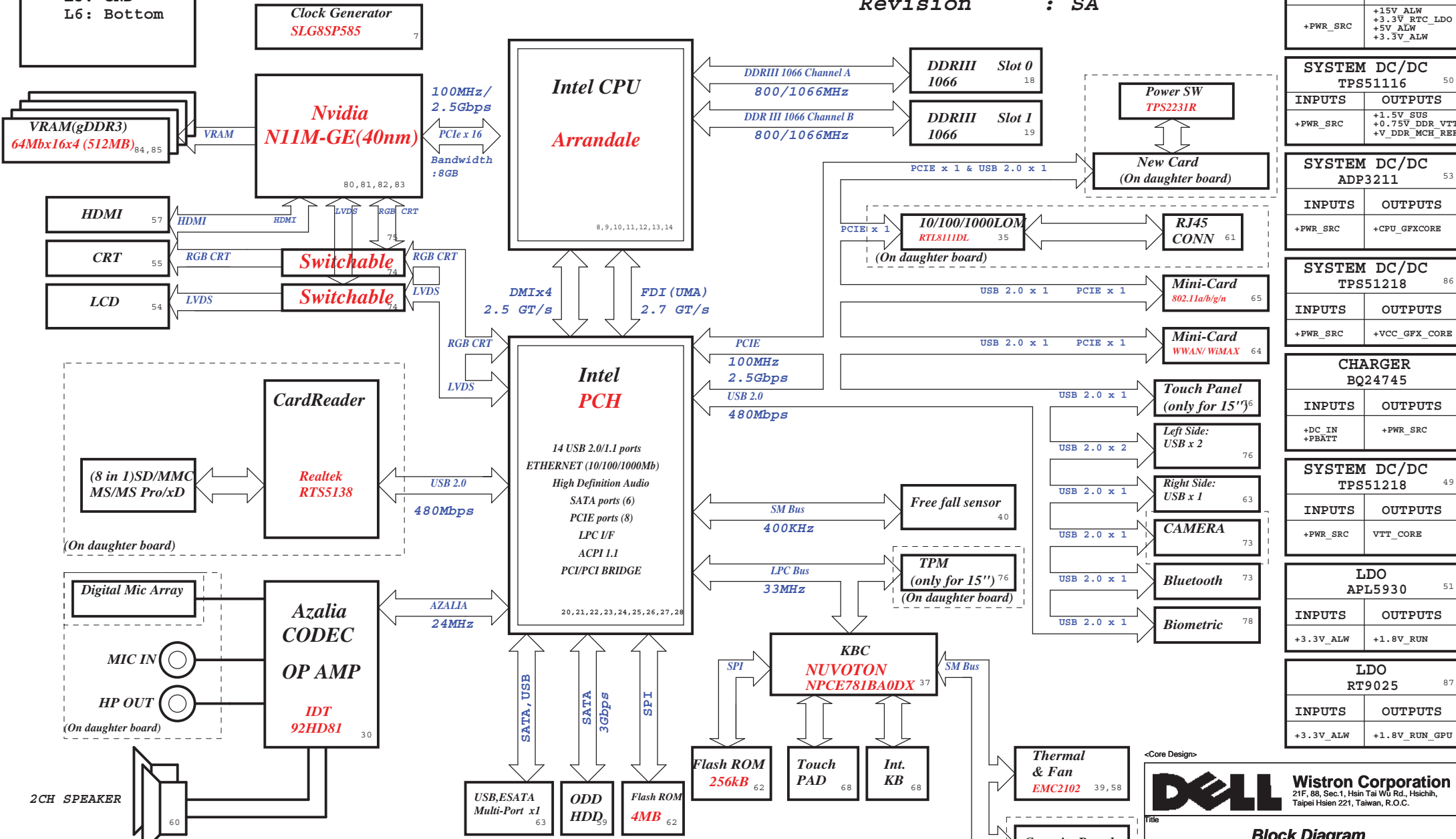
DIS : Pop when schematic is DIS

Winery CALPELLA Block Diagram

Project code : 91.4ES01.001
 Part Number : 48.4ES11.0SB
 PCB P/N : 09297
 Revision : SA

PCB LAYER

L1: Top
 L2: VCC
 L3: Signal
 L4: Signal
 L5: GND
 L6: Bottom



CPU DC/DC ISL62883 47,48	
INPUTS	OUTPUTS
+PWR_SRC	+VCC_CORE

SYSTEM DC/DC TPS51125 46	
INPUTS	OUTPUTS
+PWR_SRC	+15V_ALW +3.3V_RTC_LDO +5V_ALW +3.3V_ALW

SYSTEM DC/DC TPS51116 50	
INPUTS	OUTPUTS
+PWR_SRC	+1.5V_SUS +0.75V_DDR_VTT +V_DDR_MCH_REF

SYSTEM DC/DC ADP3211 53	
INPUTS	OUTPUTS
+PWR_SRC	+CPU GFXCORE

SYSTEM DC/DC TPS51218 86	
INPUTS	OUTPUTS
+PWR_SRC	+VCC_GFX_CORE

CHARGER BQ24745	
INPUTS	OUTPUTS
+DC_IN +PBATT	+PWR_SRC

SYSTEM DC/DC TPS51218 49	
INPUTS	OUTPUTS
+PWR_SRC	VTT_CORE

LDO APL5930 51	
INPUTS	OUTPUTS
+3.3V_ALW	+1.8V_RUN

LDO RT9025 87	
INPUTS	OUTPUTS
+3.3V_ALW	+1.8V_RUN_GPU

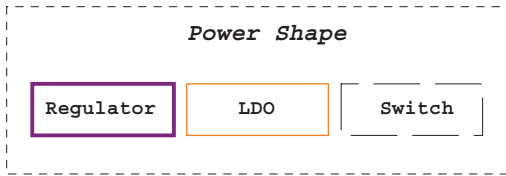
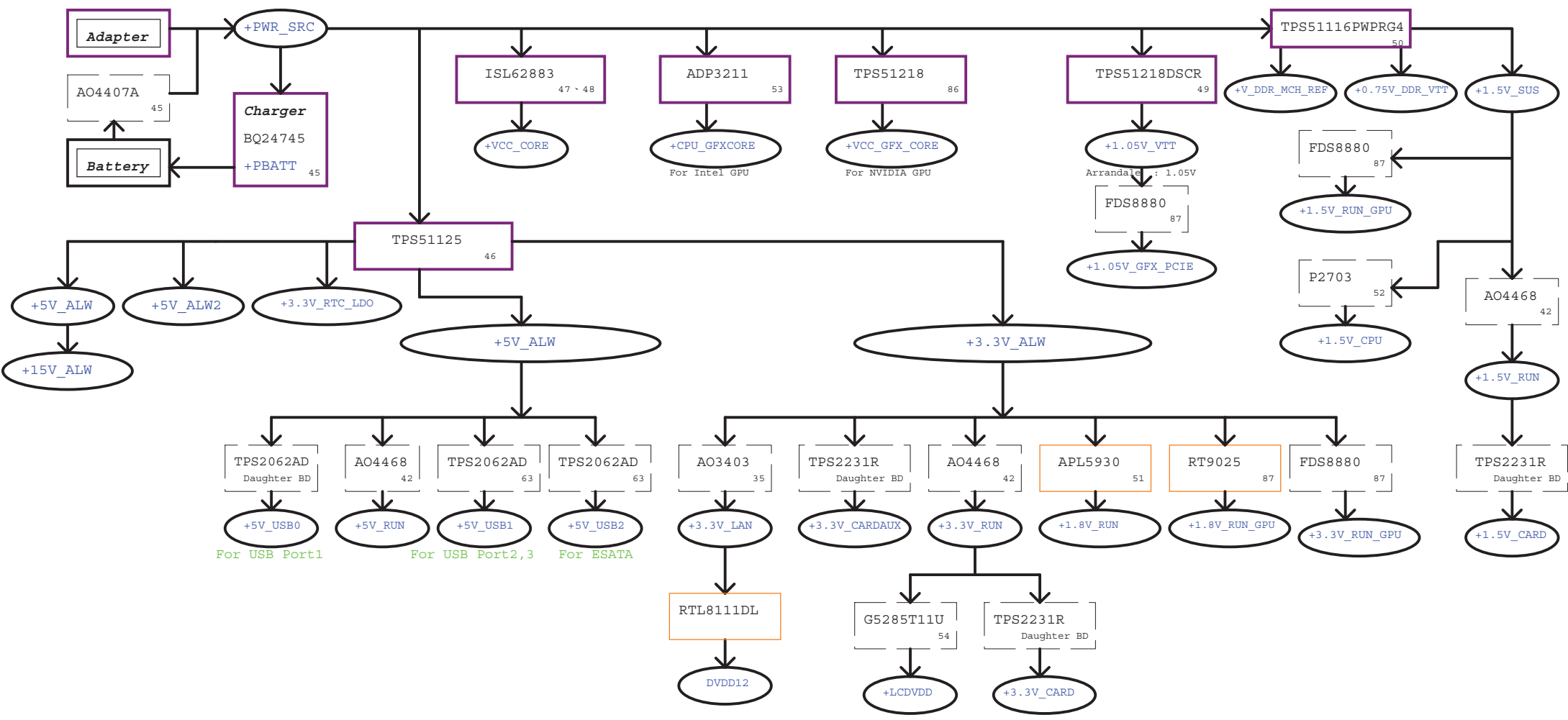
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Block Diagram

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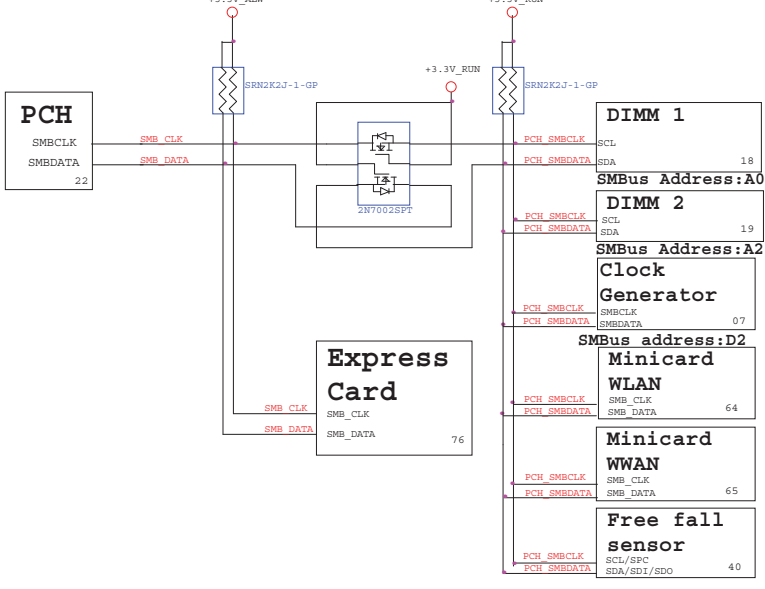
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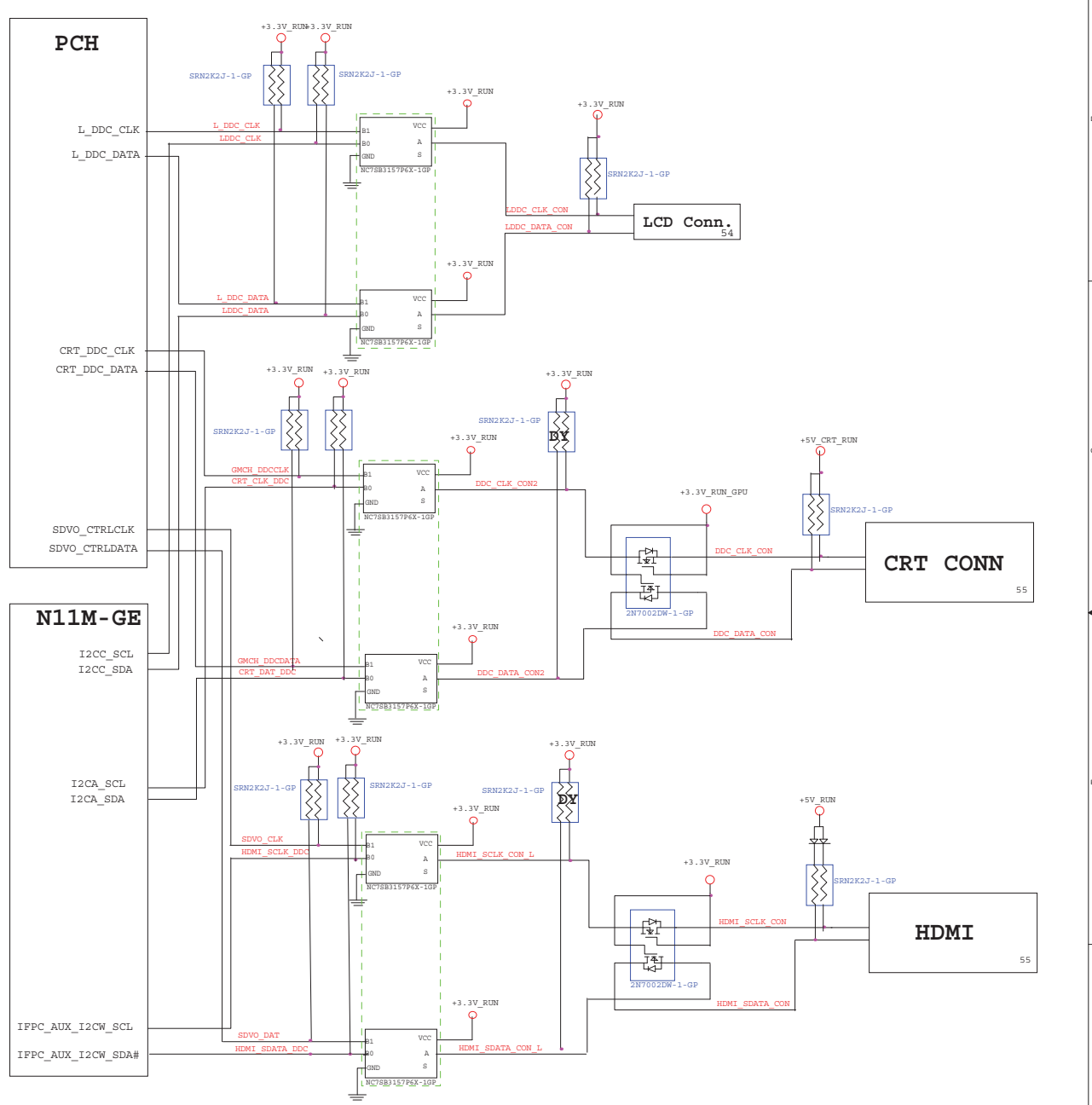
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Size: Custom	Document Number: Vostro Calpella	Rev: X01
Date: Monday, January 18, 2010	Sheet: 3	of 91

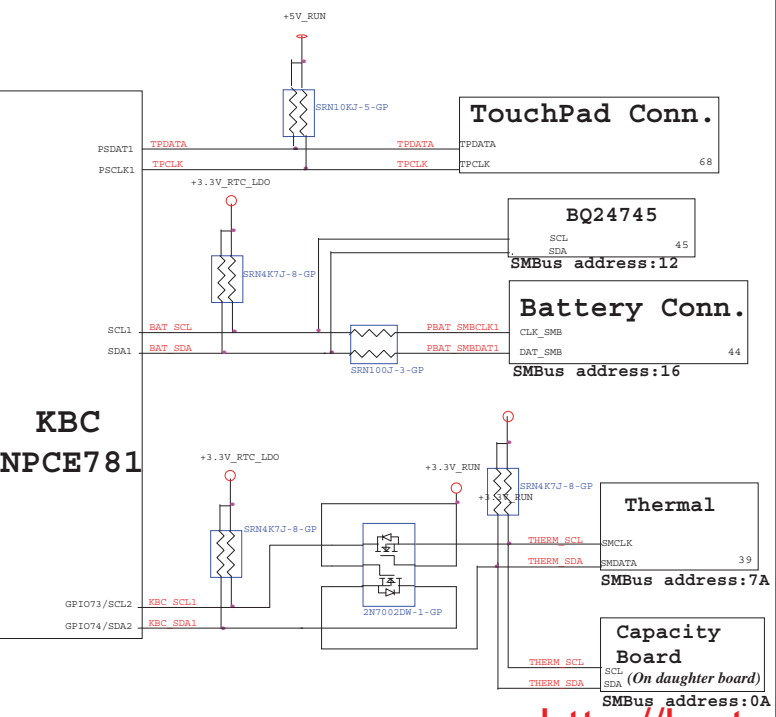
PCH SMBus Block Diagram



Switchable Graphic SMBus Block Diagram



KBC SMBus Block Diagram



<http://laptop-motherboard-schematic.blogspot.com/>

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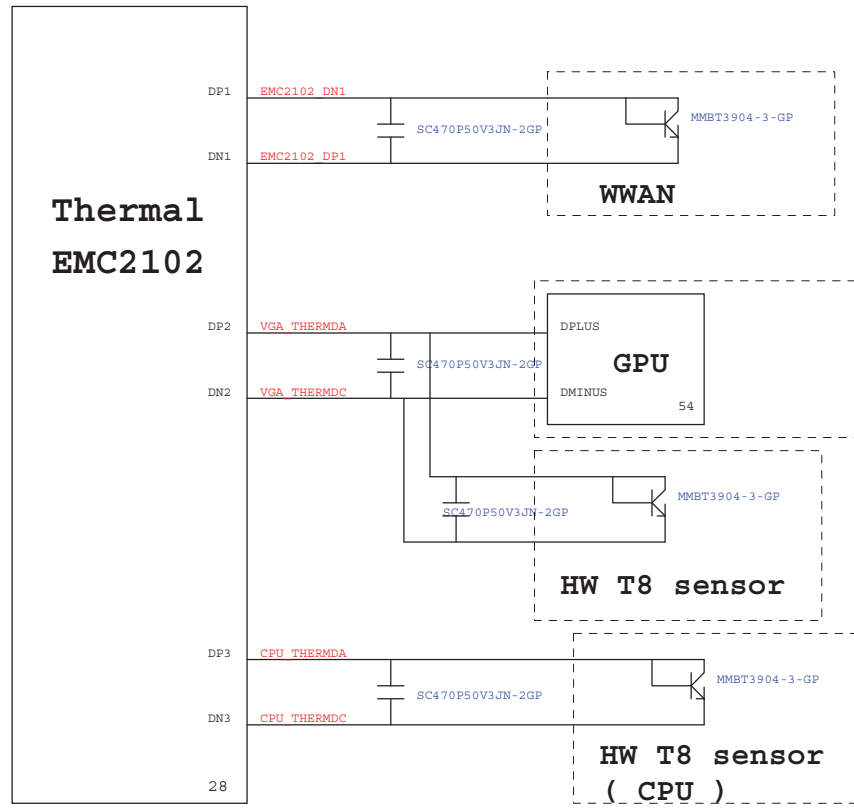
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File: **SMBUS Block Diagram**

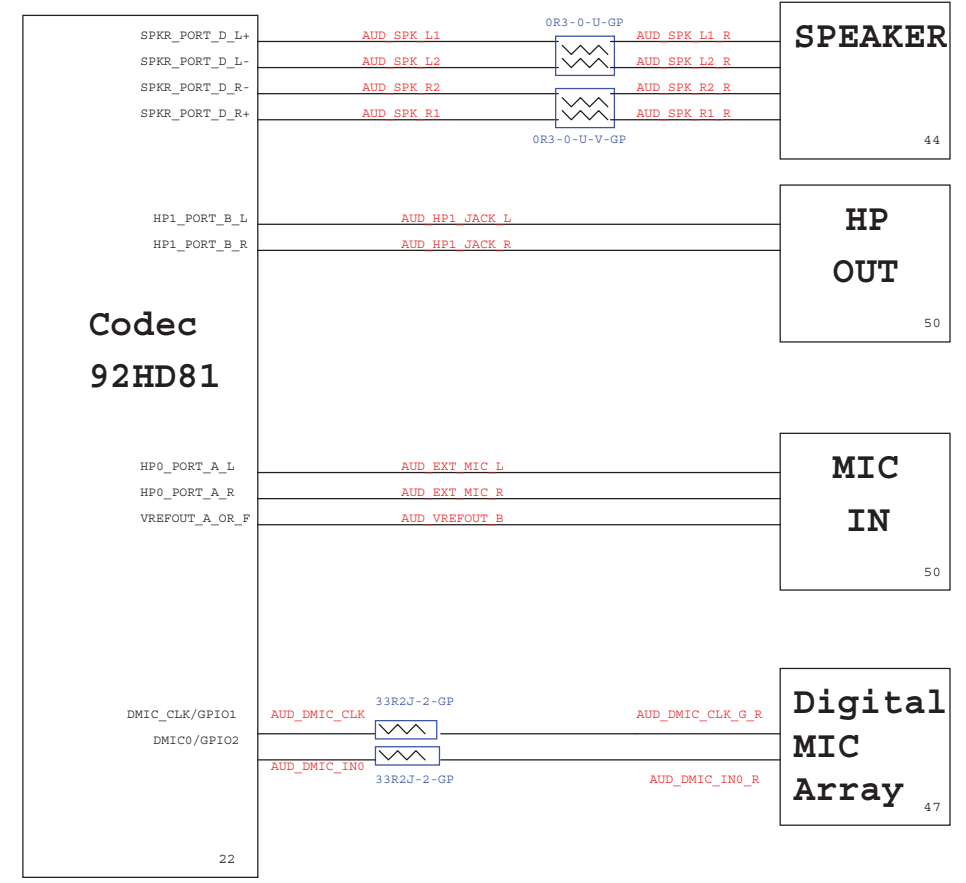
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Thermal Block Diagram



Audio Block Diagram



PCH Strapping

Calpella Schematic Checklist Rev.0_7

Name	Schematics Notes
SPKR	Reboot option at power-up Default Mode: Internal weak Pull-down. No Reboot Mode with TCO Disabled: Connect to Vcc3_3 with 8.2-kΩ - 10-kΩ weak pull-up resistor.
INIT3_3V#	Weak internal pull-down. Do not pull high.
GNT3#/GPIO55	Default Mode: Internal pull-up. Low (0) = Top Block Swap Mode: Connect to ground with 4.7-kΩ weak pull-down resistor. CRB uses a 1 k do not stuff resistor.
INTVRMEN	High (1) = Integrated VRM is enabled Low (0) = Integrated VRM is disabled
GNT0#, GNT1#/GPIO51	Default (SPI): Left both GNT0# and GNT1# floating. No pull up required. Boot from PCI: Connect GNT1# to ground with 1-kΩ pull-down resistor. Leave GNT0# Floating. Boot from LPC: Connect both GNT0# and GNT1# to ground with 1-kΩ pull-down resistor.
GNT2#/GPIO53	Default - Internal pull-up. Low (0) = Configures DMI for ESI compatible operation (for servers only. Not for mobile/desktops).
GPIO33	Default: Do not pull low. Disable ME in Manufacturing Mode: Connect to ground with 1-kΩ pull-down resistor.
SPI_MOSI	Enable iTPM: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable iTPM: Left floating, no pull-down required.
NV_ALE	Enable Danbury: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable Danbury: Connect to ground with 4.7-kΩ weak pull-down resistor.
NC_CLE	Weak internal pull-up. Do not pull low.
HAD_DOCK_EN# /GPIO[33]	Low (0): Flash Descriptor Security will be overridden. High (1) : Flash Descriptor Security will be in effect.
HDA_SDO	Weak internal pull-down. Do not pull high.
HDA_SYNC	Weak internal pull-down. Do not pull high.
GPIO15	Weak internal pull-down. Do not pull high.
GPIO8	Weak internal pull-up. Do not pull low.
GPIO27	Default = Do not connect (floating) High(1) = Enables the internal VccVRM to have a clean supply for analog rails. No need to use on-board filter circuit. Low (0) = Disables the VccVRM. Need to use on-board filter circuits for analog rails.

PCIe Routing

LANE1	Card reader
LANE2	MiniCard WLAN
LANE3	LAN
LANE4	MiniCard WWAN
LANE5	New Card


Processor Strapping

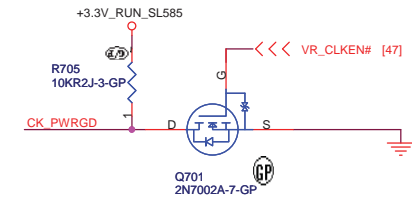
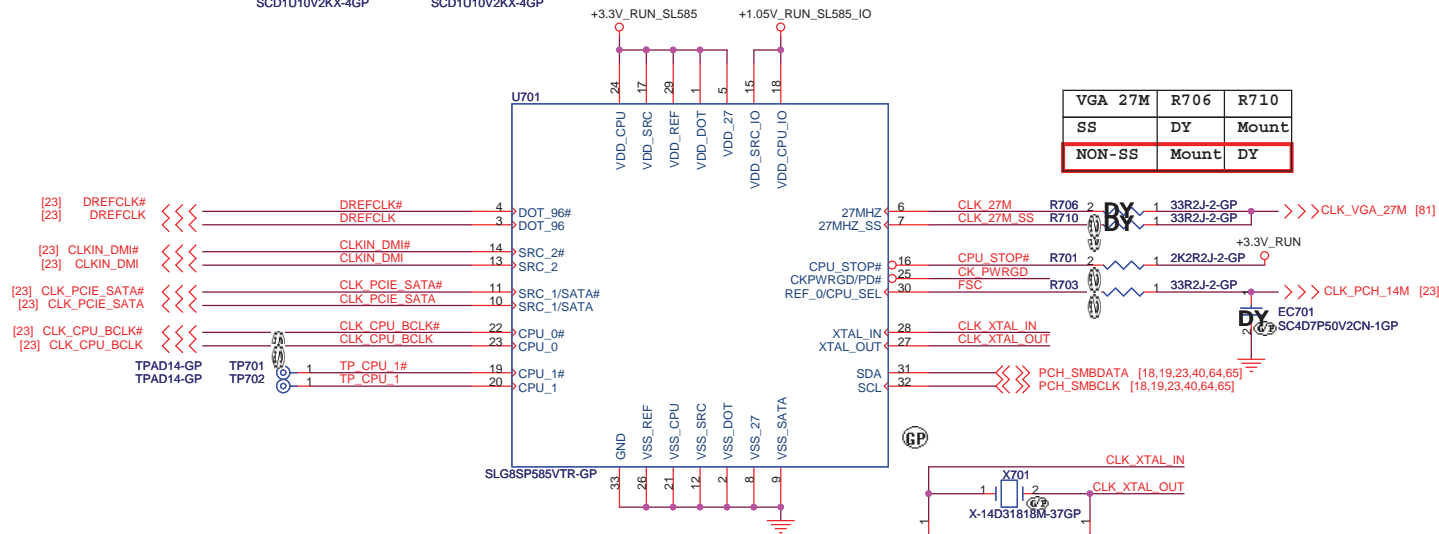
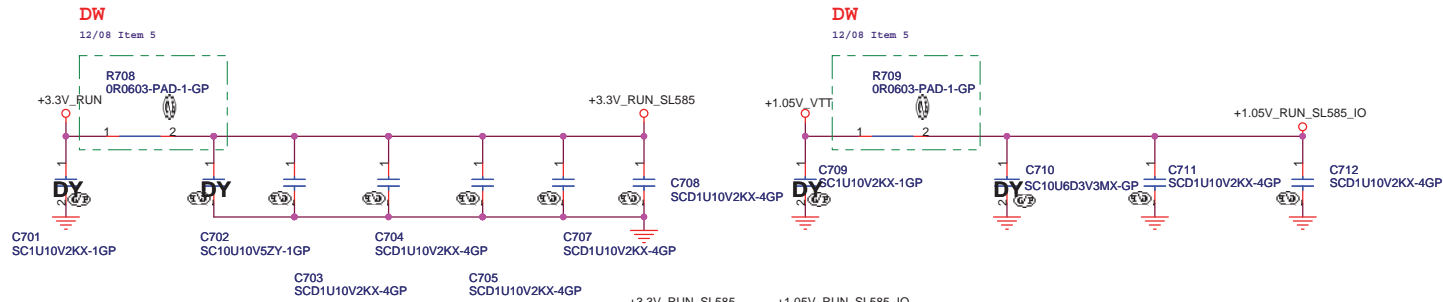
Calpella Schematic Checklist Rev.0_7

Pin Name	Strap Description	Configuration (Default value for each bit is 1 unless specified otherwise)	Default Value
CFG[4]	Embedded DisplayPort Presence	1: Disabled - No Physical Display Port attached to Embedded DisplayPort. 0: Enabled - An external Display Port device is connected to the Embedded Display Port.	1
CFG[3]	PCI-Express Static Lane Reversal	1: Normal Operation. 0: Lane Numbers Reversed 15 -> 0, 14 -> 1, ...	1
CFG[0]	PCI-Express Configuration Select	1: Single PCI-Express Graphics 0: Bifurcation enabled	1
CFG[7]	Reserved - Temporarily used for early Clarksfield samples.	Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor Note: Only temporary for early CFD samples (rPGA/BGA) [For details please refer to the WW33 MoW and sighting report]. For a common motherboard design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.	0

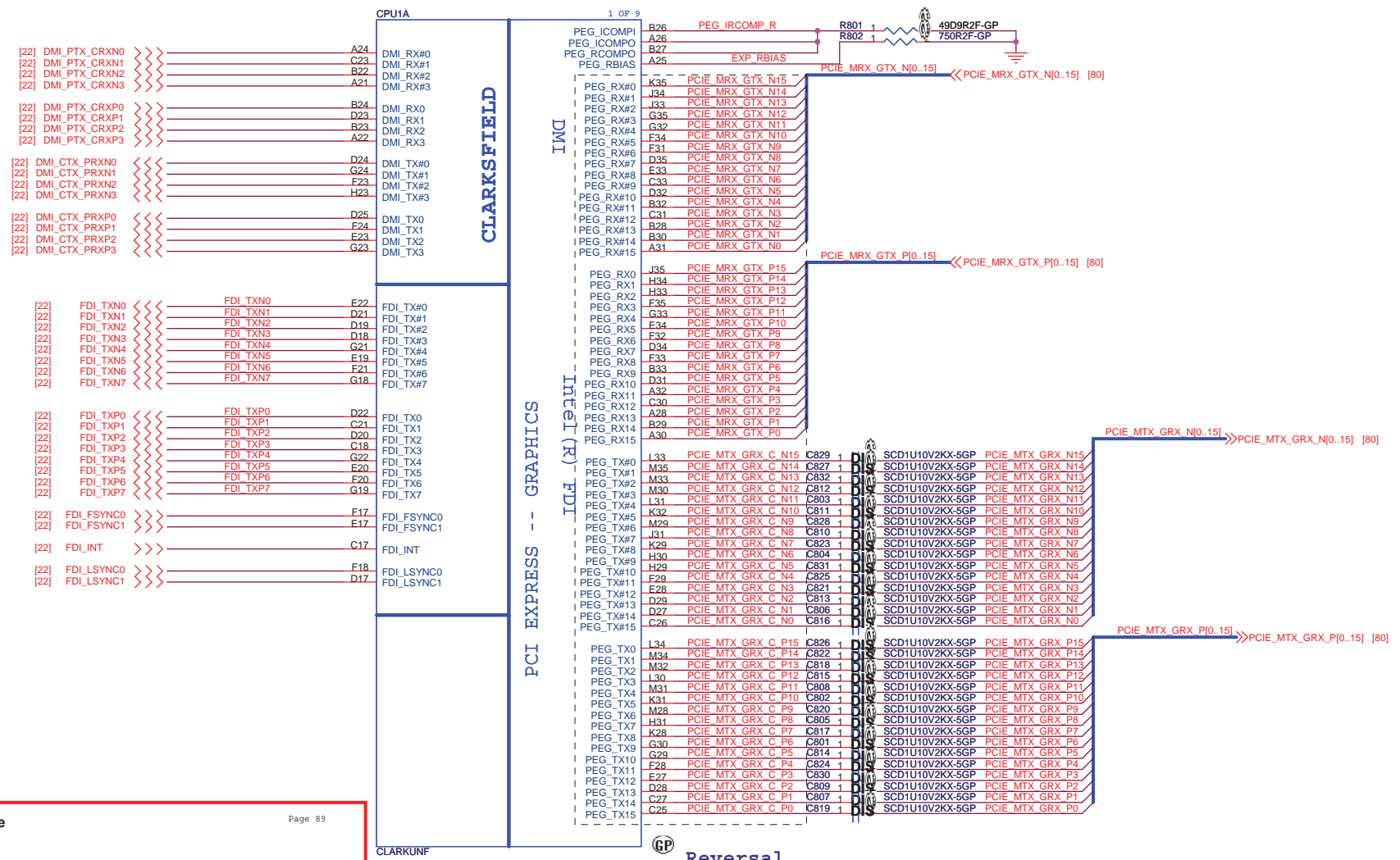
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Title			
Table of Content			
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1st Silego 71.08585.003
2nd ICS 71.93197.003



Calpella Platform Design Guide
 Revision 1.6
 2.4 Arrandale Graphics Disable Guideline
 It applies to Arrandale and Clarksfield discrete graphic designs.
 FDI_TX#[7:0] and FDI_TX#[7:0] can be left floating on the Arrandale. The GFX_IMON, FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1], and FDI_INT signals on the Arrandale side should be tied to GND (through 1-kΩ ±5% resistors).

Reversal
 1. PCI-Express Static Lane Reversal
 (15 -> 0, 14 -> 1, ...)

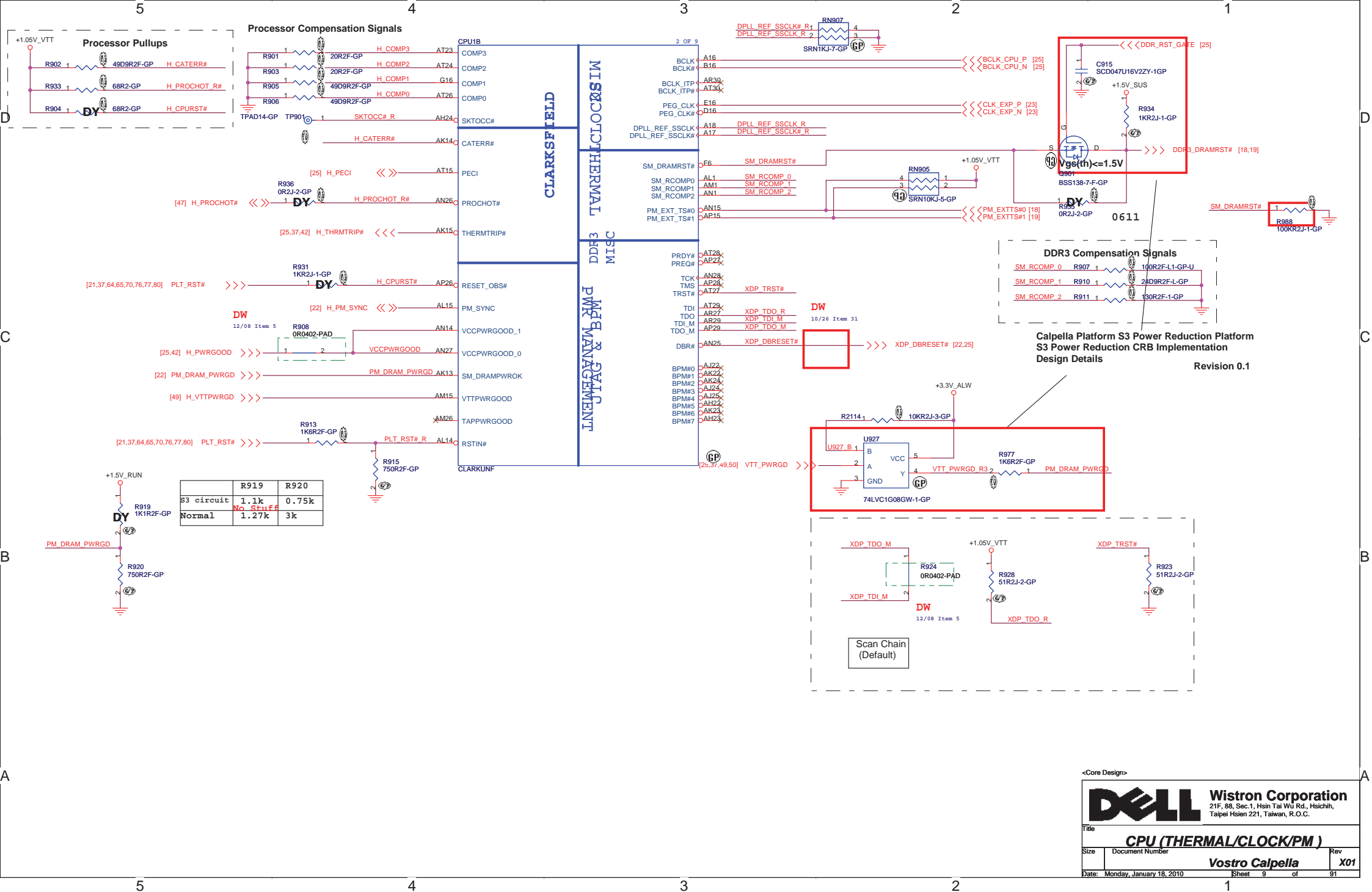
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Title: **CPU (PCIE/DMI/FDI)**

Size: Document Number
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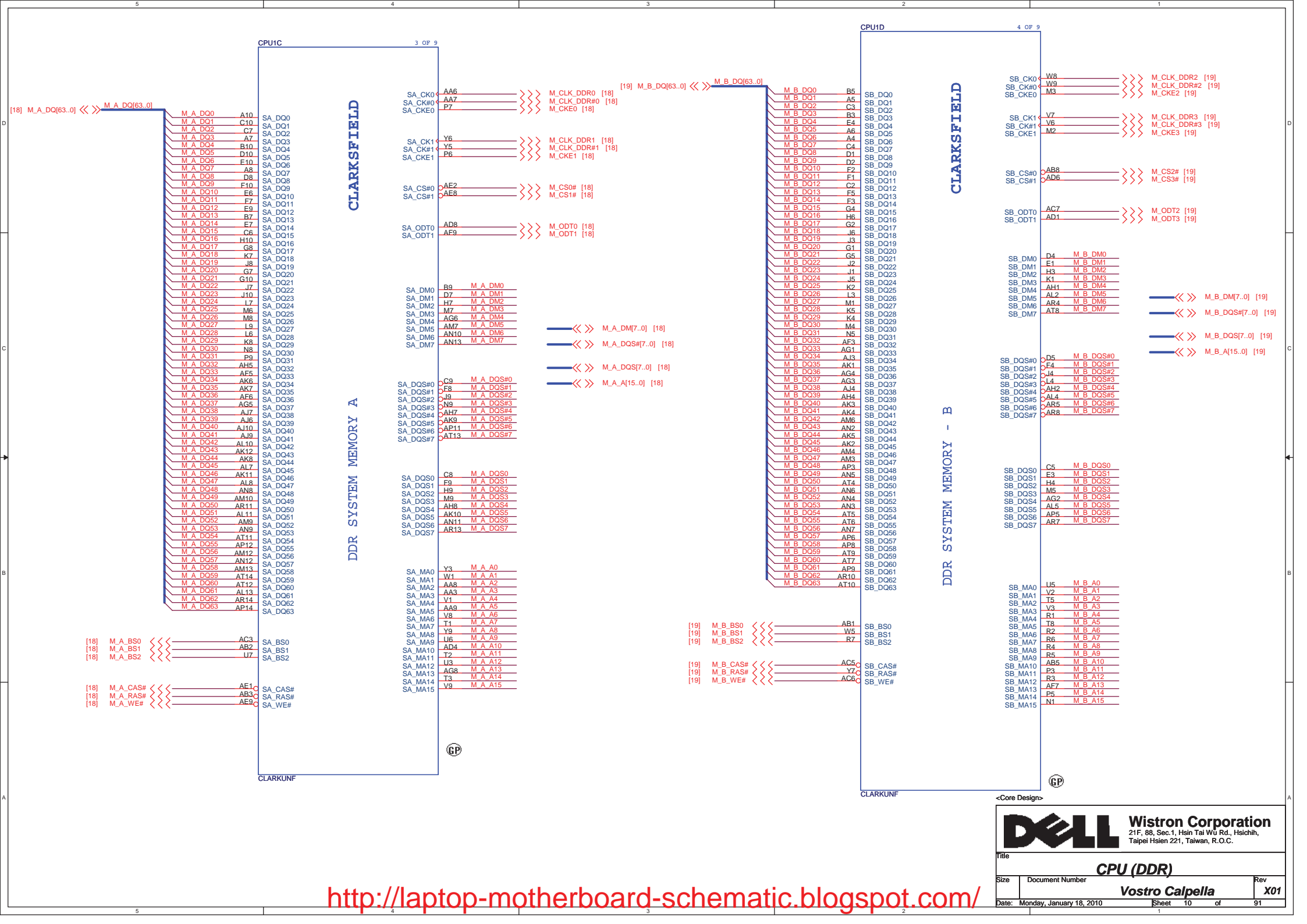
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Title: **CPU (THERMAL/CLOCK/PM)**

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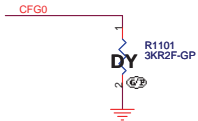
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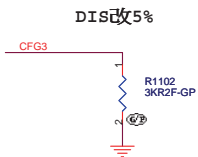
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Document Number Vostro Calpella

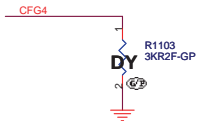
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PCI-Express Configuration Select	
CFG0	1:Single PEG 0:Bifurcation enabled



CFG3 - PCI-Express Static Lane Reversal	
CFG3	1:Normal Operation 0:Lane Numbers Reversed 15 -> 0, 14 -> 1, ...



CFG4 - Display Port Presence	
CFG4	1:Disabled; No Physical Display Port attached to Embedded Display Port 0:Enabled; An external Display Port device is connected to the Embedded Display Port

**Calpella Platform Design Guide
Revision 1.6**

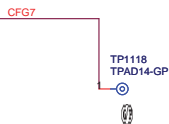
4.8.3.1 LVDS Switching

Switchable GFX, just like integrated GFX only, to enable LVDS it is required that the OEM set the LDVS (L_DDC_DATA) strap to present (pulled up) and the eDP strap (CFG[4]) to disabled (not pulled down).

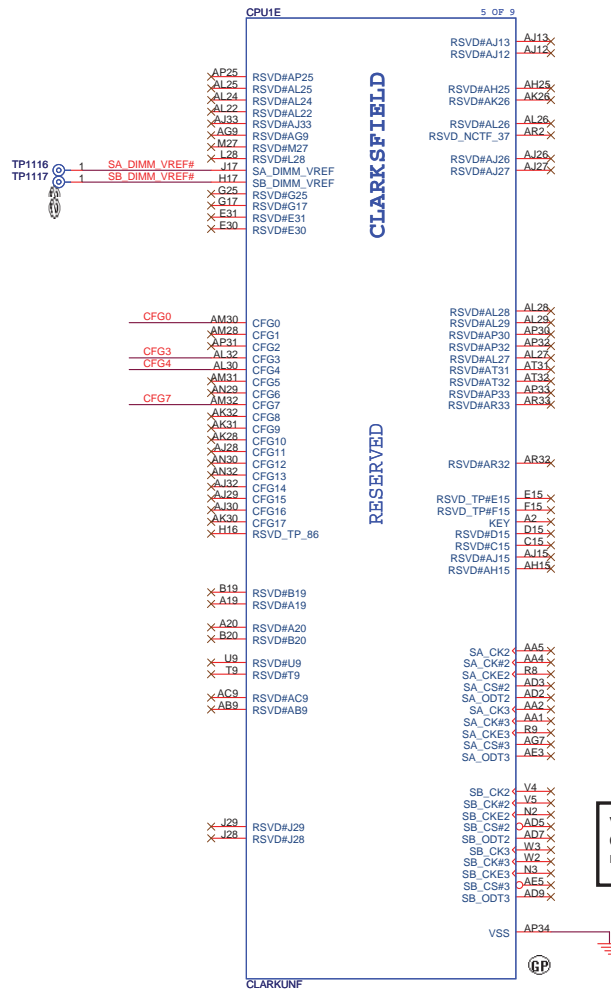
4.8.3.2 eDP Switching

eDP for Switchable GFX can only be driven out of Port D of PCH. To configure Port D for embedded DP it is required to set the DDPD_CTRLDATA strap high to 3.3V Core rail through 2.2 kΩ ±5% resistor, LVDS (L_DDC_DATA) strap as no connect and the eDP strap CFG[4] as no connect.

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CFG7(Reserved) - Temporarily used for early Clarksfield samples.	
CFG7	Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor. Note: Only temporary for early CFD sample (PGA/BGA) [For details please refer to the WW33 MoW and sighting report]. For a common M/B design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.



VSS (AP34) can be left NC is CRB implementation; EDS/DG recommendation to GND.

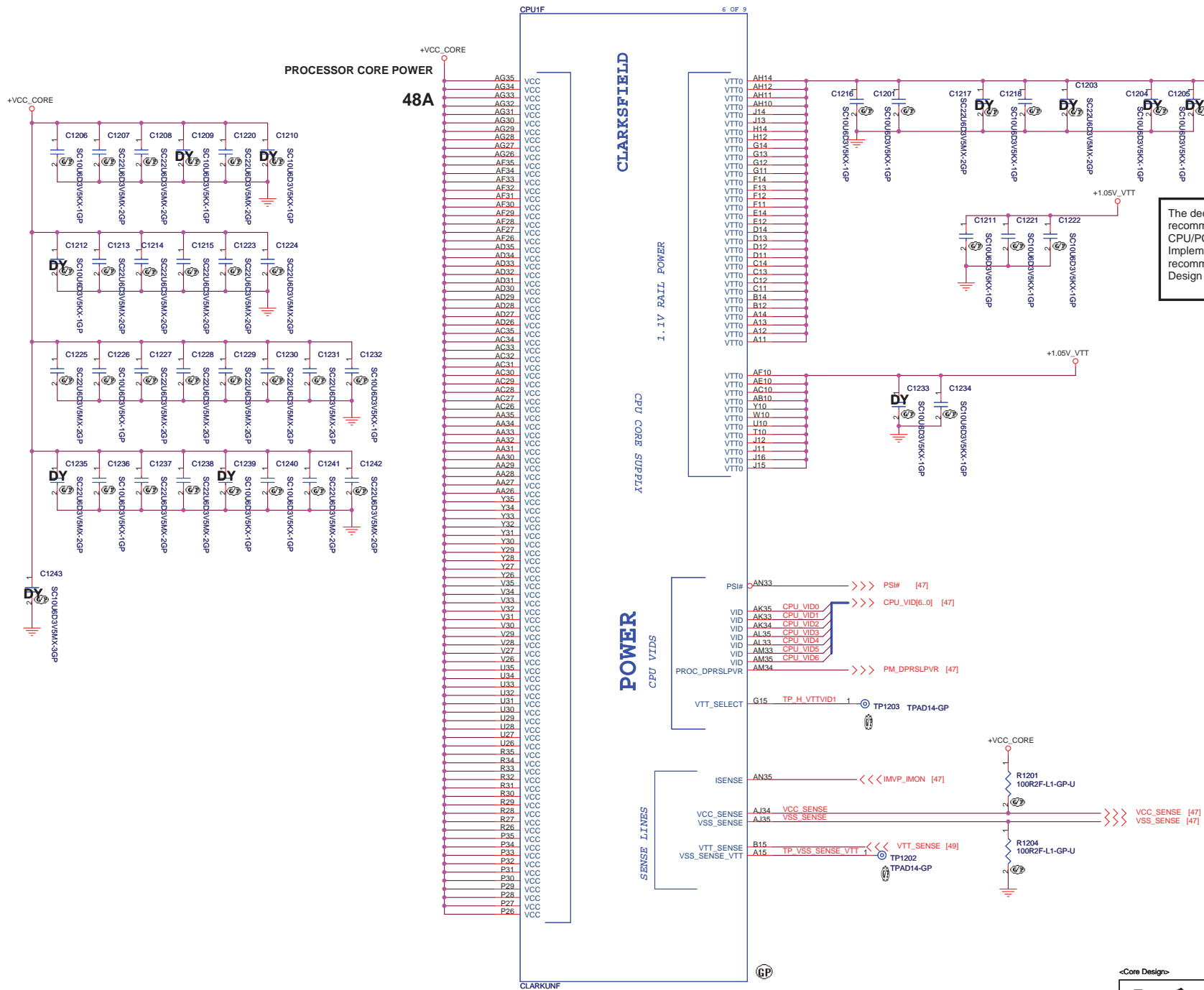
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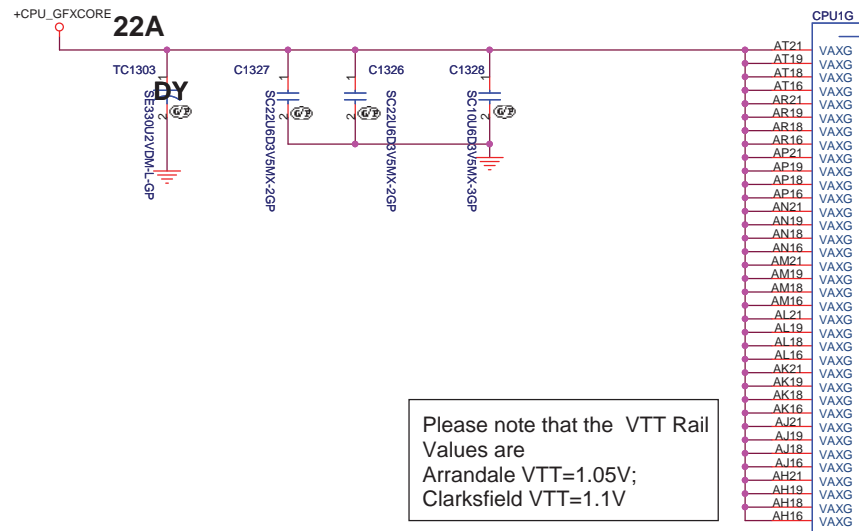


The decoupling capacitors, filter recommendations and sense resistors on the CPU/PCH Rails are specific to the CRB Implementation. Customers need to follow the recommendations in the Calpella Platform Design Guide.

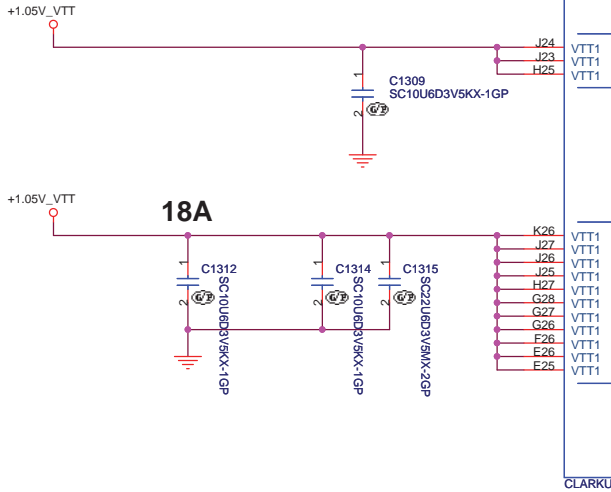
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Title		
CPU (VCC_CORE)		
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Please note that the VTT Rail Values are
 Arrandale VTT=1.05V;
 Clarksfield VTT=1.1V



- CPU1G
- AT21 VAXG
 - AT19 VAXG
 - AT18 VAXG
 - AT16 VAXG
 - AR21 VAXG
 - AR19 VAXG
 - AR18 VAXG
 - AR16 VAXG
 - AP21 VAXG
 - AP19 VAXG
 - AP18 VAXG
 - AP16 VAXG
 - AN21 VAXG
 - AN19 VAXG
 - AN18 VAXG
 - AN16 VAXG
 - AM21 VAXG
 - AM19 VAXG
 - AM18 VAXG
 - AM16 VAXG
 - AL21 VAXG
 - AL19 VAXG
 - AL18 VAXG
 - AK21 VAXG
 - AK19 VAXG
 - AK18 VAXG
 - AK16 VAXG
 - AJ21 VAXG
 - AJ19 VAXG
 - AJ18 VAXG
 - AJ16 VAXG
 - AH21 VAXG
 - AH19 VAXG
 - AH18 VAXG
 - AH16 VAXG
- CLARKUNF

CLARKSFIELD

SENSE LINES

GRAPHICS VIDS

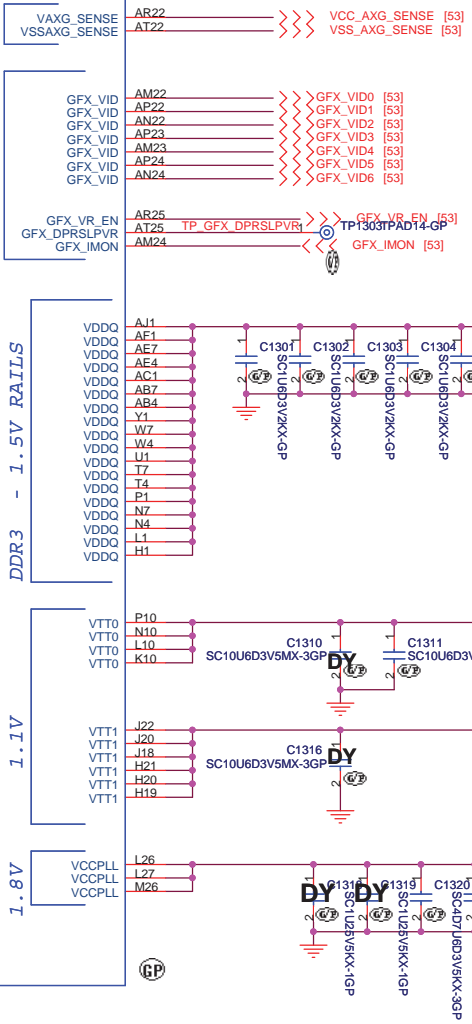
POWER

DDR3 - 1.5V RAILS

1.1V

1.8V

REG & DMI



425302_425302_Calpella_S3PowerReduction_WhitePape
 Revision 0.7

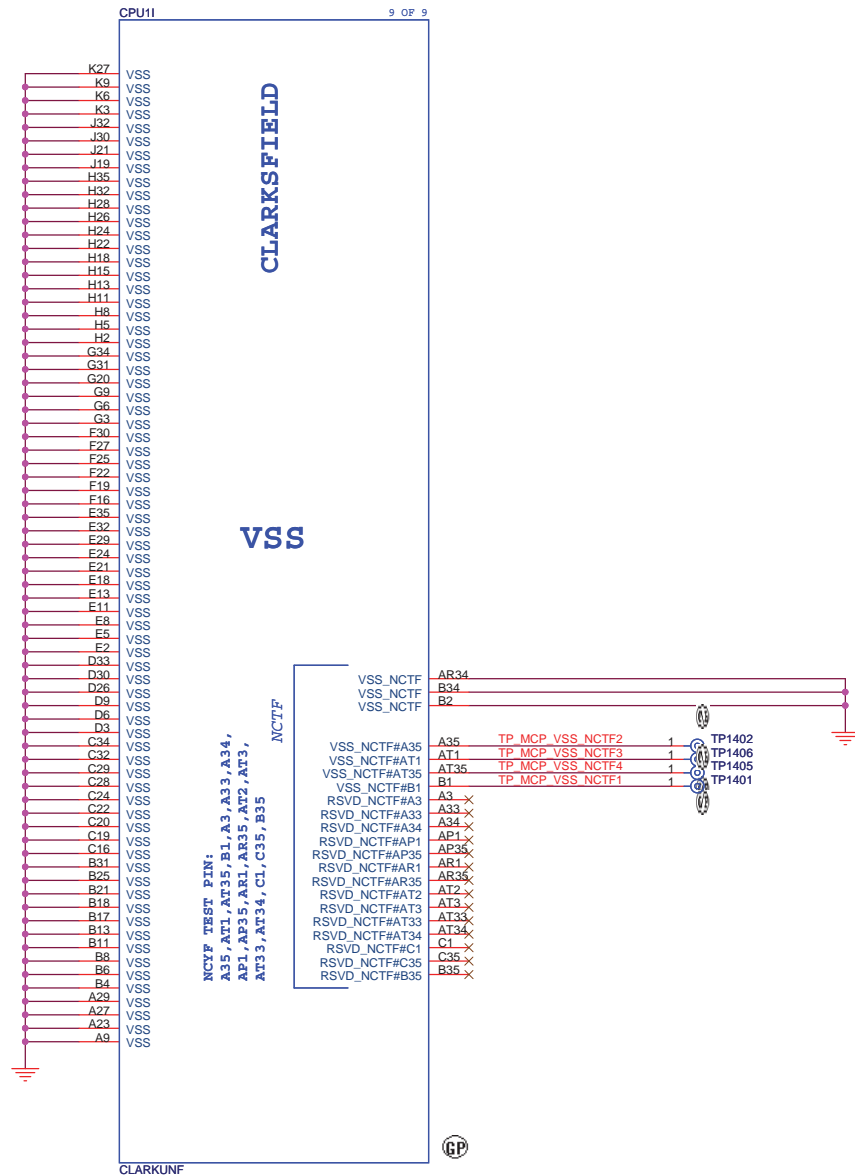
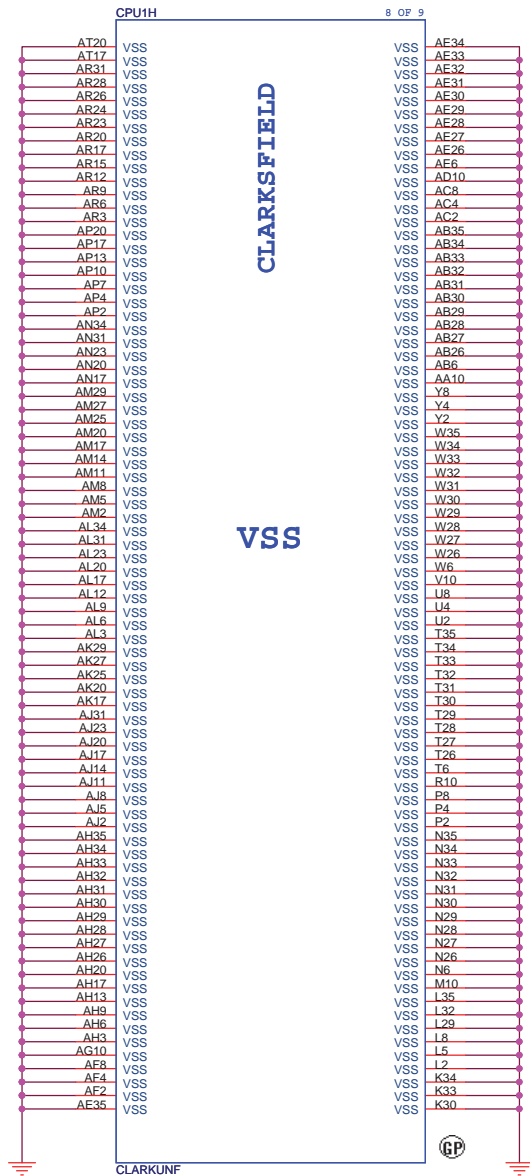
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Title: **CPU (VSS)**

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Vostro Calpella


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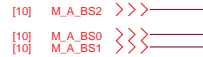
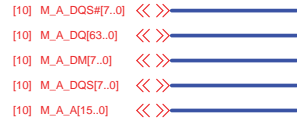
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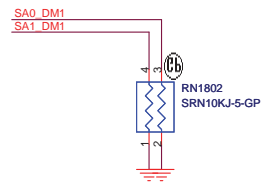
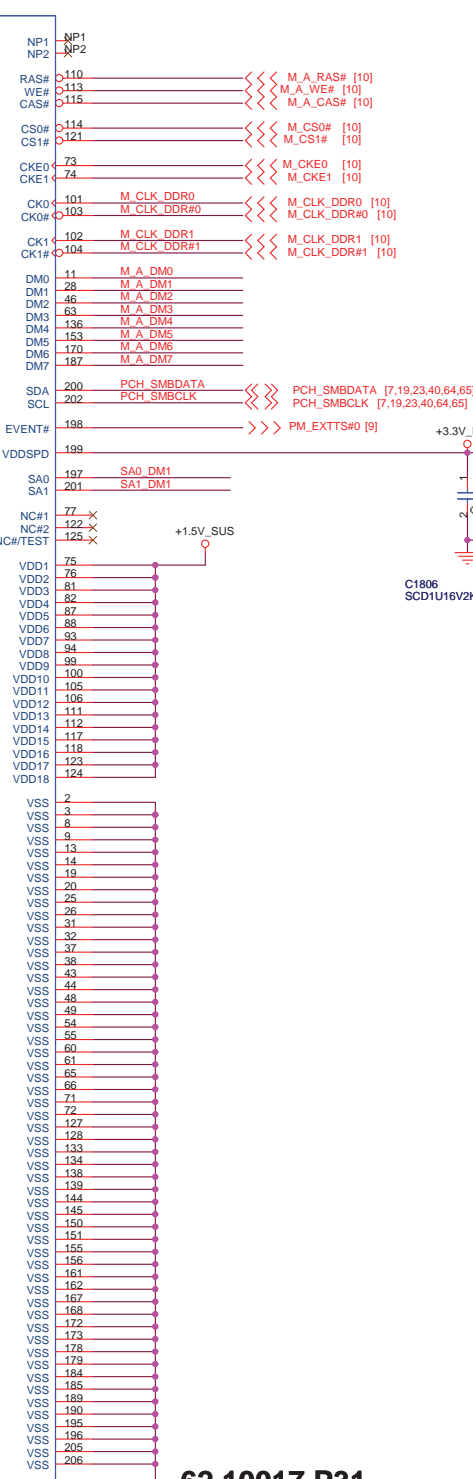
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SSID = MEMORY

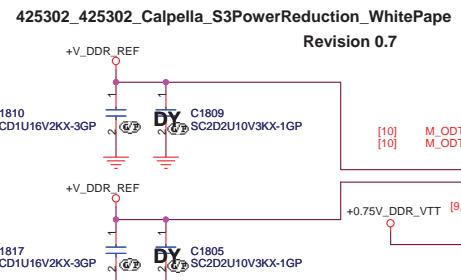
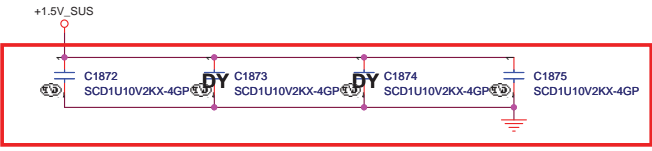
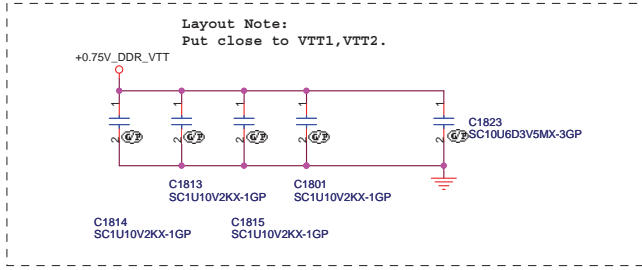
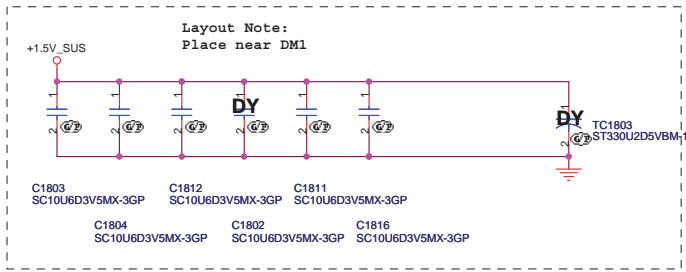


M A A0	98	A0
M A A1	97	A1
M A A2	96	A2
M A A3	95	A3
M A A4	92	A4
M A A5	91	A5
M A A6	90	A6
M A A7	86	A7
M A A8	89	A8
M A A9	85	A9
M A A10	107	A10/AP
M A A11	84	A11
M A A12	83	A12
M A A13	119	A13
M A A14	80	A14
M A A15	78	A15
M A BS2	79	A16/BA2
M A BS0	109	BA0
M A BS1	108	BA1
M A DQ0	5	DQ0
M A DQ1	7	DQ1
M A DQ2	15	DQ2
M A DQ3	17	DQ3
M A DQ4	4	DQ4
M A DQ5	6	DQ5
M A DQ6	16	DQ6
M A DQ7	18	DQ7
M A DQ8	21	DQ8
M A DQ9	23	DQ9
M A DQ10	33	DQ10
M A DQ11	35	DQ11
M A DQ12	22	DQ12
M A DQ13	24	DQ13
M A DQ14	34	DQ14
M A DQ15	36	DQ15
M A DQ16	39	DQ16
M A DQ17	41	DQ17
M A DQ18	51	DQ18
M A DQ19	53	DQ19
M A DQ20	40	DQ20
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M A DQ22	50	DQ22
M A DQ23	52	DQ23
M A DQ24	57	DQ24
M A DQ25	59	DQ25
M A DQ26	67	DQ26
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M A DQ30	68	DQ30
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M A DQ34	141	DQ34
M A DQ35	143	DQ35
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M A DQ59	193	DQ59
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M A DQ61	182	DQ61
M A DQ62	192	DQ62
M A DQ63	194	DQ63
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M A DQS#1	27	DQS1#
M A DQS#2	45	DQS2#
M A DQS#3	62	DQS3#
M A DQS#4	135	DQS4#
M A DQS#5	152	DQS5#
M A DQS#6	169	DQS6#
M A DQS#7	186	DQS7#
M A DOS0	12	DOS0
M A DOS1	29	DOS1
M A DOS2	47	DOS2
M A DOS3	64	DOS3
M A DOS4	137	DOS4
M A DOS5	154	DOS5
M A DOS6	171	DOS6
M A DOS7	188	DOS7
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M A DOS#3	62	DOS#3
M A DOS#4	135	DOS#4
M A DOS#5	152	DOS#5
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Height 5.2mm



SMBUS address:A0



<Core Design>

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Size: Document Number
Customer: **Vostro Calpella**
Date: Monday, January 18, 2010

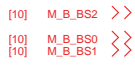
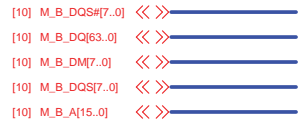
Rev: **X01**

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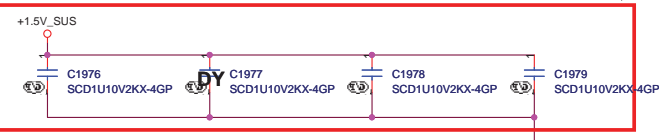
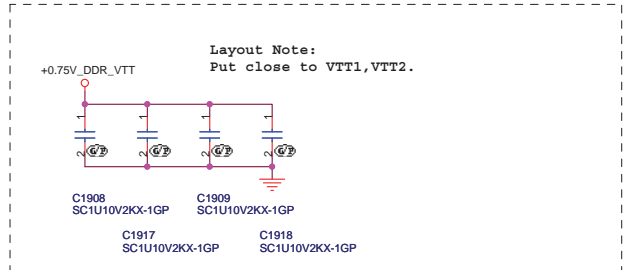
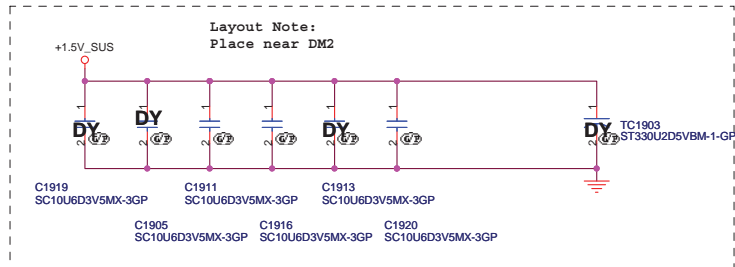
62.10017.P31

<http://laptop-motherboard-schematic.blogspot.com/>

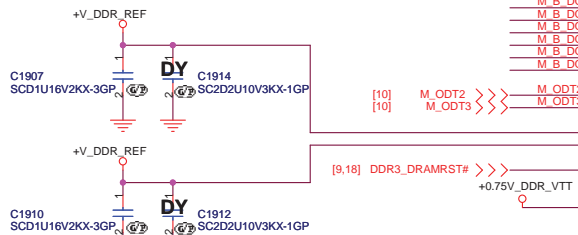
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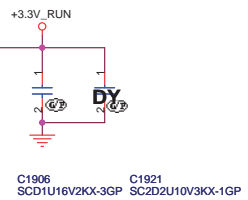
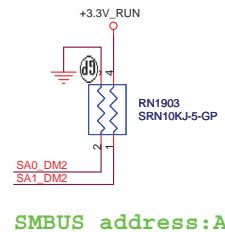
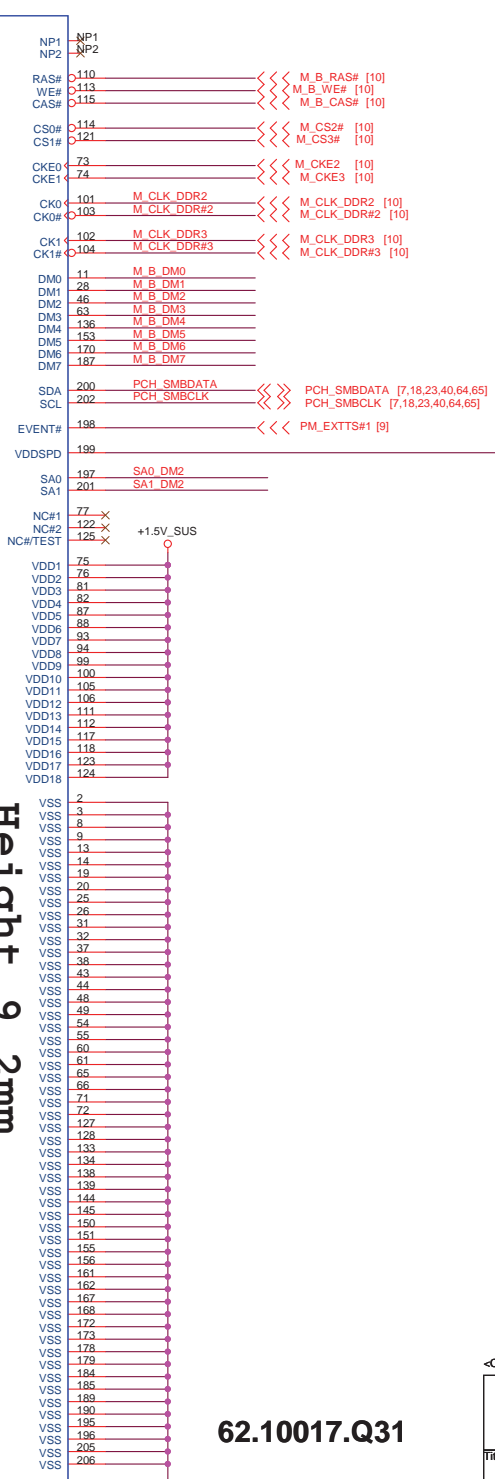
M_B A0	98	
M_B A1	97	
M_B A2	96	
M_B A3	95	
M_B A4	92	
M_B A5	91	
M_B A6	90	
M_B A7	86	
M_B A8	89	
M_B A9	85	
M_B A10	107	
M_B A11	84	
M_B A12	83	
M_B A13	119	
M_B A14	80	
M_B A15	78	
M_B BS2	79	A16/BA2
M_B BS0	109	BA0
M_B BS1	108	BA1
M_B DQ0	5	DQ0
M_B DQ1	7	DQ1
M_B DQ2	15	DQ2
M_B DQ3	17	DQ3
M_B DQ4	4	DQ4
M_B DQ5	16	DQ5
M_B DQ6	18	DQ6
M_B DQ7	21	DQ7
M_B DQ8	23	DQ8
M_B DQ9	33	DQ9
M_B DQ10	35	DQ10
M_B DQ11	22	DQ11
M_B DQ12	24	DQ12
M_B DQ13	34	DQ13
M_B DQ14	36	DQ14
M_B DQ15	39	DQ15
M_B DQ16	41	DQ16
M_B DQ17	51	DQ17
M_B DQ18	53	DQ18
M_B DQ19	40	DQ19
M_B DQ20	42	DQ20
M_B DQ21	50	DQ21
M_B DQ22	52	DQ22
M_B DQ23	57	DQ23
M_B DQ24	59	DQ24
M_B DQ25	67	DQ25
M_B DQ26	69	DQ26
M_B DQ27	56	DQ27
M_B DQ28	58	DQ28
M_B DQ29	68	DQ29
M_B DQ30	70	DQ30
M_B DQ31	129	DQ31
M_B DQ32	131	DQ32
M_B DQ33	141	DQ33
M_B DQ34	143	DQ34
M_B DQ35	130	DQ35
M_B DQ36	132	DQ36
M_B DQ37	140	DQ37
M_B DQ38	142	DQ38
M_B DQ39	147	DQ39
M_B DQ40	149	DQ40
M_B DQ41	157	DQ41
M_B DQ42	159	DQ42
M_B DQ43	146	DQ43
M_B DQ44	148	DQ44
M_B DQ45	158	DQ45
M_B DQ46	160	DQ46
M_B DQ47	163	DQ47
M_B DQ48	165	DQ48
M_B DQ49	175	DQ49
M_B DQ50	177	DQ50
M_B DQ51	164	DQ51
M_B DQ52	166	DQ52
M_B DQ53	174	DQ53
M_B DQ54	176	DQ54
M_B DQ55	181	DQ55
M_B DQ56	183	DQ56
M_B DQ57	191	DQ57
M_B DQ58	193	DQ58
M_B DQ59	180	DQ59
M_B DQ60	182	DQ60
M_B DQ61	192	DQ61
M_B DQ62	194	DQ62
M_B DQ63	194	DQ63
M_B DQS#0	10	DQS0#
M_B DQS#1	27	DQS1#
M_B DQS#2	45	DQS2#
M_B DQS#3	62	DQS3#
M_B DQS#4	135	DQS4#
M_B DQS#5	152	DQS5#
M_B DQS#6	168	DQS6#
M_B DQS#7	186	DQS7#
M_B DOS0	12	DOS0
M_B DOS1	29	DOS1
M_B DOS2	47	DOS2
M_B DOS3	64	DOS3
M_B DOS4	137	DOS4
M_B DOS5	154	DOS5
M_B DOS6	171	DOS6
M_B DOS7	188	DOS7
M_B ODT2	116	ODT0
M_B ODT3	120	ODT1
VREF_CA	126	VREF_CA
VREF_DQ	1	VREF_DQ
RESET#	30	RESET#
VTT1	203	VTT1
VTT2	204	VTT2



425302_425302_Calpella_S3PowerReduction_WhitePape
Revision 0.7



Height 9.2mm



Note:
If SA0_DIM0 = 0, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA0
If SA0_DIM0 = 1, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA2
If SA0_DIM0 = 0, SA1_DIM0 = 1
SO-DIMMA SPD Address is 0xA4

62.10017.Q31

<Core Design>

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **DDR3-SODIMM SLOT2**

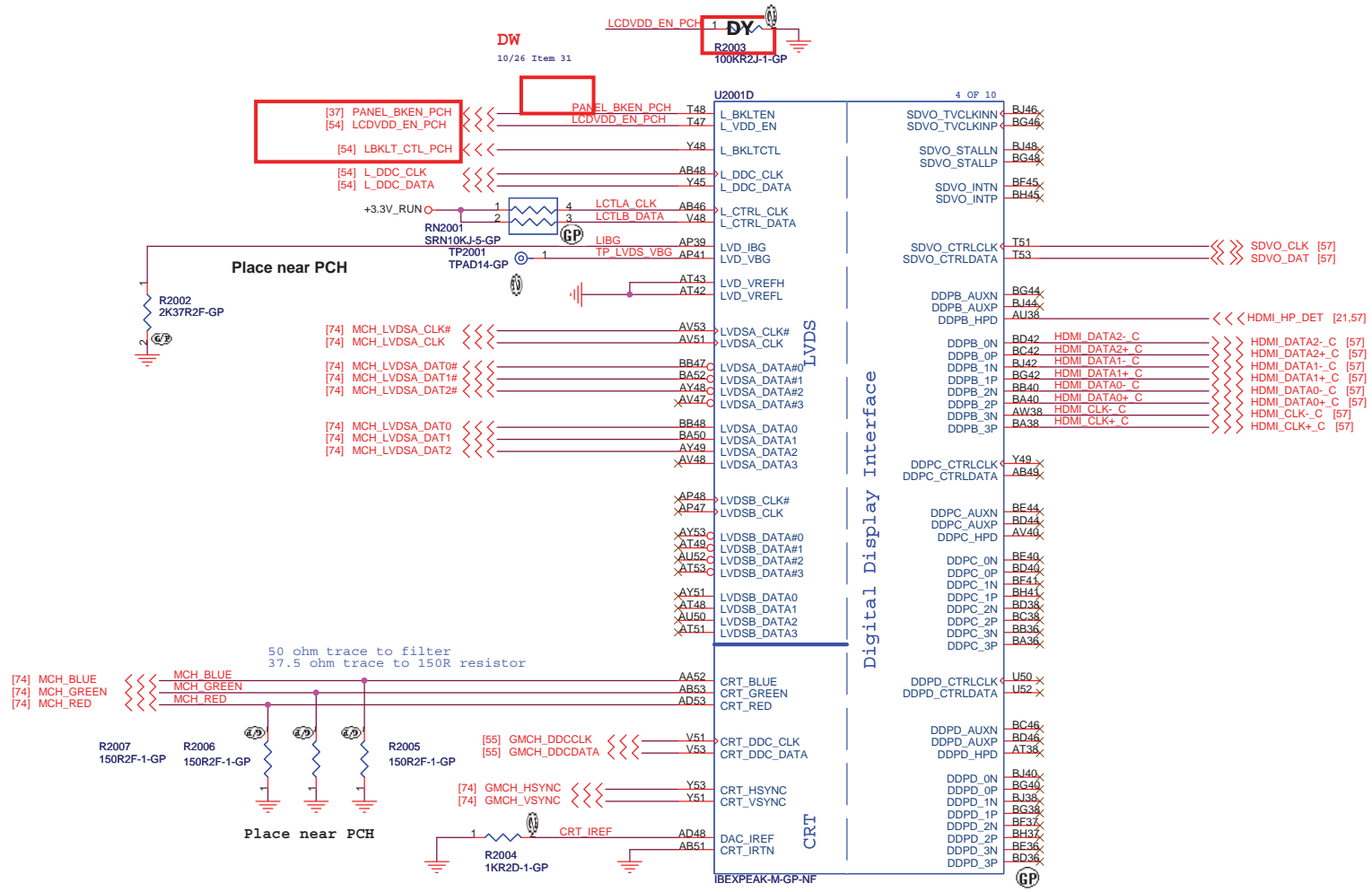
Size: Document Number

Customer: **Vostro Calpella**


Date: Monday, January 18, 2010

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Rev: **X01**



<Core Design>

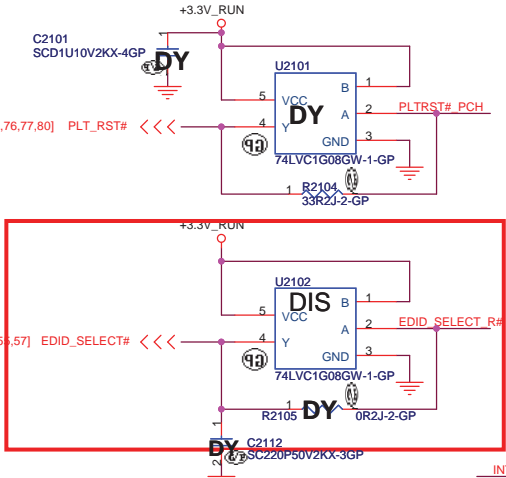
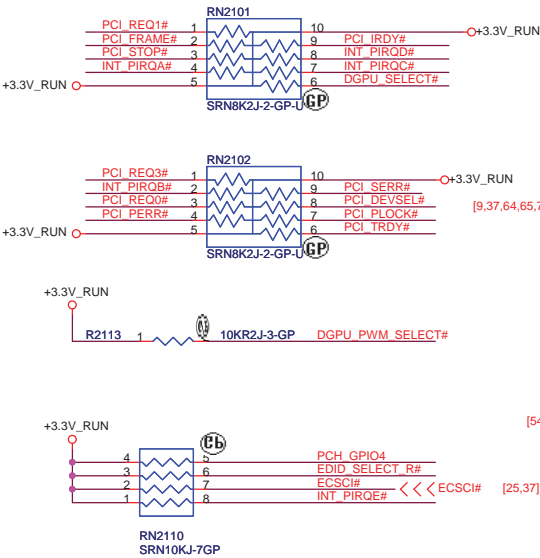


Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (LVDS/CRT/DDI)**

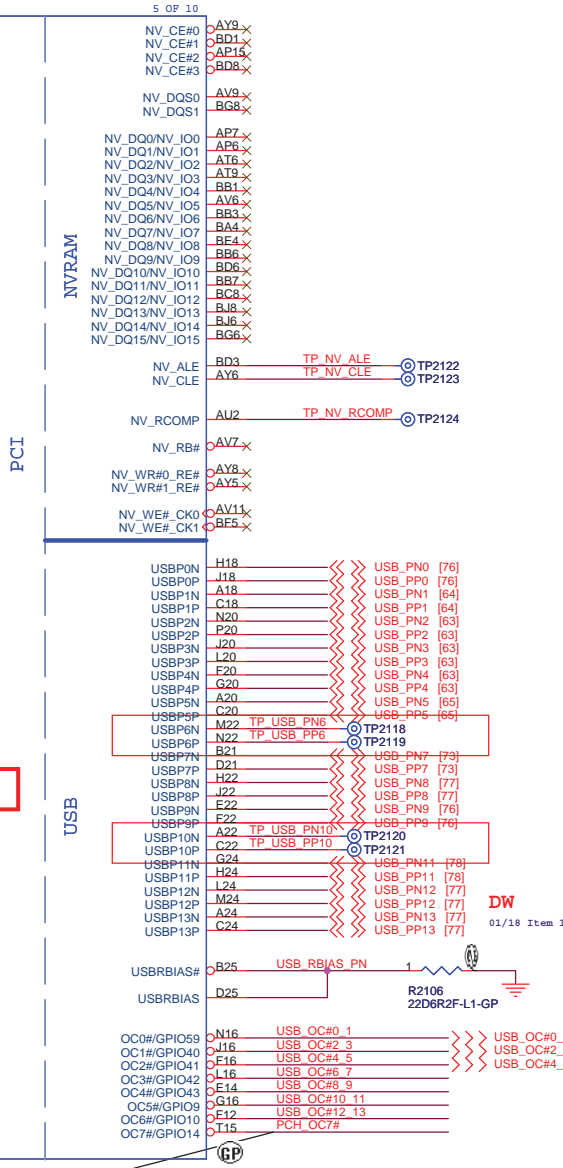
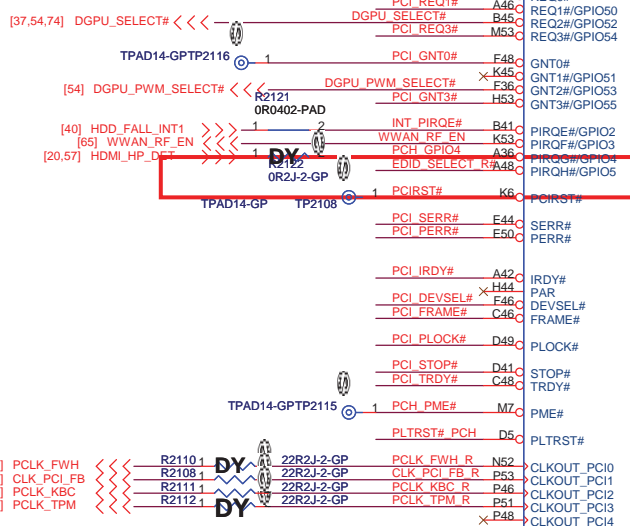
Size	Document Number	Rev
	Vostro Calpella	X01

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BOOT BIOS Strap		
PCI_GNT#0	PCI_GNT#1	BOOT BIOS Location
0	0	LPC
0	1	Reserved
1	0	PCI
1	1	SPI (Default)

DW
10/19 Changed
1.Changed EDID_SELECT# pin from PCH_GPIO66 to PCH_GPIO5 for fixed glitch

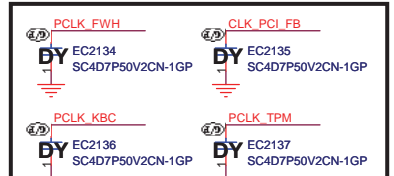


USB	
Pair	Device
0	USB1
1	WLAN
2	USB2
3	USB3
4	USB for ESATA
5	WWAN
6	RESERVED (Not available for HM55)
7	RESERVED (Not available for HM55)
8	BLUETOOTH
9	Touch Panel
10	CAMERA
11	Biometric
12	New Card
13	CardReader

A16 swap override Strap/Top-Block Swap Override jumper

PCI_GNT#3	Low = A16 swap override/Top-Block Swap Override enabled High = Default
-----------	---

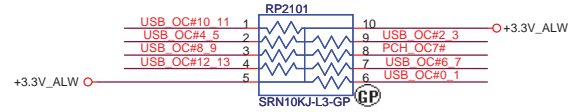
Reserve by pass cap near the U2001, For EMI



Calpella Platform Design Guide
Revision 1.6

Table 111. Overcurrent Pin Example Configuration

These OC7# pins are not used for USB overcurrent protection and should be configured as GPIOs. The unused USB ports can be left as no connect.



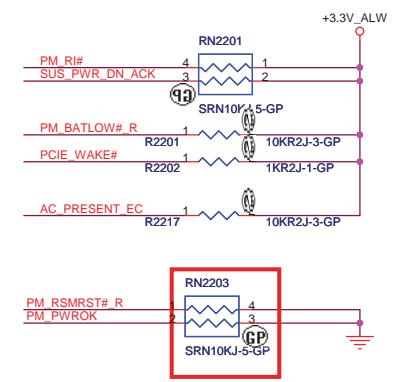
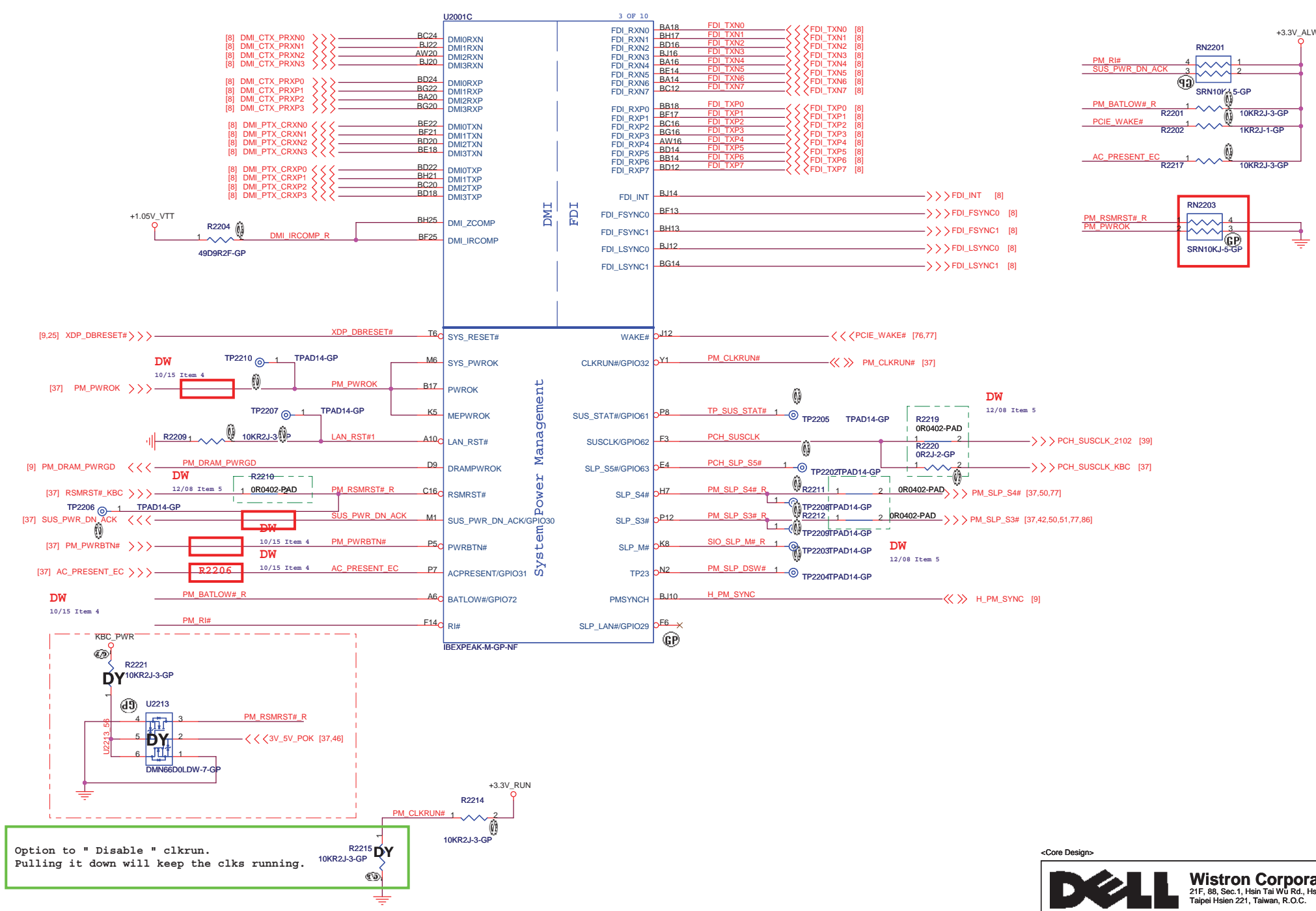
Core Design>

Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

File: **PCH (PCI/USB/NVRAM)**

Size	Document Number	Rev
	Vostro Calpella	X01

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Option to "Disable" clkrun.
Pulling it down will keep the clks running.

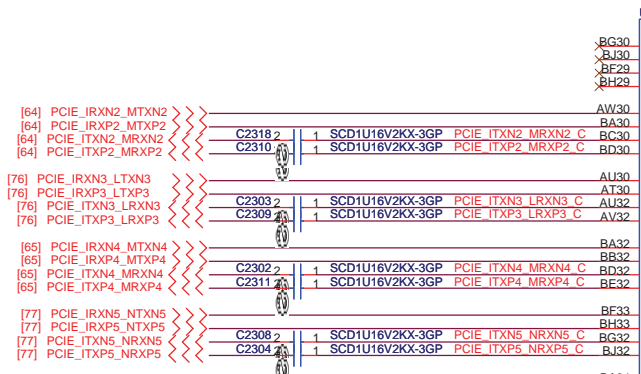
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DELL Wistron Corporation
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Title: **PCH (DM I/FDI/PM)**

Size	Document Number	Rev
		X01

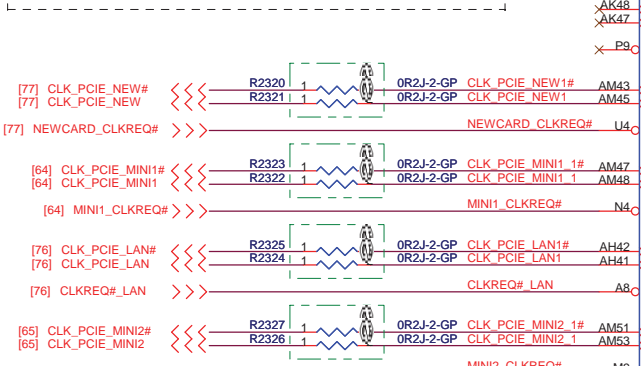
Date: Monday, January 18, 2010 Sheet 22 of 91



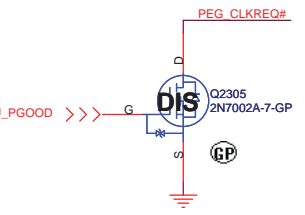
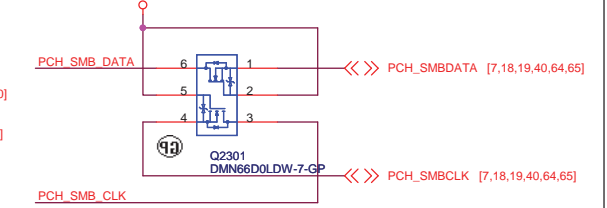
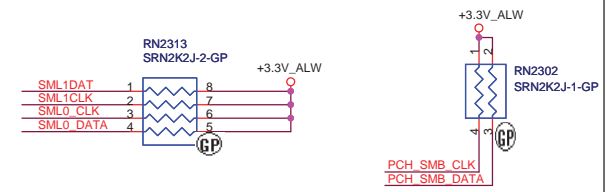
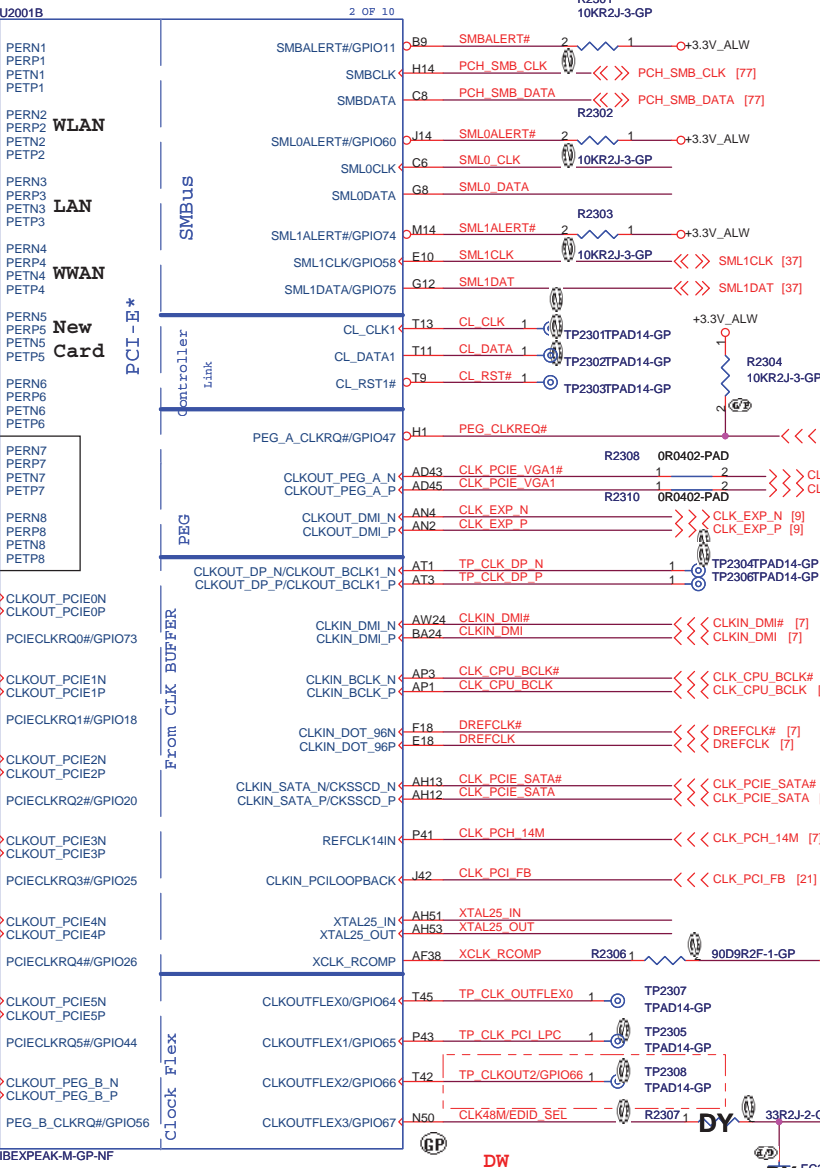
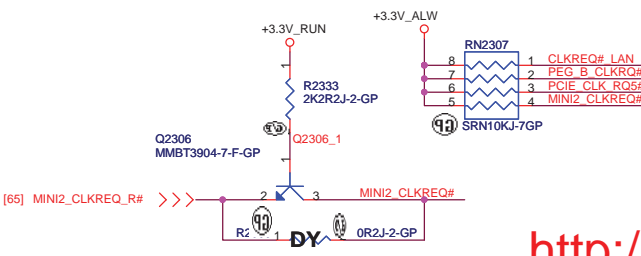
(Not available for HM55)

(Not available for HM55)

PCIECLKRQ{0,3,4,5,6,7}# should have a 10K pull-up to +3.3V_ALW.
 PCIECLKRQ{1,2} should have a 10K pull-up to +3.3_RUN



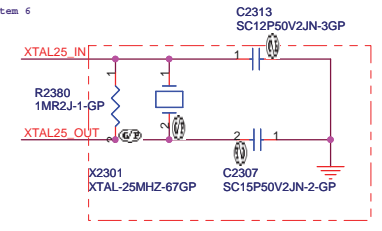
DW
 12/10 Item 3
 Reserve 0402 00hm resistors
 , For RF Team to try solve PCIe noise



Display Clock Integration

	C2313	C2307	X2301	R2380
Normal	0R2J-2-GP	DY	DY	DY
dale DCI	SC18P	SC18P	25MHZ	1MR

DW
 10/15 Item 6



DY
 EC2338
 SC4D7P50V2CN-1GP
 Near R23071

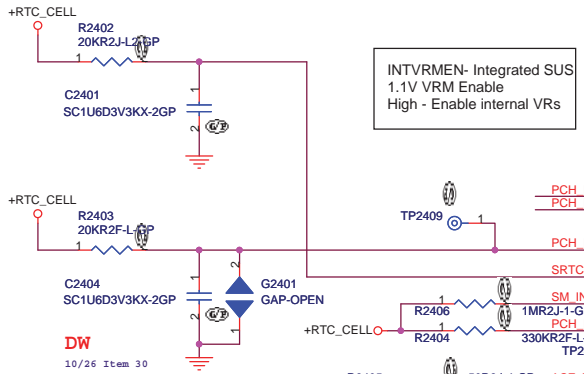
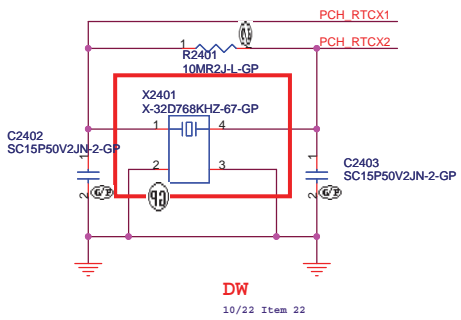
<Core Design>

DELL Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

File: **PCH (PCI-E/SMBUS/CLOCK/CL)**

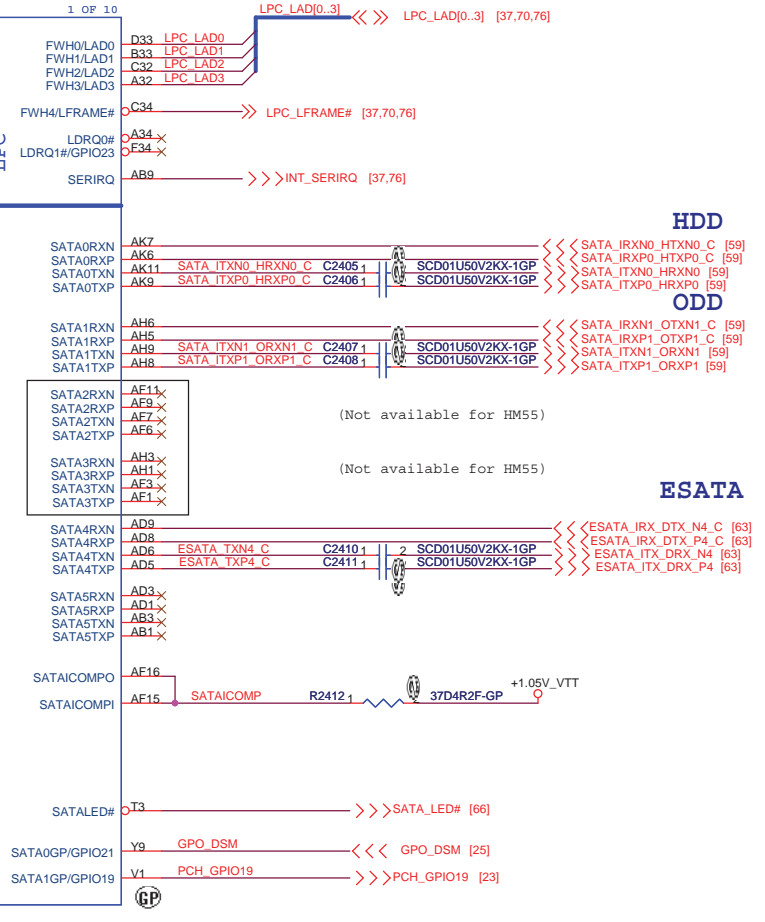
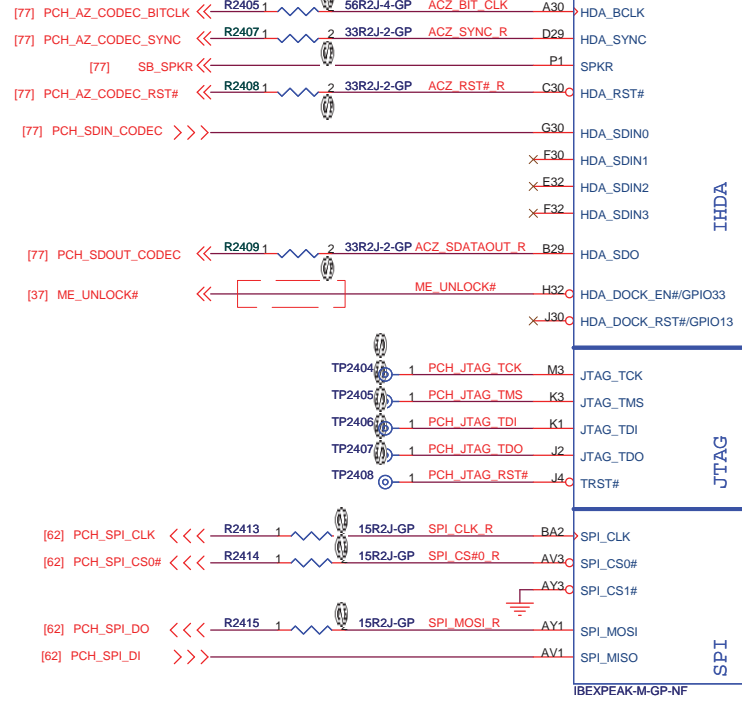
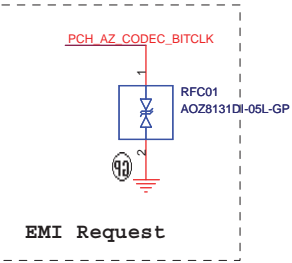
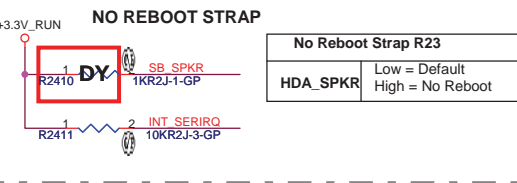
Size	Document Number	Rev
		X01

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Flash Descriptor Security Override/ ME Debug Mode

ME_UNLOCK# This strap should only be asserted low via external pull down in manufacturing/debug environments ONLY.



<Core Design>

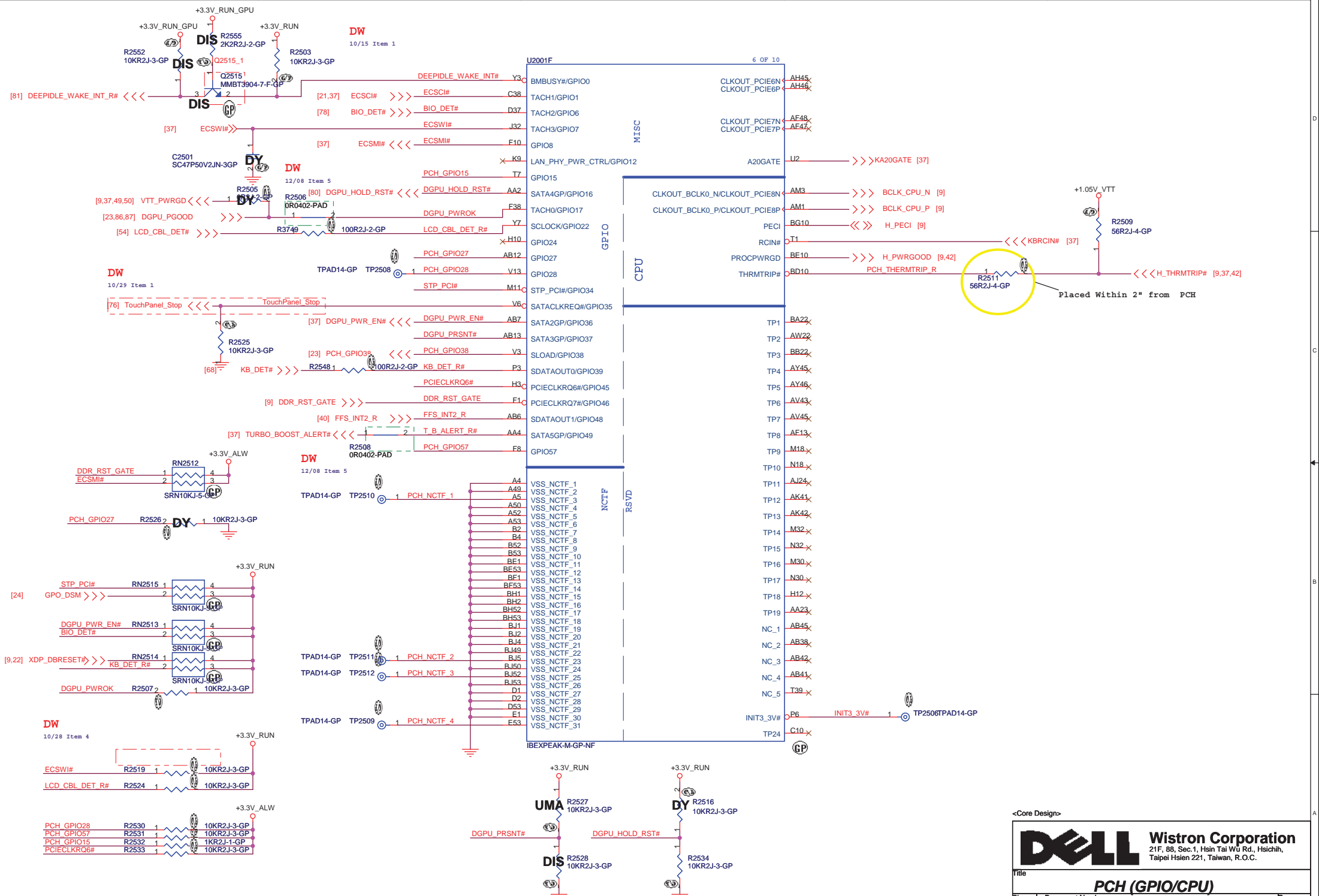
DELL Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (SPI/RTC/LPC/SATA/IHDA)**

Size: Document Number Rev: X01

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Vostro Calpella



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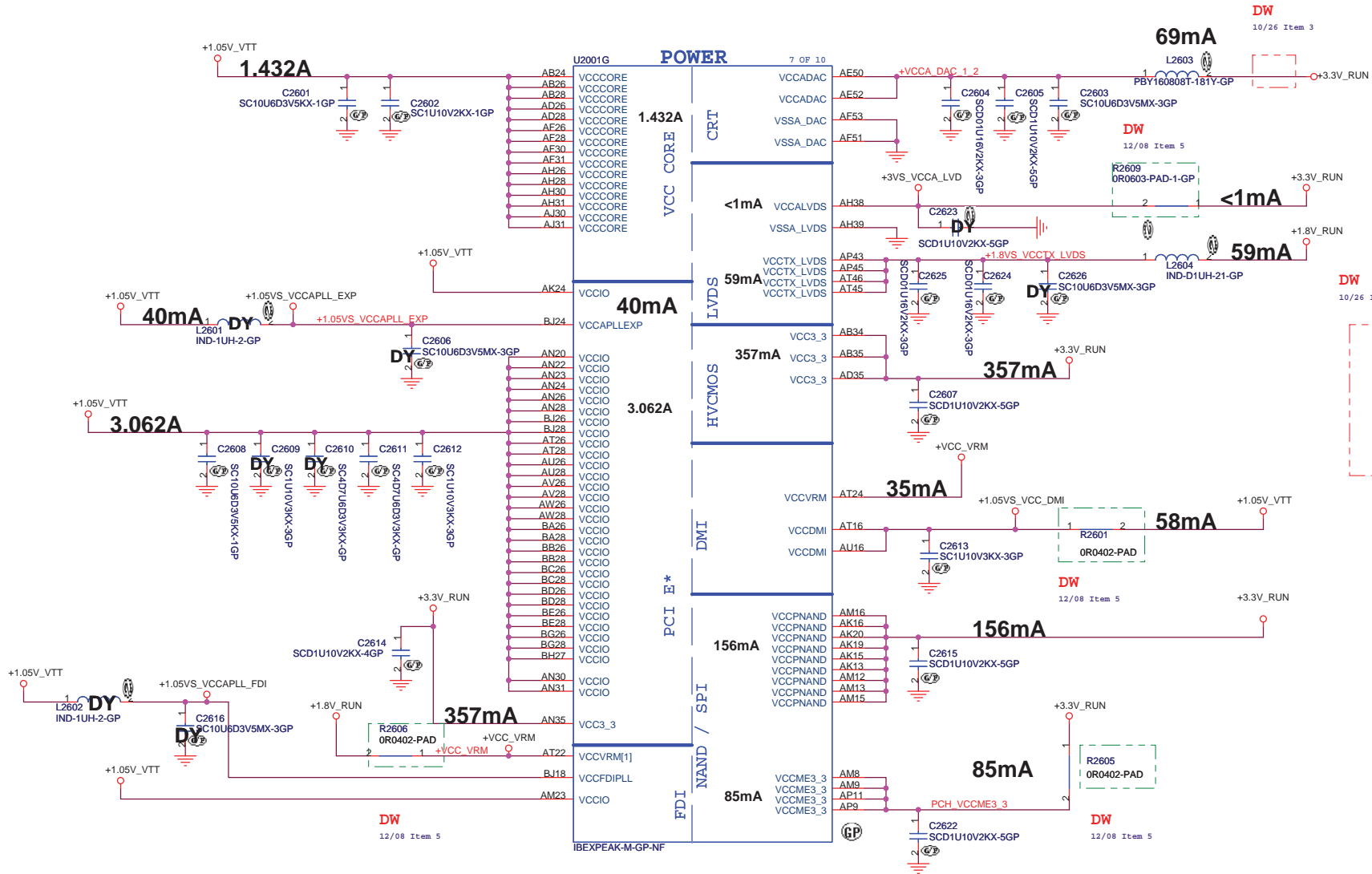
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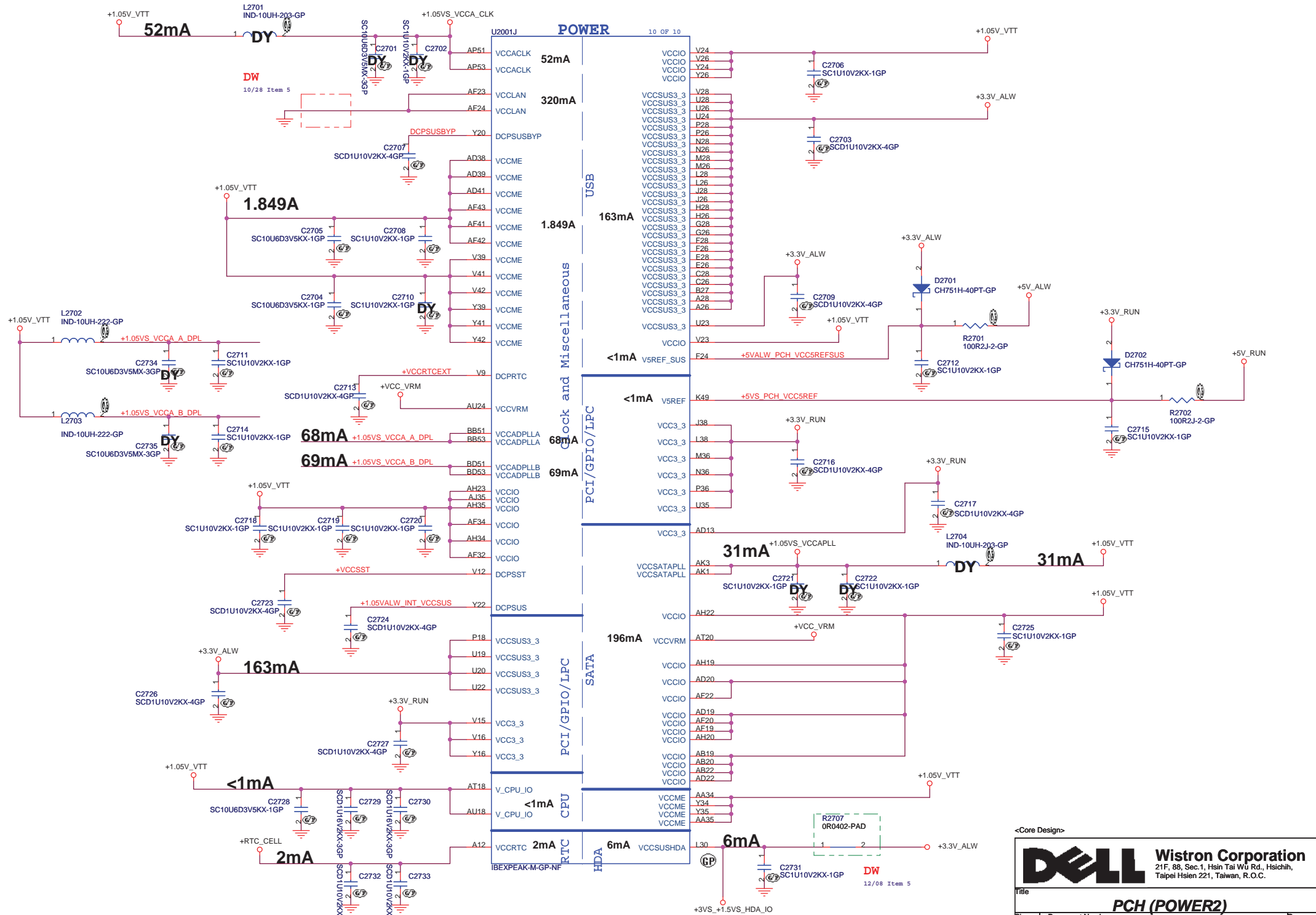
DELL Wistron Corporation
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (GPIO/CPU)**

Size	Document Number	Rev
		X01

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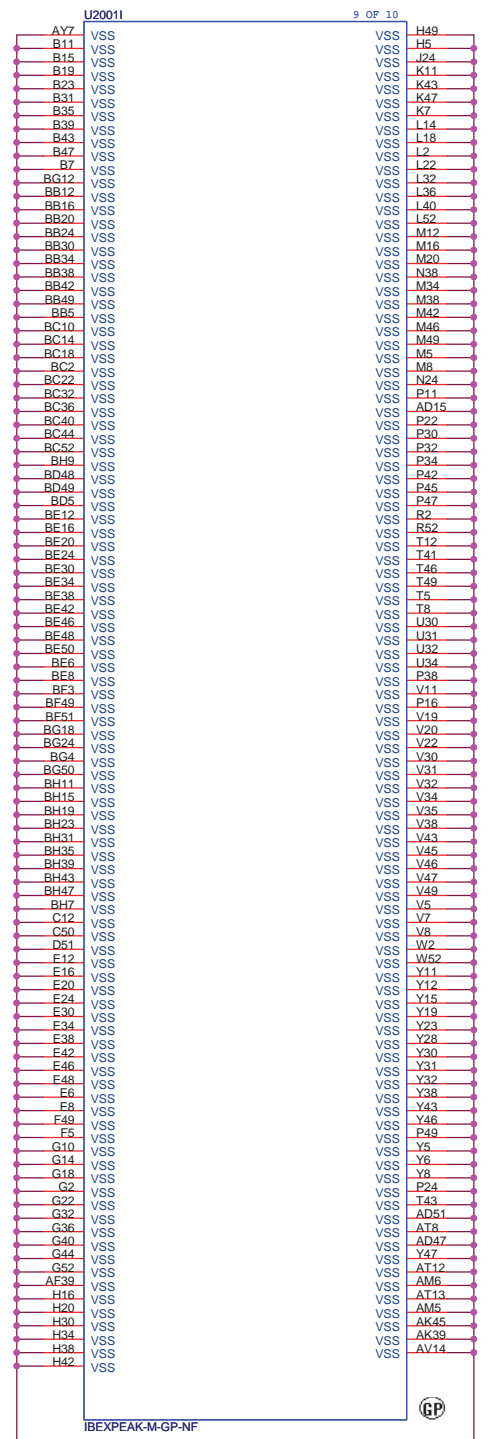
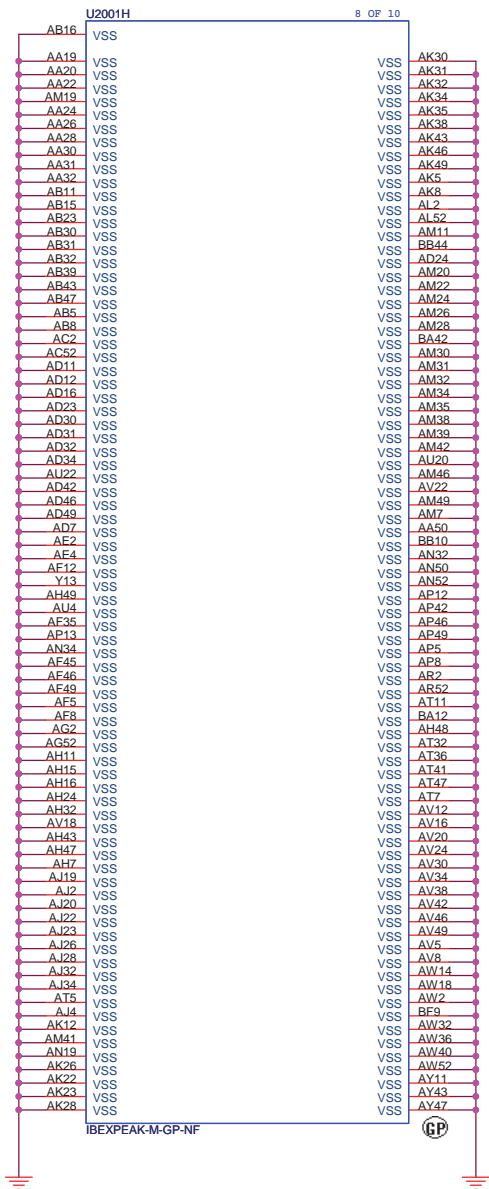
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Wistron Corporation
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (POWER2)**

Size	Document Number	Rev
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Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.


Title: **PCH (VSS)**

Size	Document Number	Rev
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Custom	Vostro Calpella				X01
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Custom	Vostro Calpella	X01	
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Title					
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Size	Document Number				Rev
Custom	Vostro Calpella				X01
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Size	Document Number				Rev
Custom	Vostro Calpella				X01
Date: Monday, January 18, 2010			Sheet	33	of 91


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Date: Monday, January 18, 2010		Sheet 34 of 91


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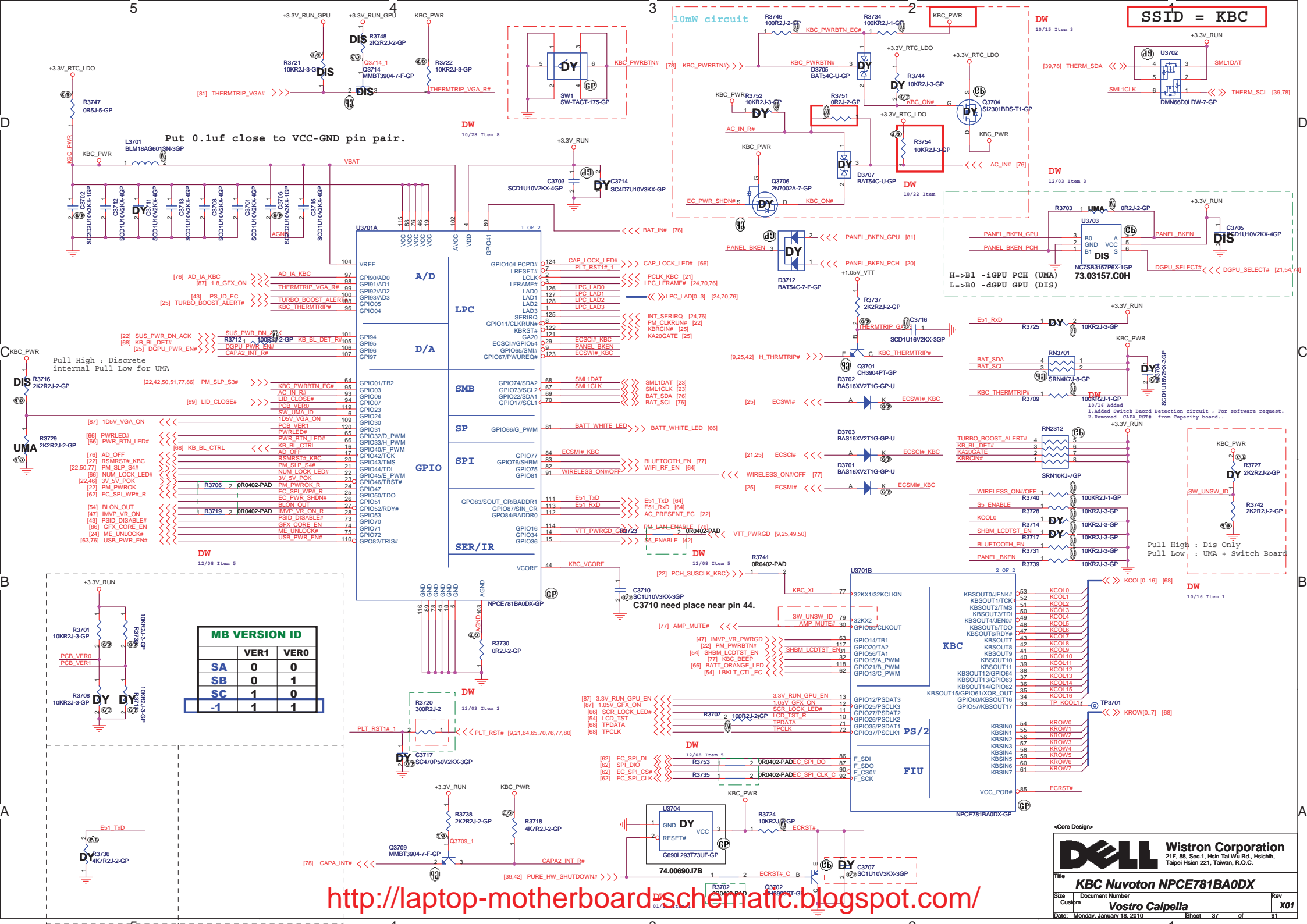
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Date: Monday, January 18, 2010	Sheet 35 of 91	1

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<Core Design>

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Title		(Reserve)
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Put 0.1uF close to VCC-GND pin pair.


MB VERSION ID		
	VER1	VER0
SA	0	0
SB	0	1
SC	1	0
	-1	1

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Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Heichih, Taipei Hsien 221, Taiwan, R.O.C.
KBC Nuovton NPCE781BA0DX
 Size: Document Number
 Custm: Vostro Calpella
 Rev: X01
 Date: Monday, January 18, 2010 Sheet 37 of 91

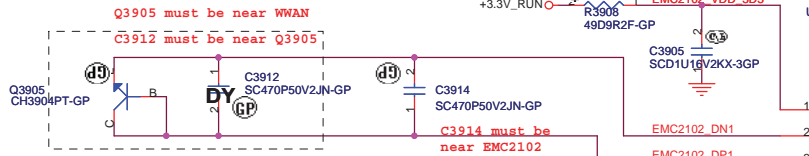
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Size	Document Number				Rev
Custom	Vostro Calpella				X01
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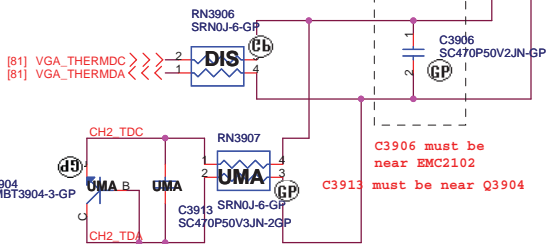
SSID = Thermal

1. WWAN



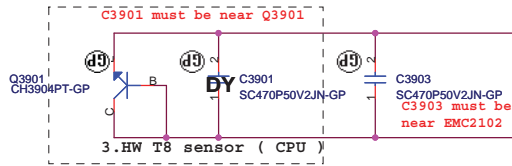
Layout notice:
H_THERMDA, H_THERMDC routing together,
Trace width / Spacing = 10 / 10 mil

2. GPU Sensor



2. CPU Sensor

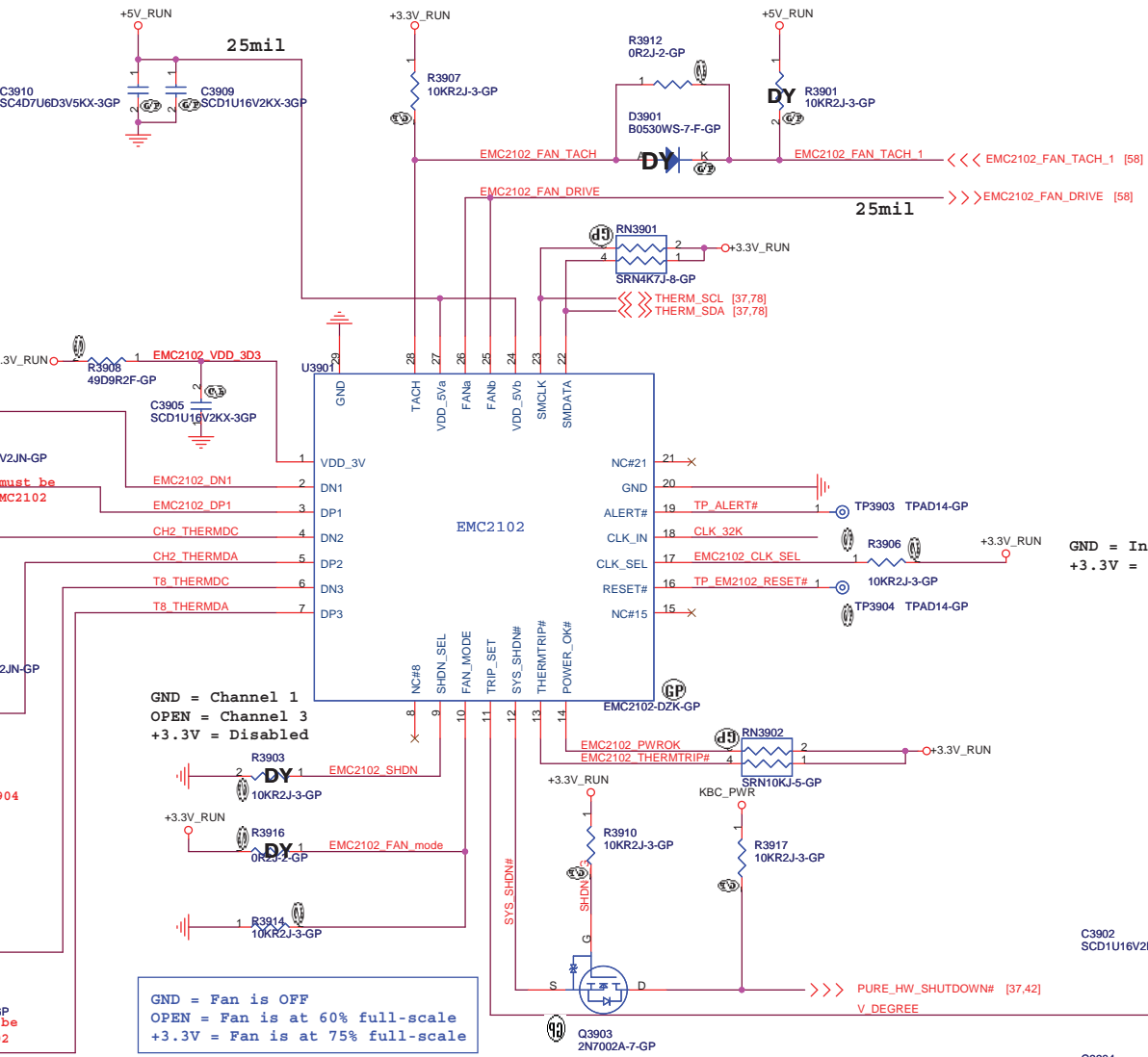
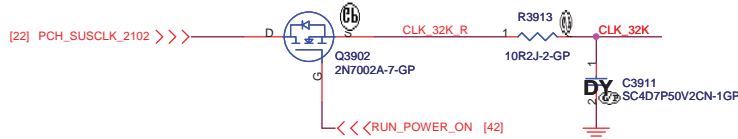
Layout notice:
Both VGA_THERMDA and THERMDC routing
10 mil trace width and 10 mil spacing.



3. HW T8 sensor (CPU)

Layout notice:
Both DN3 and DP3 routing 10 mil
trace width and 10 mil spacing.

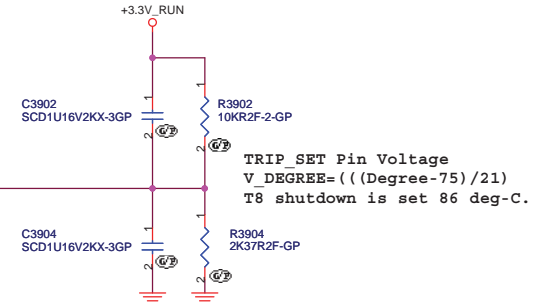
32K suspend clock output



GND = Channel 1
OPEN = Channel 3
+3.3V = Disabled

GND = Fan is OFF
OPEN = Fan is at 60% full-scale
+3.3V = Fan is at 75% full-scale

GND = Internal Oscillator Selected
+3.3V = External 32.768kHz Clock Selected



<Core Design>

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **Thermal/Fan Controller EMC2102**

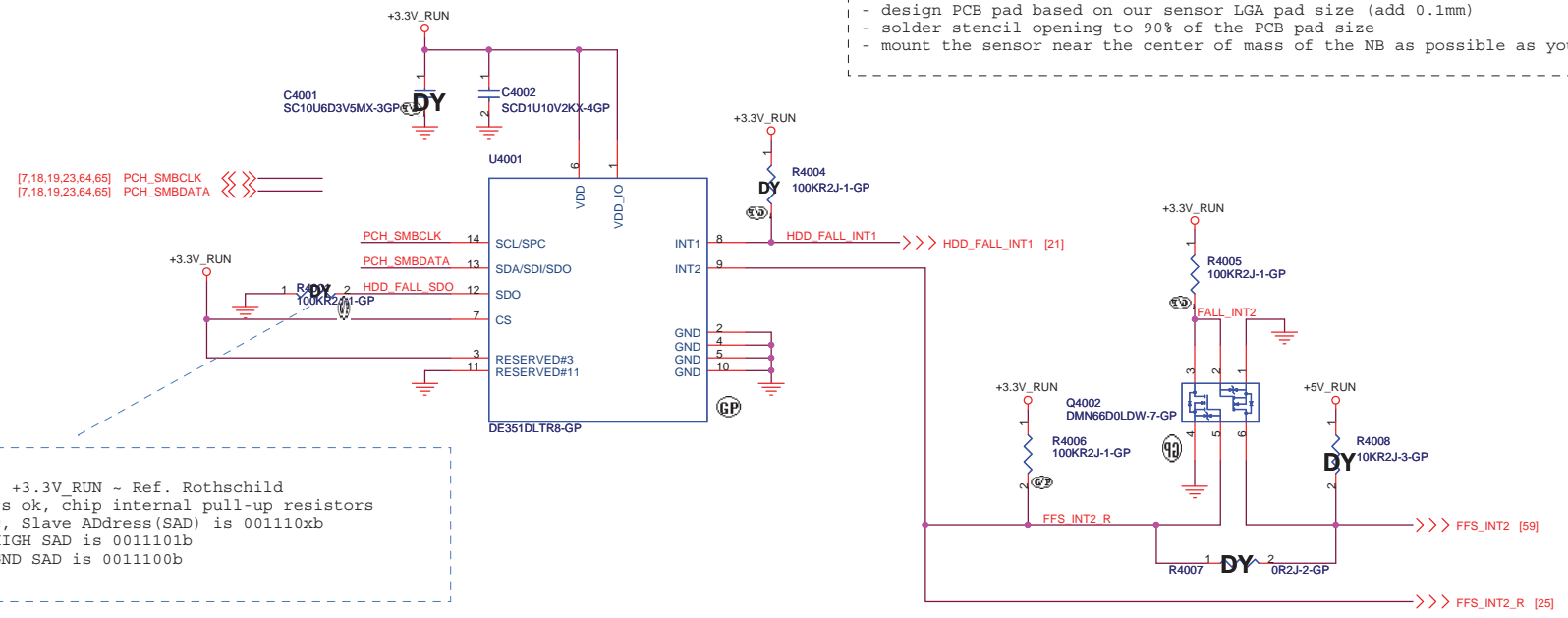
Size	Document Number	Rev
Custom	Vostro Calpella	X01

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Free Fall Sensor

Note

- no via, trace, under the sensor (keep out area around 2mm)
- stay away from the screw hole or metal shield soldering joints
- design PCB pad based on our sensor LGA pad size (add 0.1mm)
- solder stencil opening to 90% of the PCB pad size
- mount the sensor near the center of mass of the NB as possible as you can



09/0422
 (#1) Just pull +3.3V_RUN ~ Ref. Rothschild
 (#2) FAE/ DY is ok, chip internal pull-up resistors
 (#3) From spec, Slave Address(SAD) is 001110xb
 Pull HIGH SAD is 0011101b
 Pull GND SAD is 0011100b

Note
 (1) Keep all signals are the same trace width. (included VDD, GND).
 (2) No VIA under IC bottom.

<Core Design>


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Title: **Free Fall Sensor**

Size	Document Number	Rev
Custom	Vostro Calpella	X01
Date: Monday, January 18, 2010	Sheet 40 of	91

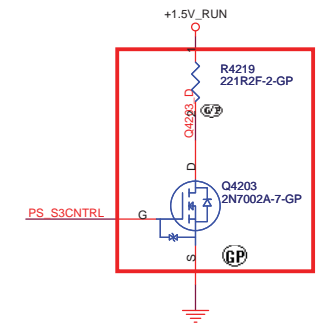
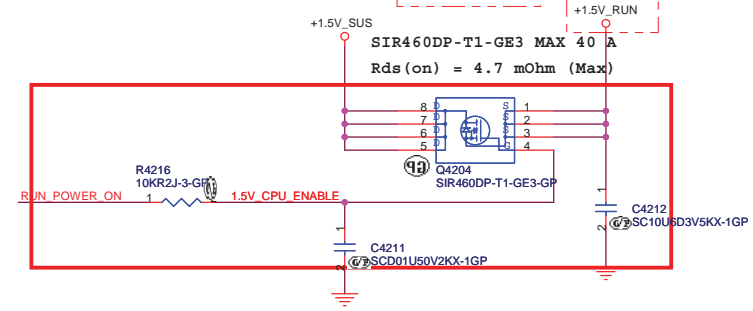
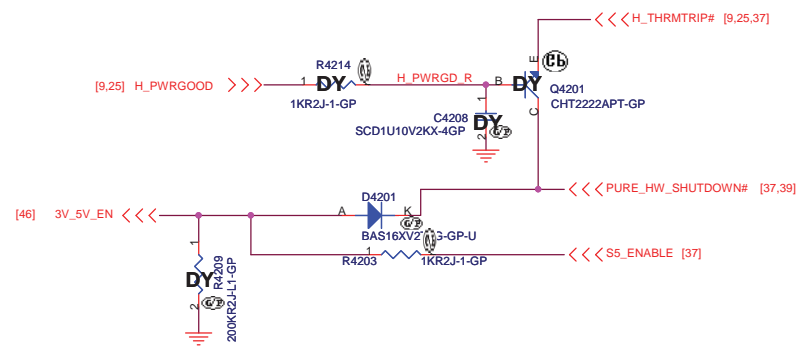
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<Core Design>

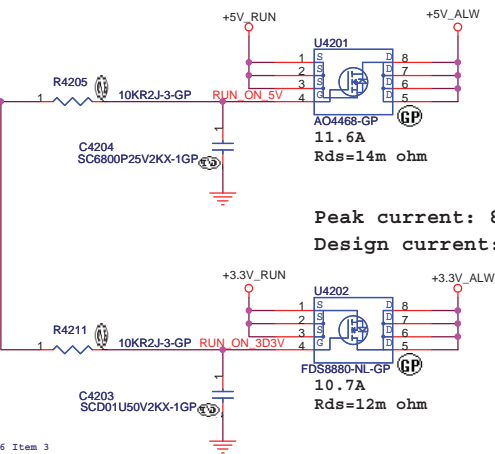
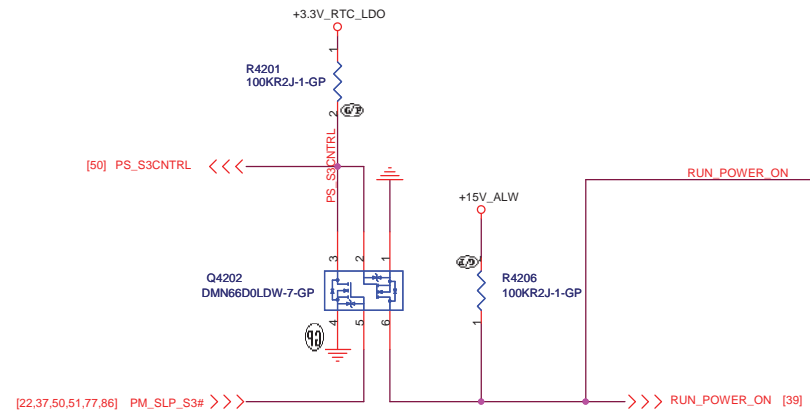
			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
Custom	Vostro Calpella				X01
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SSID = Reset.Suspend

+1.5V_RUN:
 Peak current: 4650 mA
 Design current: 3255 mA



Calpella Platform S3 Power Reduction Platform
 S3 Power Reduction CRB Implementation
 Design Details
 Revision 0.1

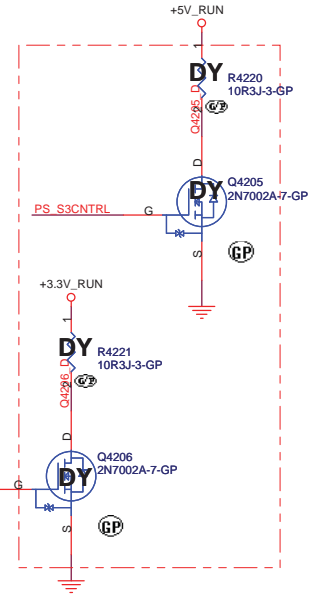


Peak current: 5605.6mA (HD:1100 ODD:2500)
 Design current: 3923.92 mA

Peak current: 8379.2 mA
 Design current: 5865.4 mA

DW
 12/08 Item 1

DW
 10/26 Item 3

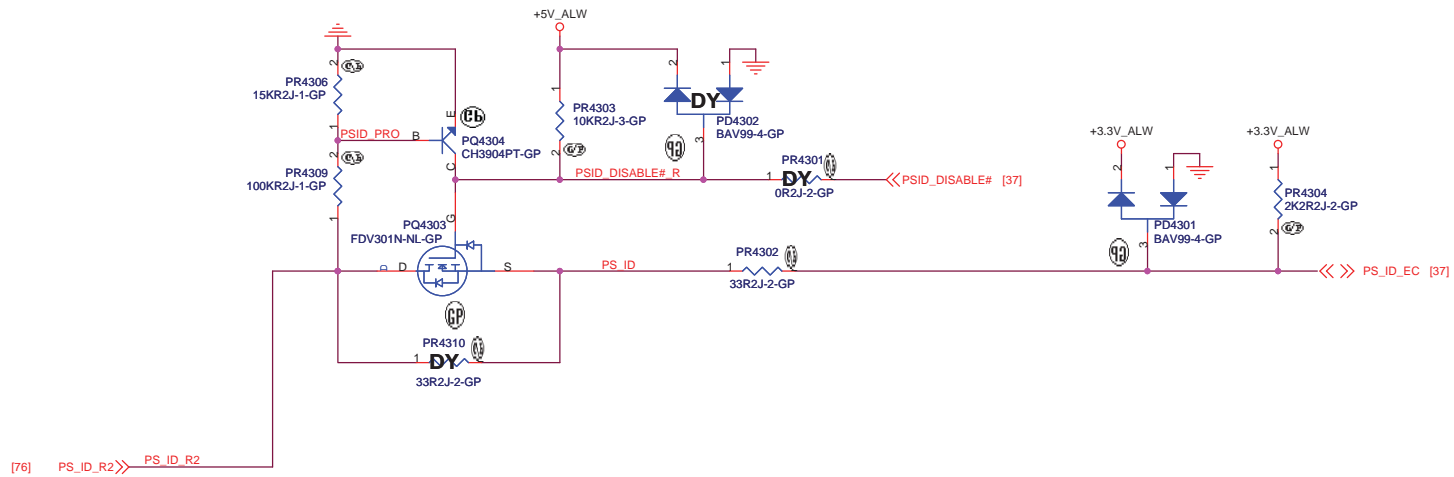


<Core Design>

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Title: **Power Plane Enable**

Size	Document Number	Rev
Custom	Vostro Calpella	X01
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<http://laptop-motherboard-schematic.blogspot.com/>

<Core Design>

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Title		
DC IN		
Size	Document Number	Rev
Custom	Vostro Calpella	X01
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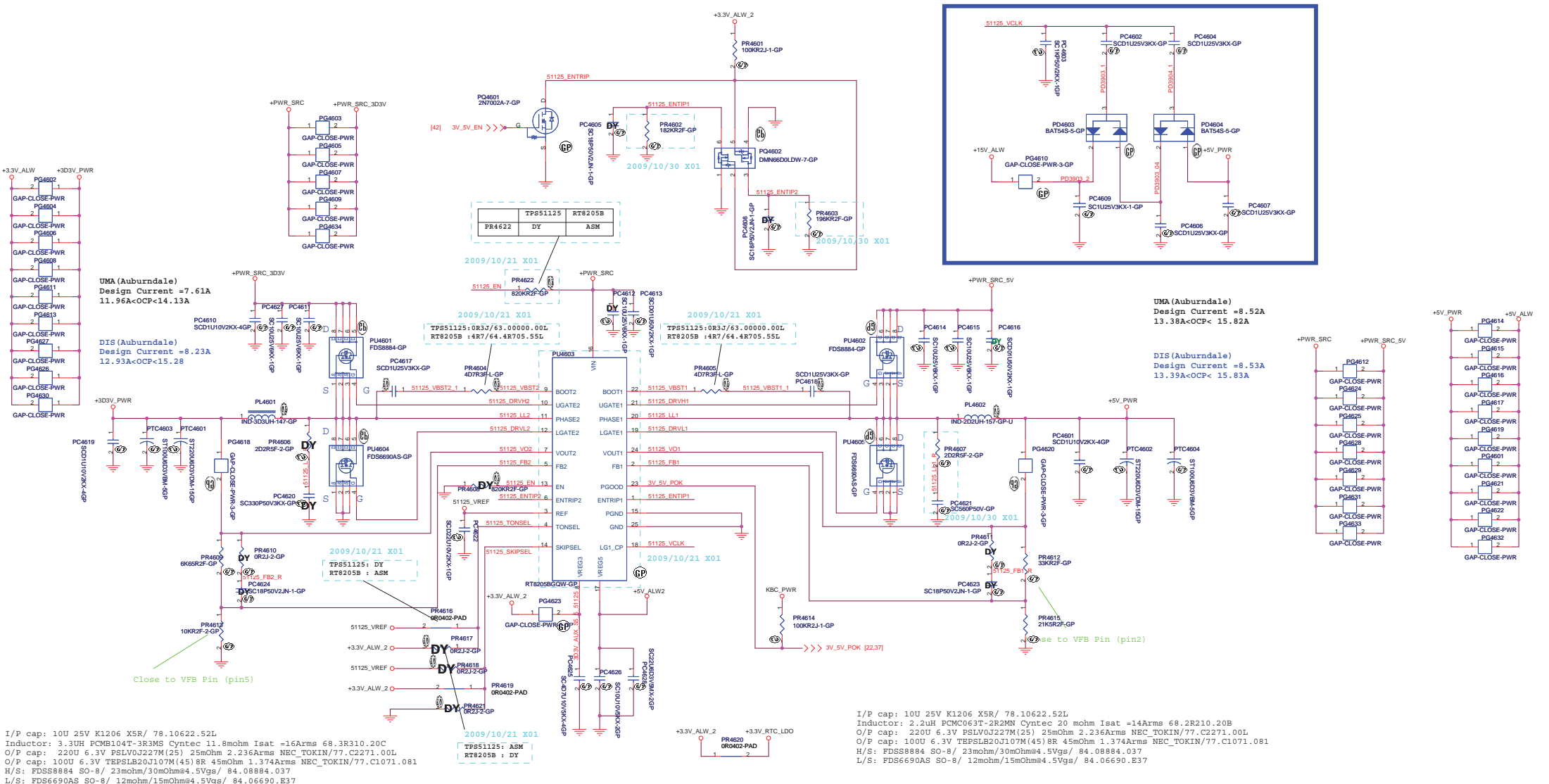
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		Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title		
(Reserve)		
Size A3	Document Number Vostro Calpella	Rev X01
Date: Monday, January 18, 2010	Sheet 44 of 91	

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<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
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Date: Monday, January 18, 2010			Sheet	45	of 91



UMA (Auburndale)
Design Current = 7.61A
11.96A < OCP < 14.13A

DIS (Auburndale)
Design Current = 8.23A
12.93A < OCP < 15.28

UMA (Auburndale)
Design Current = 8.52A
13.38A < OCP < 15.82A

DIS (Auburndale)
Design Current = 8.53A
13.39A < OCP < 15.83A

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 3.3UH PCMB104T-3R3MS Cyntec 11.8mohm Isat =16Arms 68.3R310.20C
O/P cap: 220U 6.3V PSLV0J227M(25) 25mohm 2.236Arms NEC_TOKIN/77.C2271.00L
O/P cap: 100U 6.3V TEPSLB20J107M(45) 8R 45mohm 1.374Arms NEC_TOKIN/77.C1071.081
H/S: FDS8884 SO-8/ 23mohm/30mohm@4.5Vgs/ 84.08884.037
L/S: FDS6690AS SO-8/ 12mohm/15mohm@4.5Vgs/ 84.06690.E37

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 2.2uH PCMC063T-2R2MN Cyntec 20 mohm Isat =14Arms 68.2R210.20B
O/P cap: 220U 6.3V PSLV0J227M(25) 25mohm 2.236Arms NEC_TOKIN/77.C2271.00L
O/P cap: 100U 6.3V TEPSLB20J107M(45) 8R 45mohm 1.374Arms NEC_TOKIN/77.C1071.081
H/S: FDS8884 SO-8/ 23mohm/30mohm@4.5Vgs/ 84.08884.037
L/S: FDS6690AS SO-8/ 12mohm/15mohm@4.5Vgs/ 84.06690.E37

TONSEL	CH1	CH2	SKIPSEL	VREG3 or VREG5	VREF (2V)	GND
GND	200kHz	265kHz	Operating Mode	OOA Auto Skip	Auto Skip	PWM only
VREF	245kHz	305kHz				
VREG3	300kHz	375kHz				
VREG5	365kHz	460kHz				

EN0	Operating Mode	VREG3 or VREG5	GND
Open	enable both LDOs, VCLK on and ready to turn on switcher channels	820kΩ to GND	GND

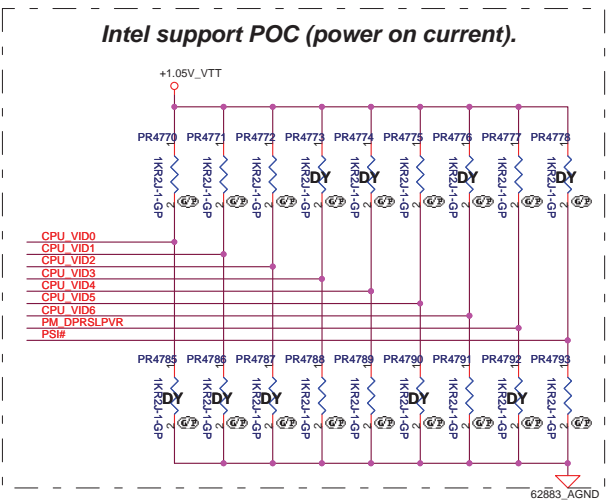
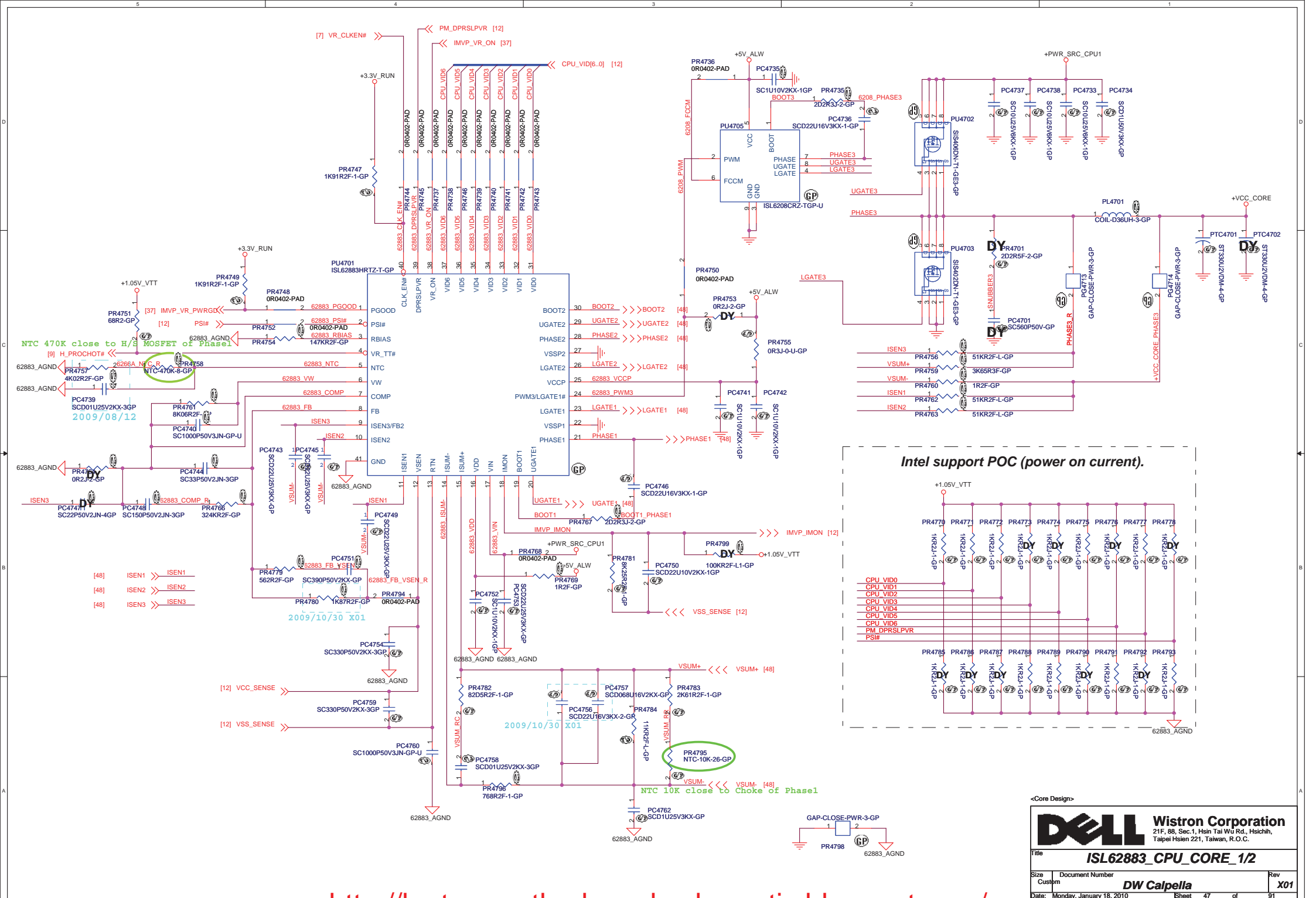
Core Design

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File: **RT8205B_5V/3D3V**

Size: Document Number **DW Calpella** Rev **X01**

Date: Monday, January 18, 2010 Sheet 46 of 91

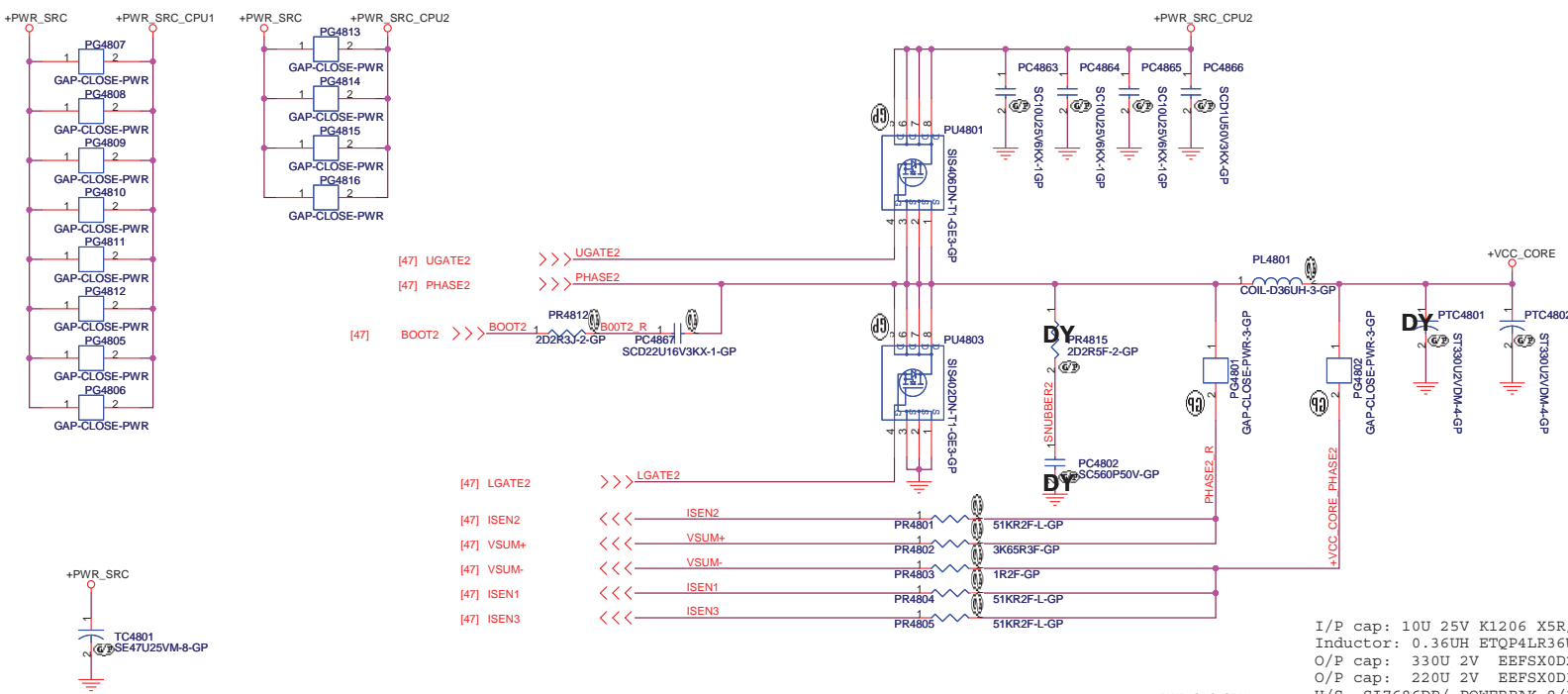


<Core Design>

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Title: **ISL62883_CPU_CORE_1/2**

Size	Document Number	Rev
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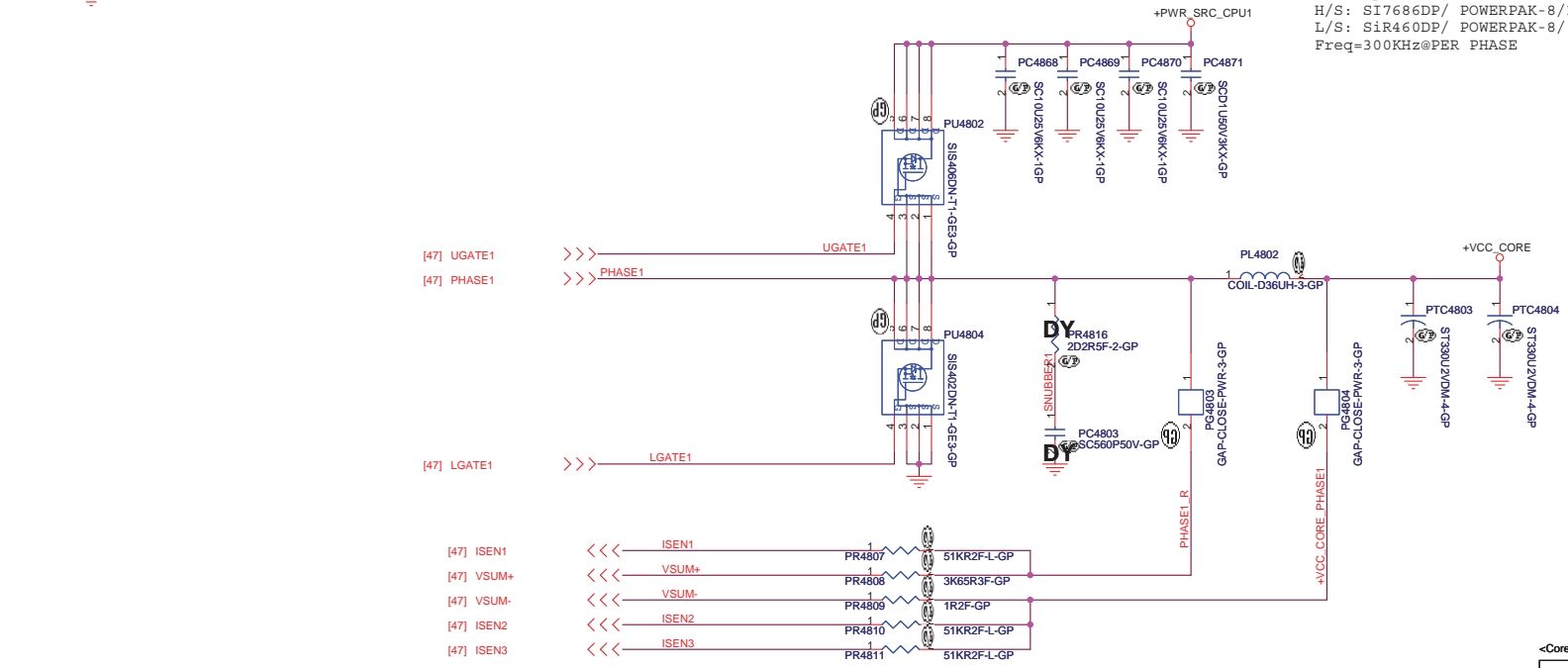
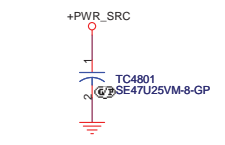


- [47] UGATE2 >>> UGATE2
- [47] PHASE2 >>> PHASE2
- [47] BOOT2 >>> BOOT2
- [47] LGATE2 >>> LGATE2
- [47] ISEN2 <<< ISEN2
- [47] VSUM+ <<< VSUM+
- [47] VSUM- <<< VSUM-
- [47] ISEN1 <<< ISEN1
- [47] ISEN3 <<< ISEN3

DIS(Auburndale)
 Design Current = 34A
 Peak Current=48A
 57.6A<OCP< 67.2A

UMA(Auburndale)
 Design Current = 34A
 Peak Current=48A
 57.6A<OCP< 67.2A

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
 Inductor: 0.36UH ETQP4LR36WFC PANASONIC 1.1mohm/ 68.R3610.20A
 O/P cap: 330U 2V BEFSX0D221E7 6mOhm 3.0Arms Panasonic/79.33719.20L
 O/P cap: 220U 2V BEFSX0D331XE 7mOhm 3.4Arms Panasonic/79.22719.90L
 H/S: SI7686DP/ POWERPAK-8/11mOhm/14mOhm@4.5Vgs/ 84.07686.037
 L/S: SiR460DP/ POWERPAK-8/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037
 Freq=300KHz@PER PHASE



- [47] UGATE1 >>> UGATE1
- [47] PHASE1 >>> PHASE1
- [47] LGATE1 >>> LGATE1
- [47] ISEN1 <<< ISEN1
- [47] VSUM+ <<< VSUM+
- [47] VSUM- <<< VSUM-
- [47] ISEN2 <<< ISEN2
- [47] ISEN3 <<< ISEN3

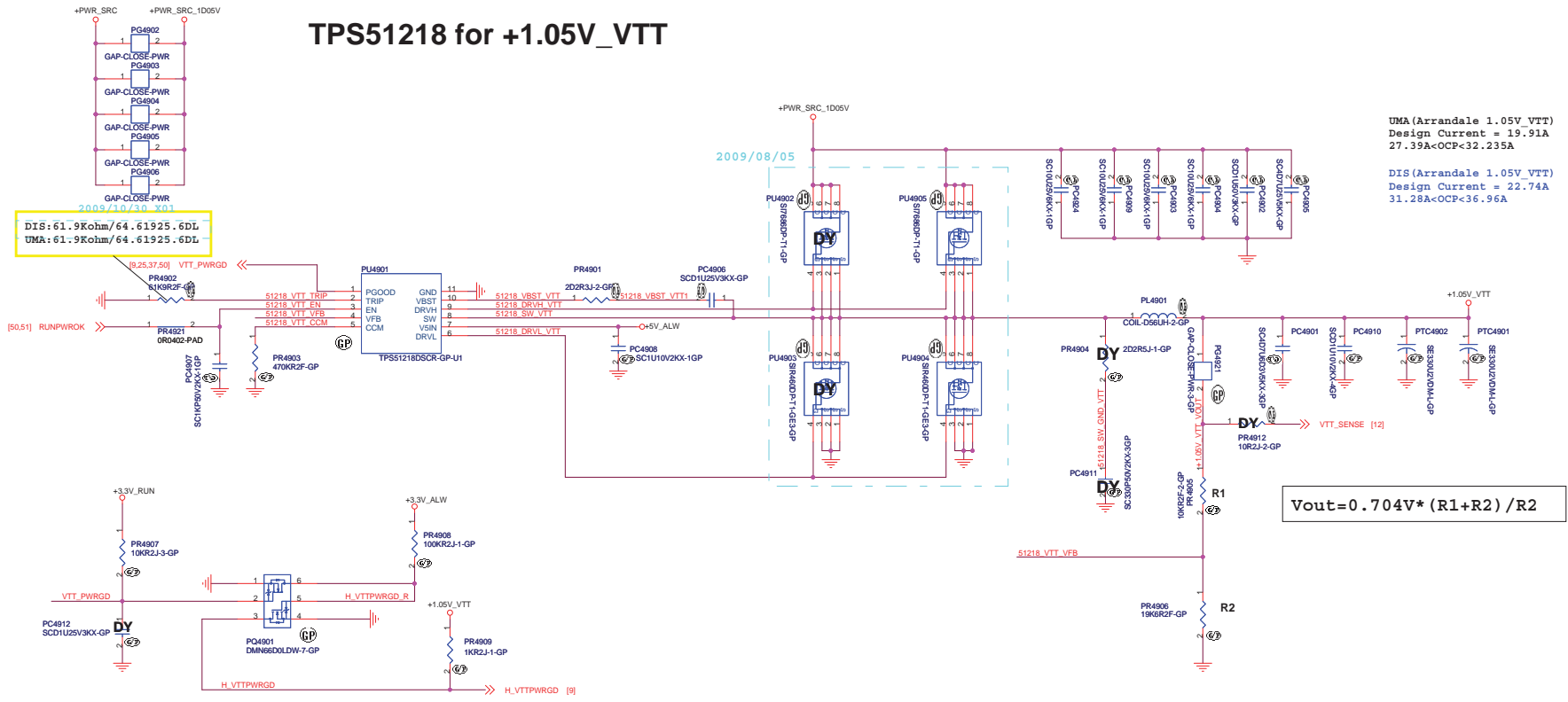
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Title **ISL62883_CPU_CORE_2/2**

Size	Document Number	Rev
Customer	DW Calpella	X01
Doc No	January 18, 2010	Sheet 48 of 91

TPS51218 for +1.05V_VTT



UMA(Arrandale 1.05V_VTT)
Design Current = 19.91A
27.39A<OCP<32.235A

DIS(Arrandale 1.05V_VTT)
Design Current = 22.74A
31.28A<OCP<36.96A

DIS: 61.9Kohm/64.61925.6DL
UMA: 61.9Kohm/64.61925.6DL

Frequency setting
470K -->290KHz
200K -->340KHz
100K -->380KHz
39K -->430KHz

$$V_{out} = 0.704V * (R1 + R2) / R2$$

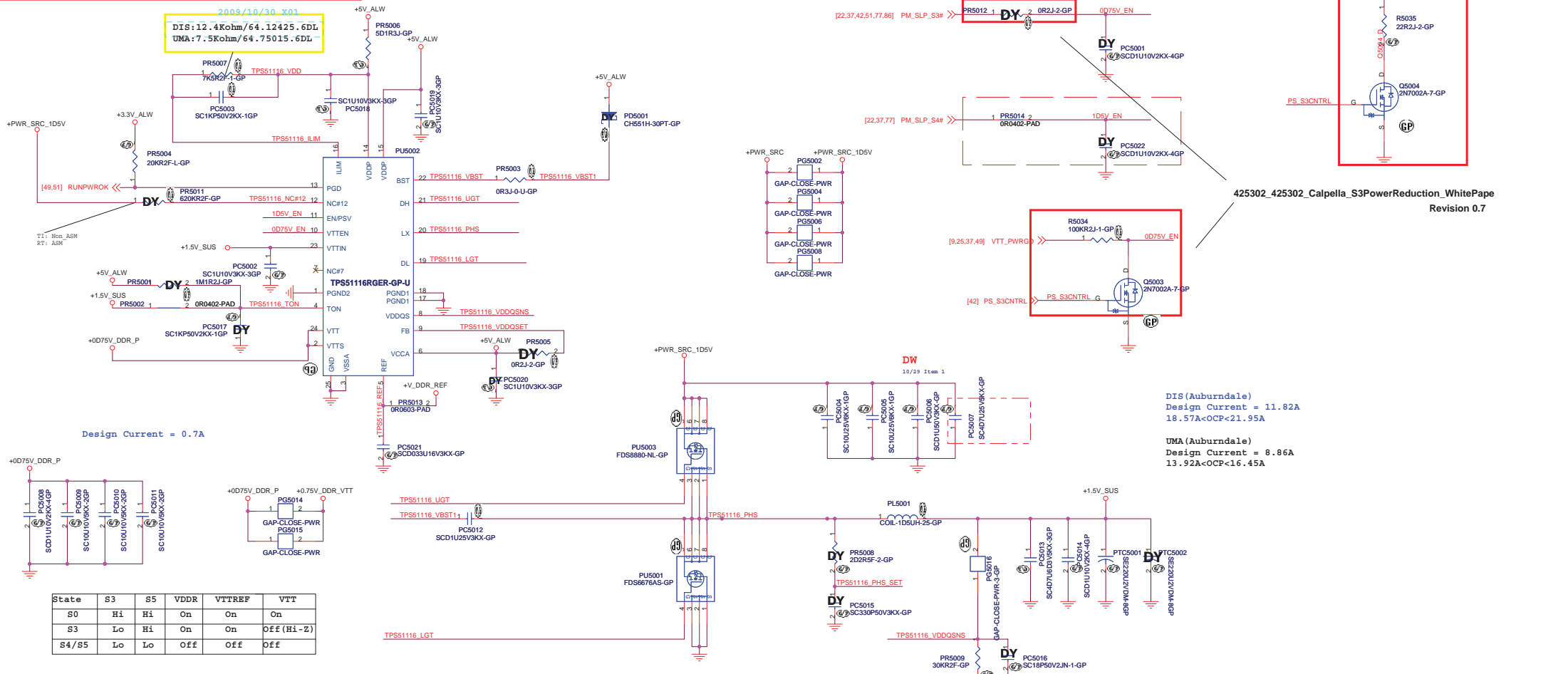
I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 0.56uH PCMC104T-R56MN Cyntec DCR:1.8mohm Isat=25Arms 68.R5610.10D
O/P cap: 330U 2.5V EBF5X0D331ER 9mOhm 3Arms PANASONIC/ 79.33719.L01
H/S: SIR474DP-T1-GE3/10mohm/ 12mOhm@4.5Vgs/ 84.00474.037
L/S: SI7170DP-T1-GE3/3.6mOhm/4.3mohm@4.5Vgs/ 84.07170.037

<Core Design>

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Title		TPS51218 +1.05V_VTT	
Size	Document Number	Rev	
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SSID = PWR.Plane.Regulator_1p5v0p75v

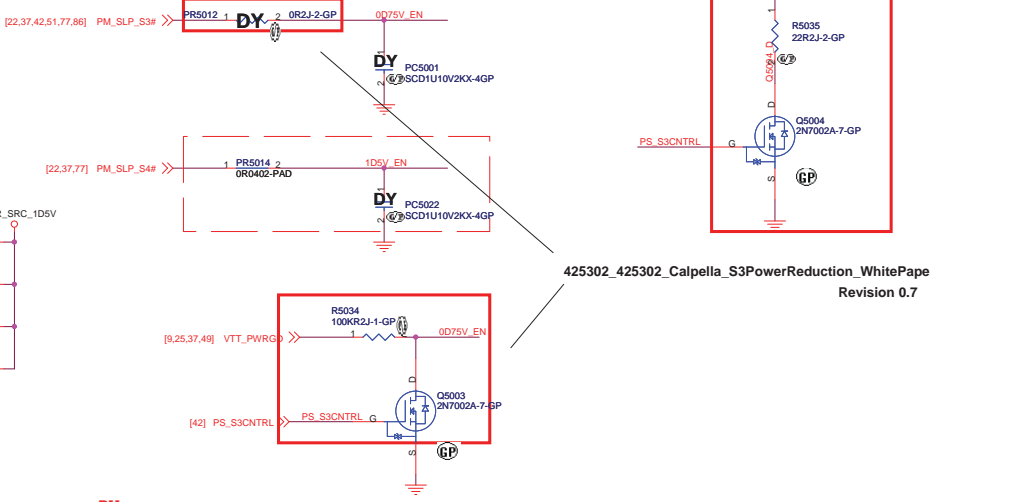


Design Current = 0.7A

State	S3	S5	VDDR	VTTREF	VTT
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off	Off	Off

VDDQSET	VDDQ (V)	VTTREF and VTT	NOTE
GND	2.5	VVDDQSNS/2	DDR
V5IN	1.8	VVDDQSNS/2	DDR2
FB Resistors	Adjustable	VVDDQSNS/2	1.5 V < VVDDQ < 3 V

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
 Inductor: 1.5UH PCMC104T-1R5MN Cyntec DCR:4.2mohm Isat =33Arms 68.1R510.10J
 O/P cap: 220U 2V EBFCKOD221ER 15mOhm 2.7Arms PANASONIC/ 79.22719.20L
 H/S: FDS8890 SO-8/ 9.6mOhm/12mOhm @4.5Vgs/ 84.08880.037
 L/S: FDS8672S SO-8/ 5.3mOhm/7.0mOhm@4.5Vgs/ 84.08672.A37
 Switching freq-->400KHz



425302_425302_Calpella_S3PowerReduction_WhitePape
 Revision 0.7

DIS (Auburdale)
 Design Current = 11.82A
 18.57A<OCP<21.95A
 UMA (Auburdale)
 Design Current = 8.86A
 13.92A<OCP<16.45A

<Core Design>

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 Taipei Hsien 221, Taiwan, R.O.C.

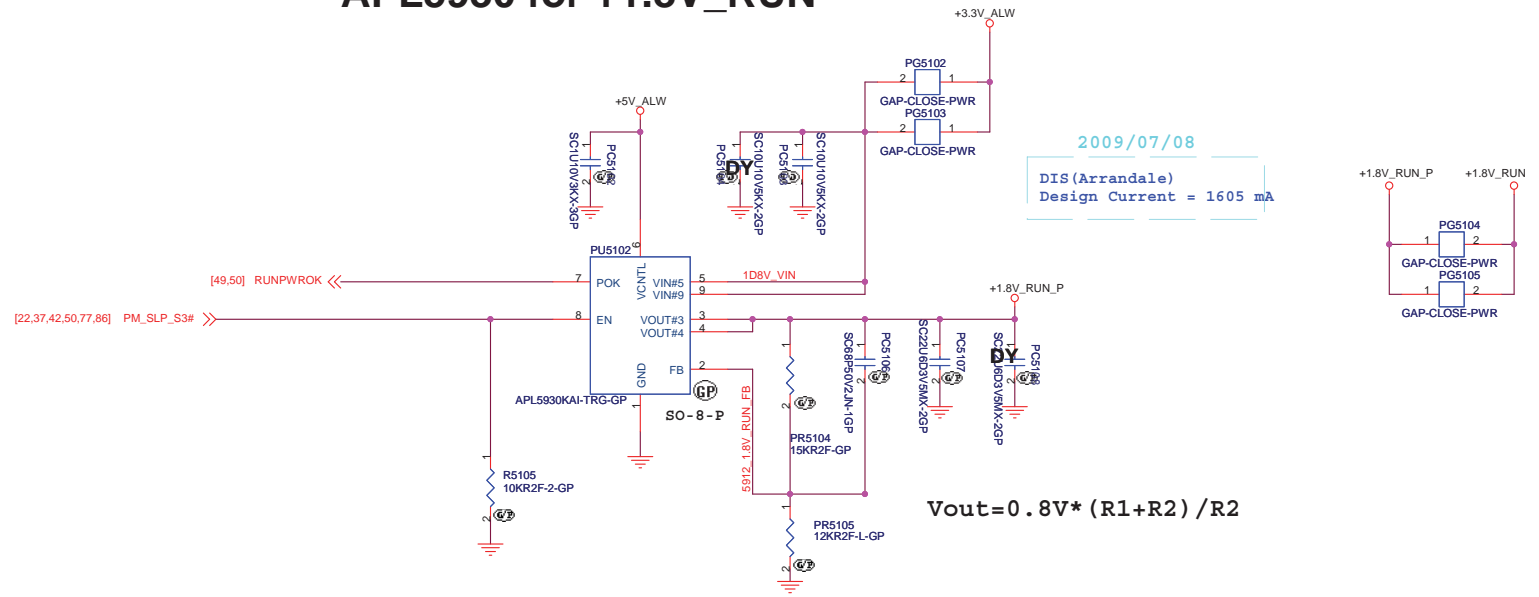
Title: **TPS51116 +1.5V SUS**

Size: Custom | Document Number: DW Calpella | Rev: X01

Date: Monday, January 18, 2010 | Sheet: 50 of 91

SSID = PWR.Plane.Regulator_1p8v

APL5930 for +1.8V_RUN




<Core Design>

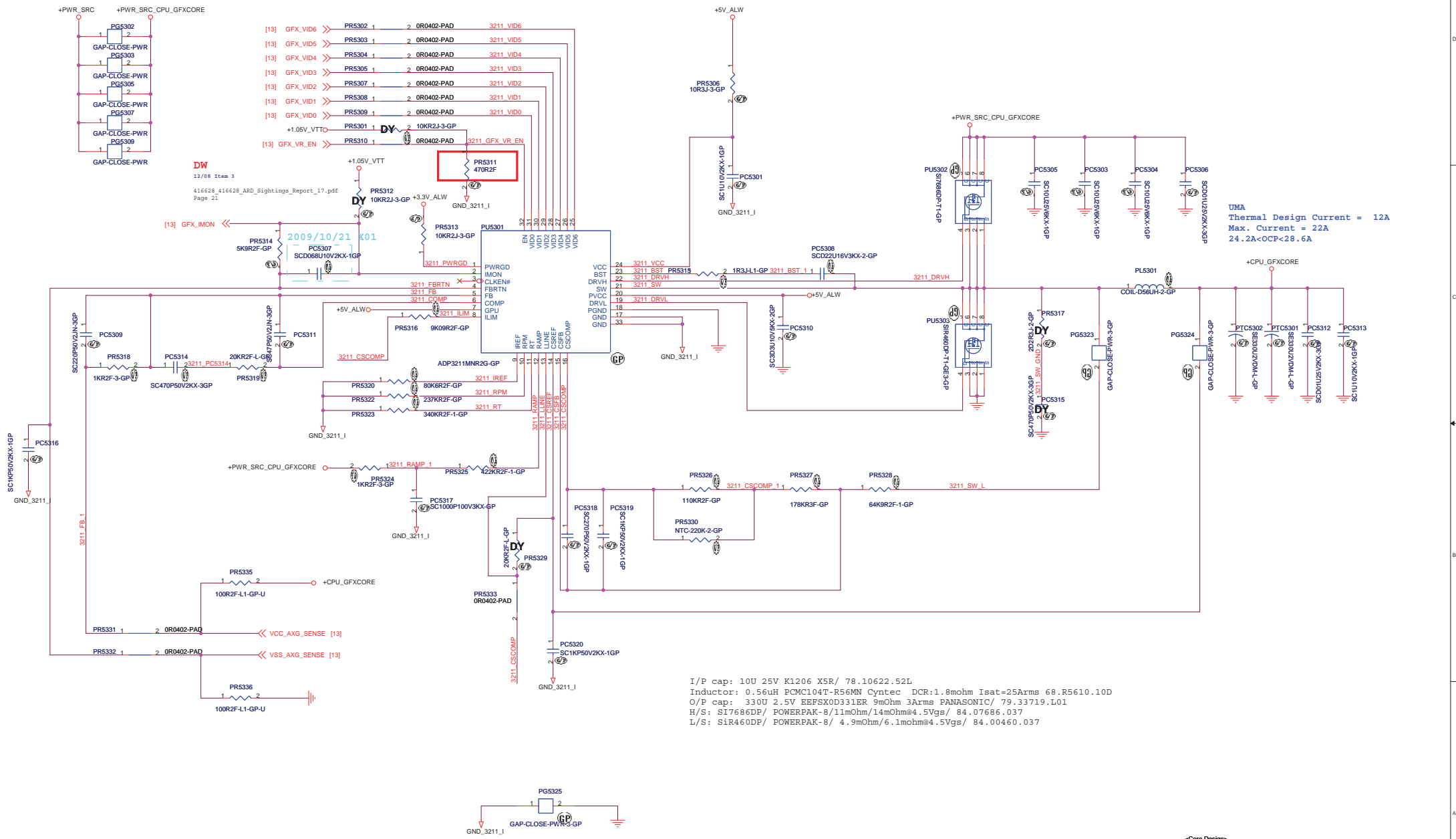
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
APL5930 +1.8V RUN			
Size	Document Number	Rev	
Custom	DW Calpella	X01	
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<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
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SSID = CPU.GFX.Regulator



I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
 Inductor: 0.56uH PCMC104T-R56MN Cyntec DCR:1.8mohm Isat=25Arms 68.R5610.10D
 O/P cap: 330U 2.5V EEFSX0D331ER 9mOhm 3Arms PANASONIC/ 79.33719.L01
 H/S: SI7686DP/ POWERPAK-B/11mOhm/14mOhm@4.5Vgs/ 84.07686.037
 L/S: SiR460DP/ POWERPAK-B/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037

UMA Thermal Design Current = 12A
 Max. Current = 22A
 24.2A < OCP < 28.6A

<Core Design>

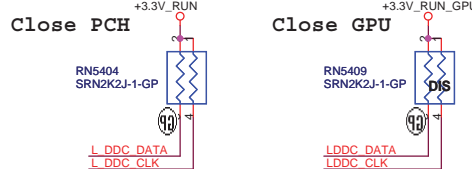
Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **ADP3211 CPU GFXCORE**

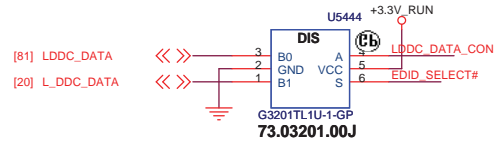
Size: Custom Document Number: **DW Calpella UMA** Rev: **X01**

Date: Monday, January 18 2010 Sheet 53 of 91

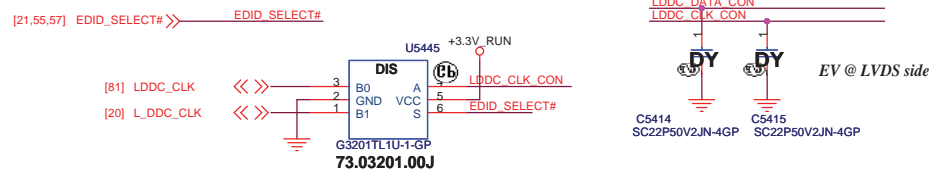
SSID = VIDEO



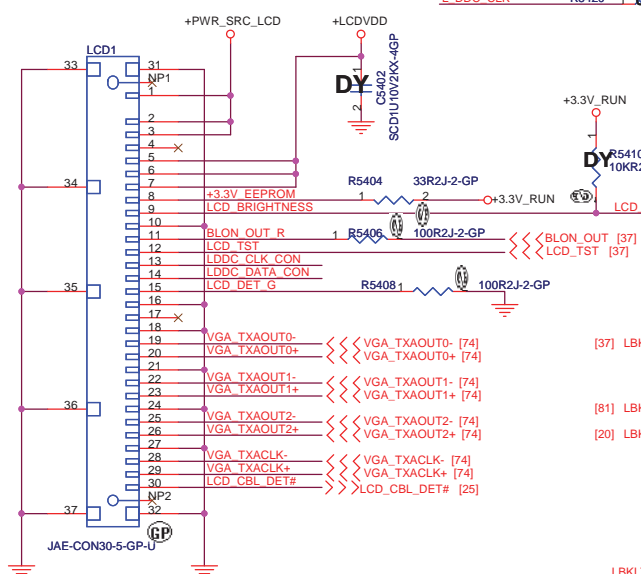
UMA/DIS LVDS DDC CLK/DAT select circuit



H=>B1 -iGPU PCH (UMA)
L=>B0 -dGPU GPU (DIS)

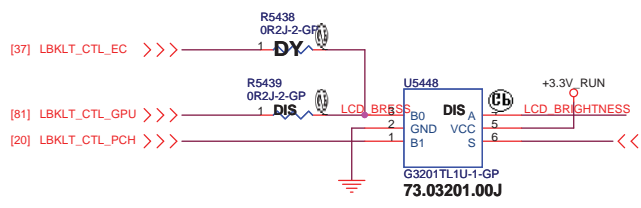


LVDS CONNECTOR

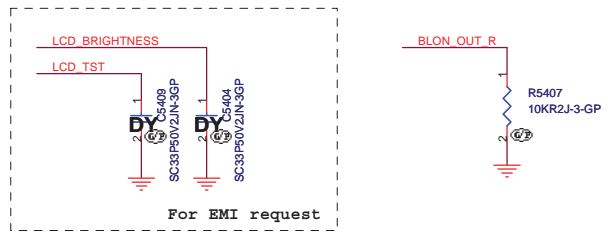


20.F1555.030

UMA/DIS LVDS PWM select circuit

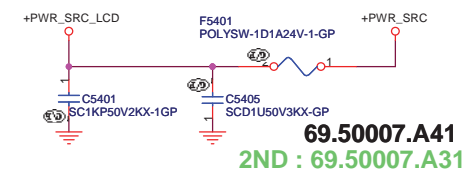


H=>B1 -iGPU PCH (UMA)
L=>B0 -dGPU GPU (DIS)



SSID = Inverter

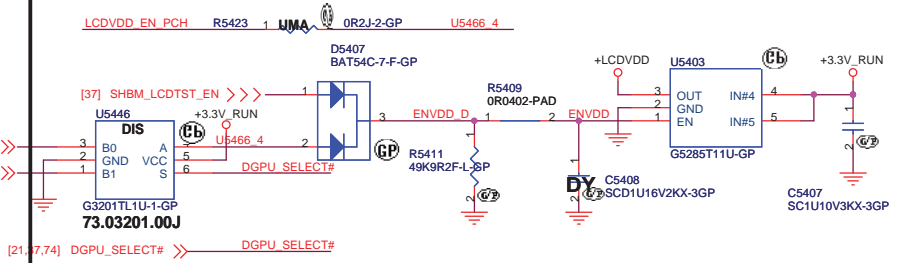
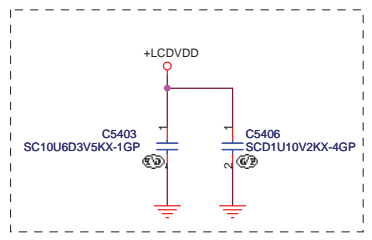
INVERTER POWER



69.50007.A41
2ND : 69.50007.A31

SSID = VIDEO

LCD POWER



H=>B1 -iGPU PCH (UMA)
L=>B0 -dGPU GPU (DIS)

<Core Design>

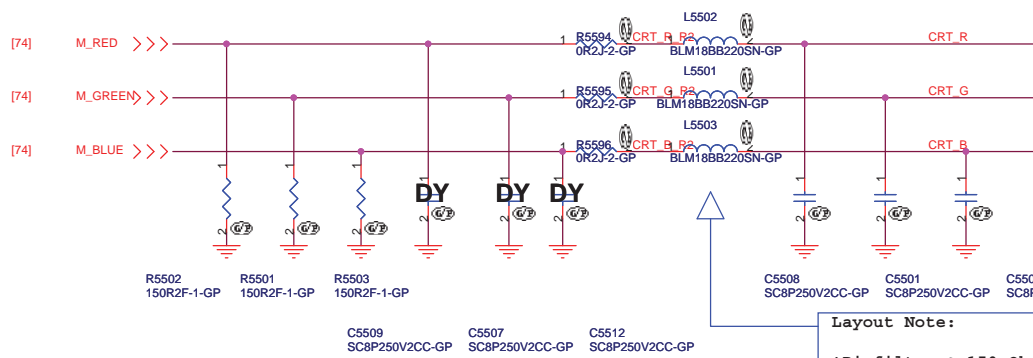
DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **LCD/Inverter Connector**

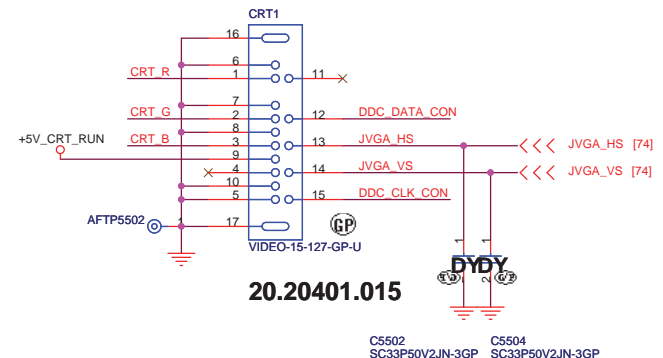
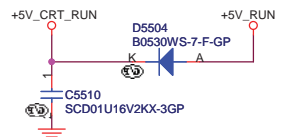
Size: Document Number
Custm: **Vostro Calpella**

Date: Monday, January 18, 2010 Sheet 54 of 91

SSID = VIDEO

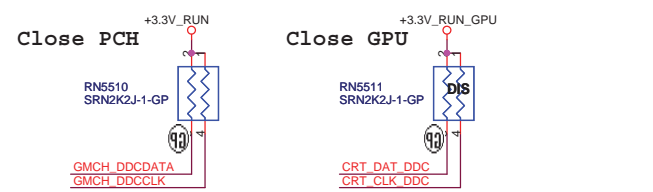


Layout Note:
 *Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN.
 * RGB signal will hit 75 Ohm first, then pi-filter, finally CRT CONN.

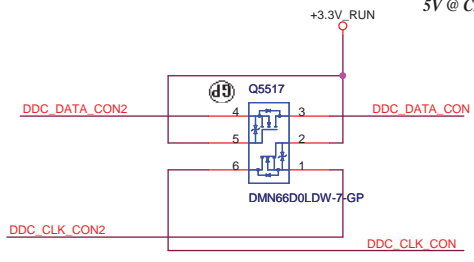
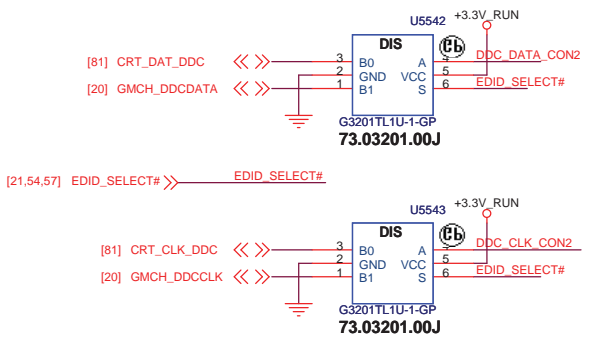
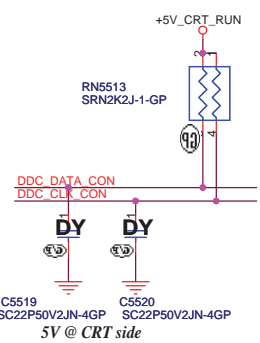


20.20401.015

- AFTP5503 @ 1 +5V_CRT_RUN
- AFTP5501 @ 1 DDC_DATA_CON
- AFTP5509 @ 1 DDC_CLK_CON
- AFTP5507 @ 1 CRT_R
- AFTP5506 @ 1 CRT_G
- AFTP5508 @ 1 CRT_B
- AFTP5504 @ 1 JVGA_HS
- AFTP5505 @ 1 JVGA_VS



UMA/DIS CRT DDC CLK/DAT select circuit



H=>B1 -iGPU PCH (UMA)
 L=>B0 -dGPU GPU (DIS)



<Core Design>


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Title: **CRT Connector**

Size: A3
 Document Number: **Vostro Calpella**
 Date: Monday, January 18, 2010
 Sheet: 55 of 91
 Rev: **X01**

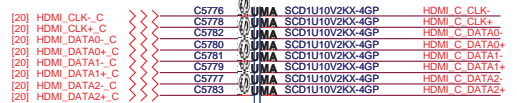
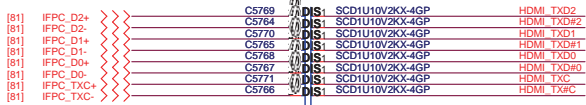
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<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
Custom	Vostro Calpella				X01
Date: Monday, January 18, 2010			Sheet	56	of 91

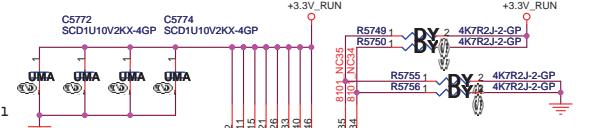
UMA/DIS HDMI signal select circuit

Place near connector



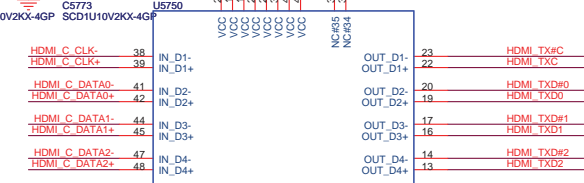
Close to PCH

UMA HDMI level shift circuit

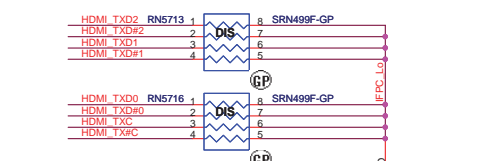


jitter elimination control

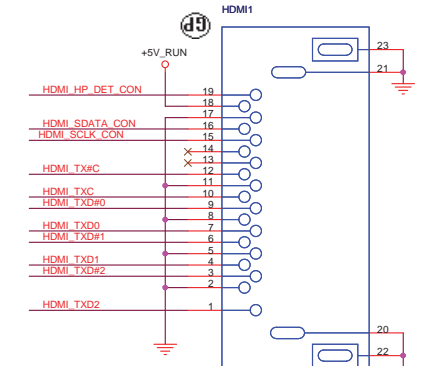
PC0	PC1	EQ
0	0	8db
0	1	4db
1	0	12db
1	1	0db



PS8101 TMDs inputs equalization control

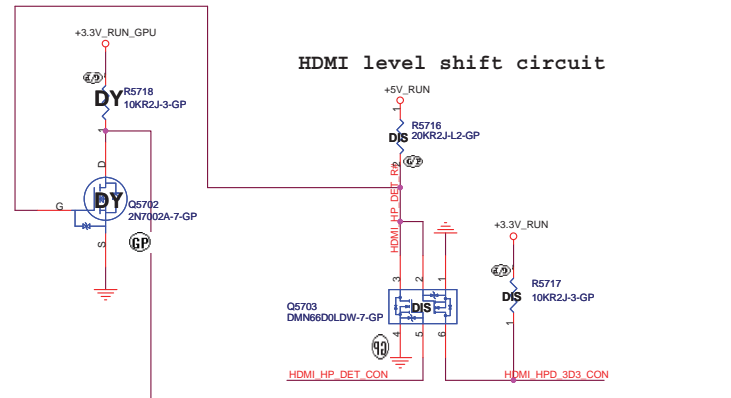


Place near connector



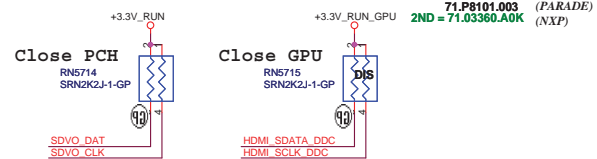
Close HDMI Connect

22.10296.061

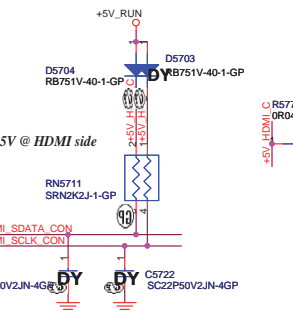
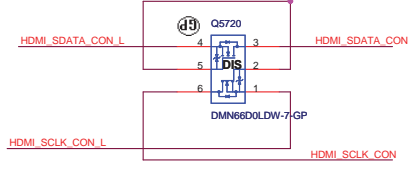
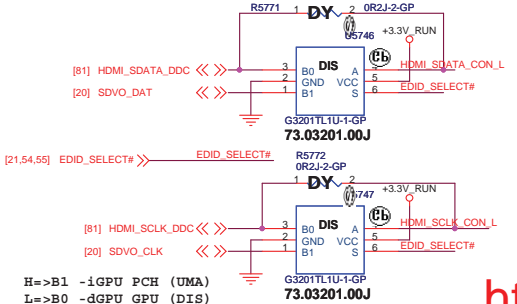


HDMI level shift circuit

UMA/DIS HDMI Detection select circuit



UMA/DIS HDMI DDC CLK/DAT select circuit



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<Core Design>

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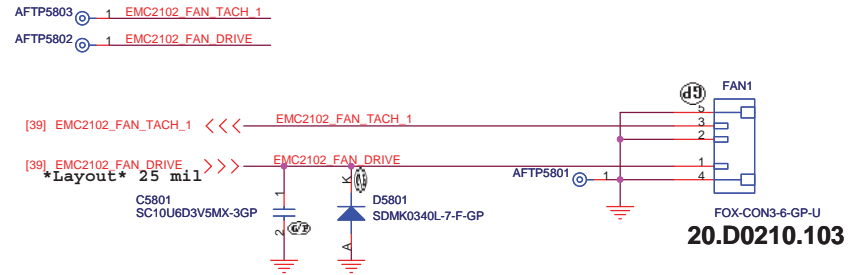
Title: **HDMI Connector**

Size: Document Number: **Vostro Calpella** Rev: **X01**

Date: Monday, January 18, 2010 Sheet 57 of 91

SSID = Thermal

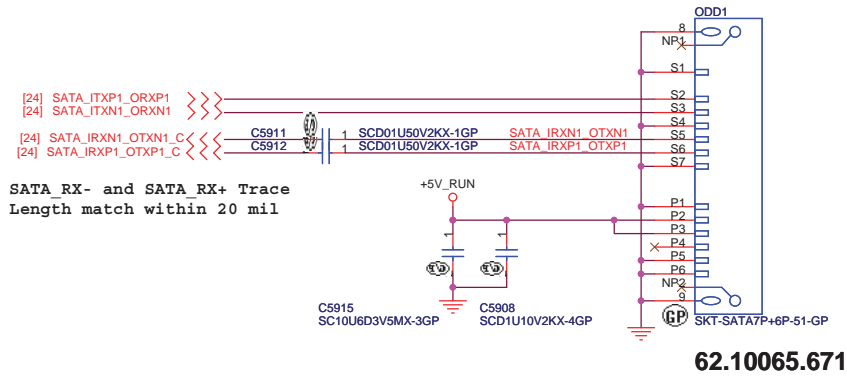
Fan Connector



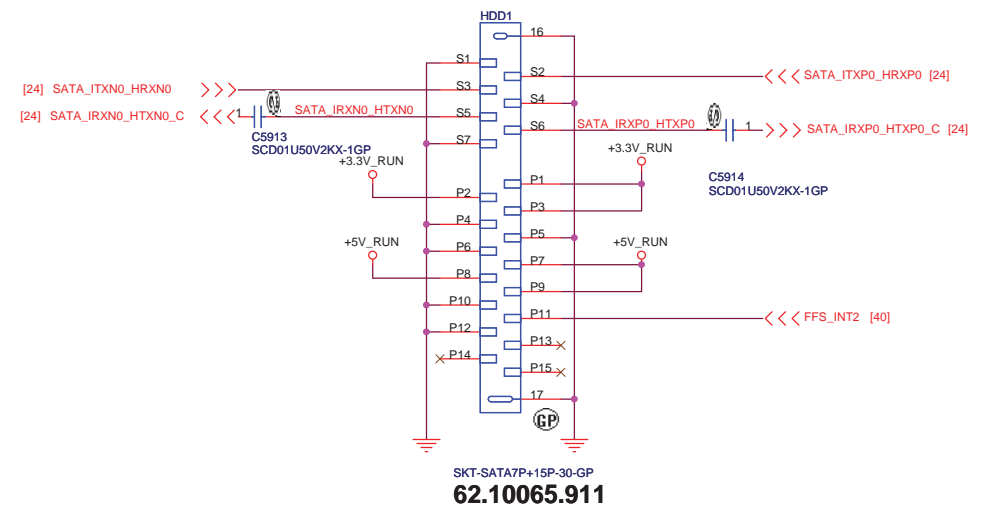
<Core Design>

DELL Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title FAN		
Size A3	Document Number Vostro Calpella	Rev X01
Date: Monday, January 18, 2010	Sheet 58 of 91	

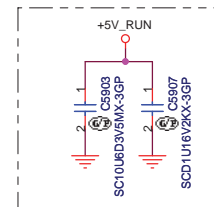
ODD Connector



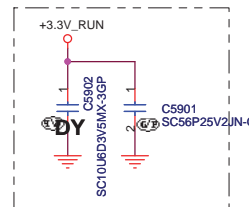
SATA HDD Connector



Close to CONN
5V power pin




Close to CONN
3.3V power pin




(Blank)

<Core Design>

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Title					
(Reserve)					
Size	Document Number				Rev
Custom	Vostro Calpella				X01
Date: Monday, January 18, 2010			Sheet	60	of 91

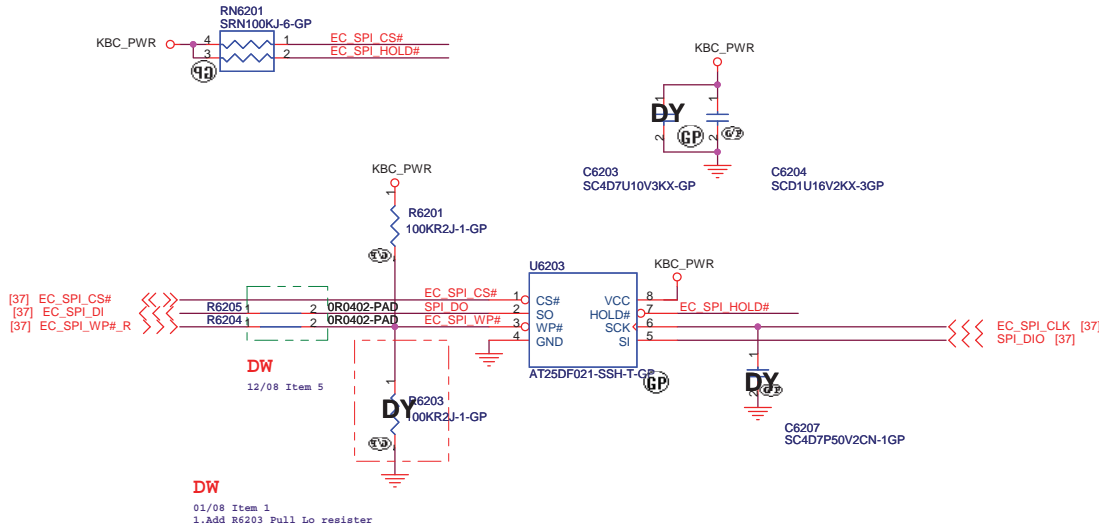
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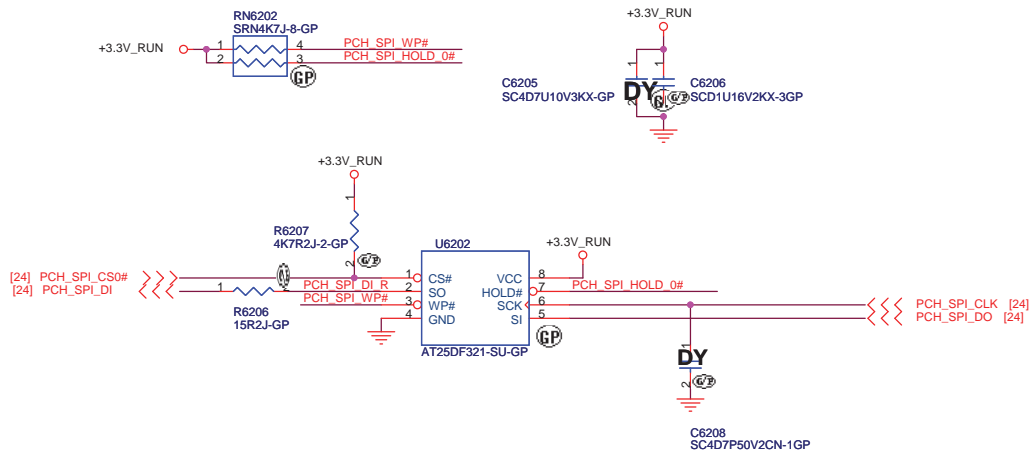
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title		
(Reserve)		
Size Custom	Document Number Vostro Calpella	Rev X01
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SSID = Flash.ROM

SPI FLASH ROM (256K bytes) for KBC

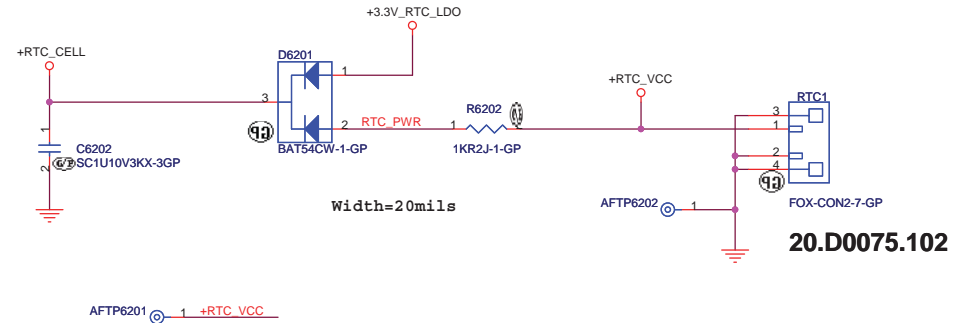


SPI FLASH ROM (4M bytes) for PCH



SSID = RBATT

RTC Connector



<Core Design>

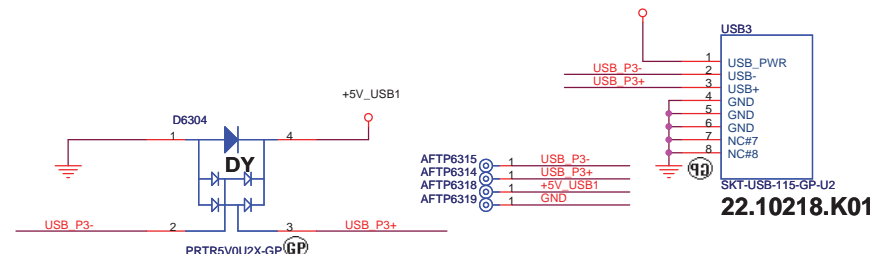
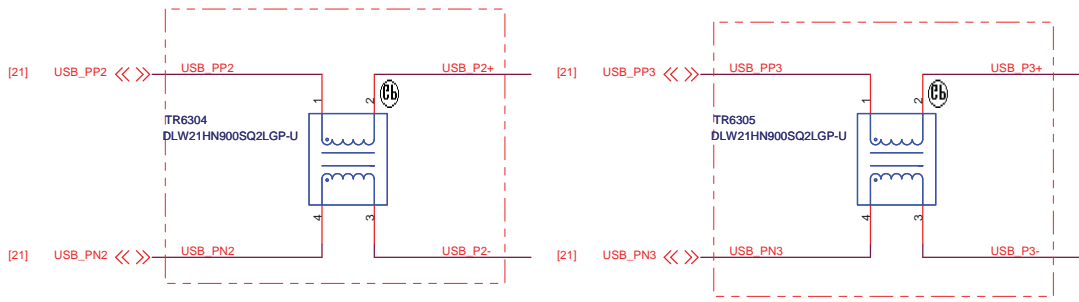
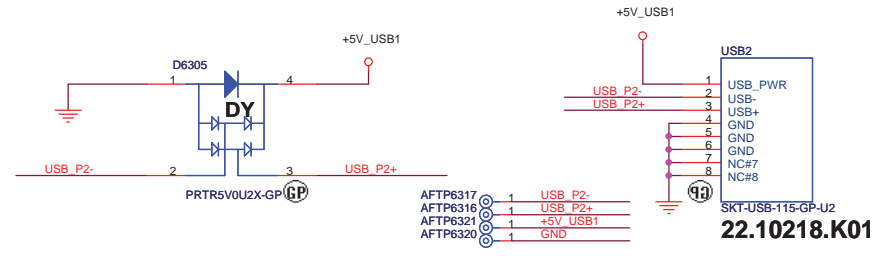
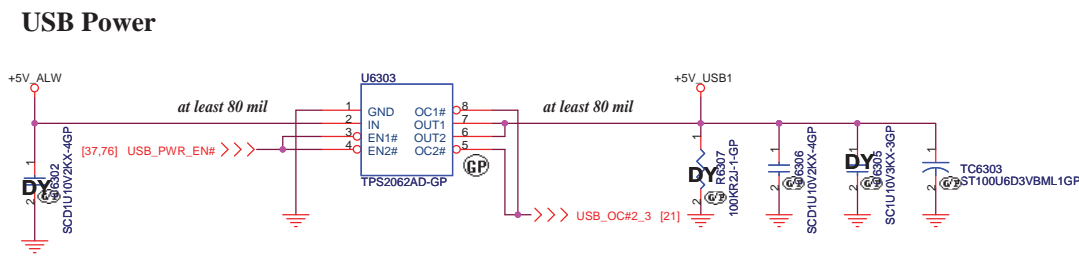
DELL Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title: **EEPROM/RTC Connector**

Size: A3	Document Number: Vostro Calpella	Rev: X01
Date: Monday, January 18, 2010	Sheet 62 of 91	

SSID = USB

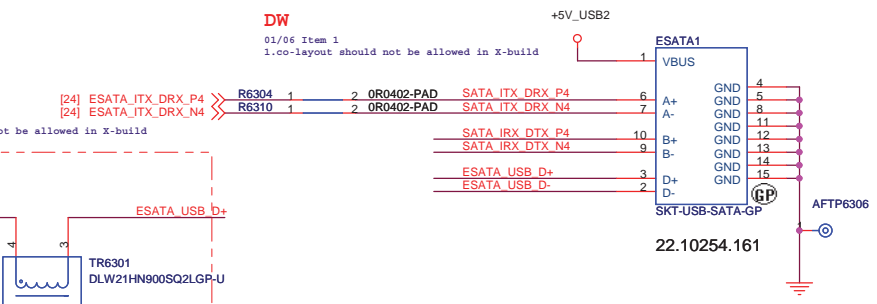
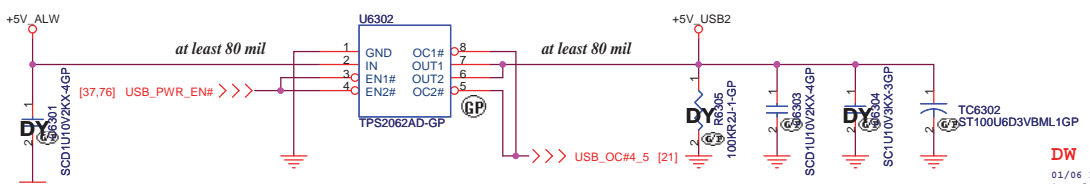
USB Power



DW
01/06 Item 1
1.co-layout should not be allowed in X-build

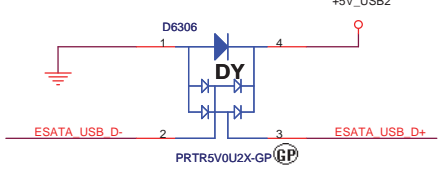
DW
01/06 Item 1
1.co-layout should not be allowed in X-build

ESATA Power



DW
01/06 Item 1
1.co-layout should not be allowed in X-build

DW
01/06 Item 1
1.co-layout should not be allowed in X-build



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Taipei Hsien 221, Taiwan, R.O.C.

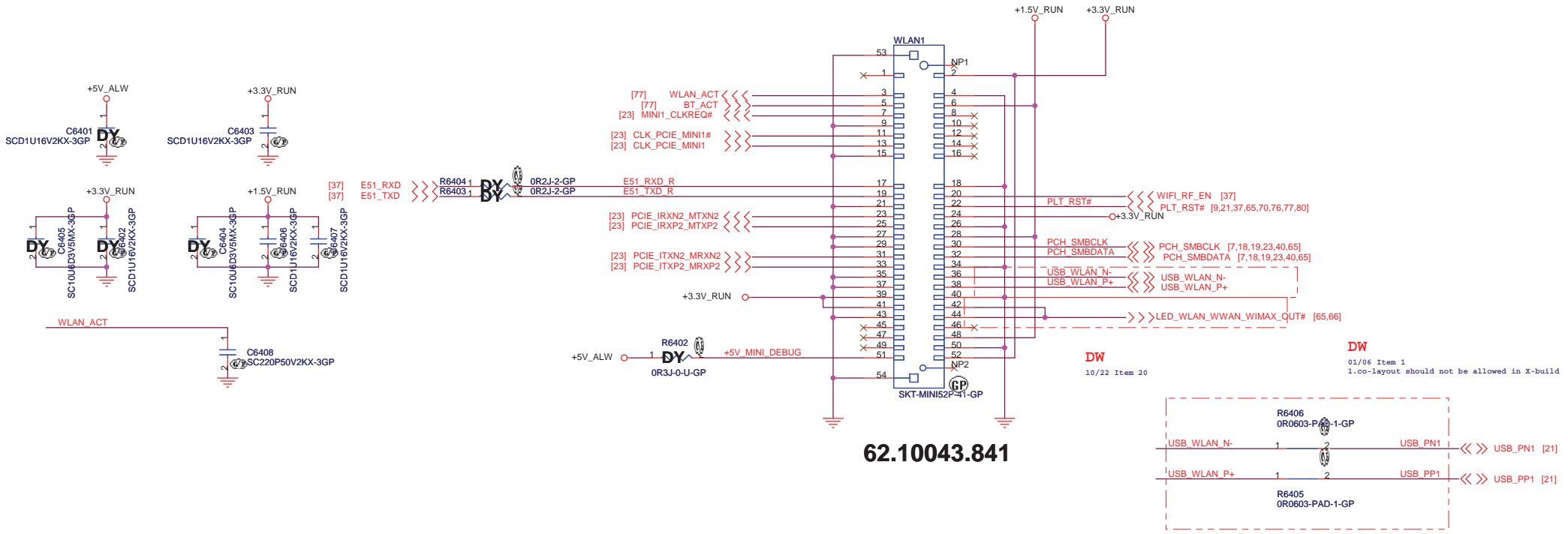
Title: **USB /ESATA Port**

Size	Document Number	Rev
Custom	Vostro Calpella	X01

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SSID = Wireless

Mini Card Connector(802.11a/b/g/n)



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Taipei Hsien 221, Taiwan, R.O.C.

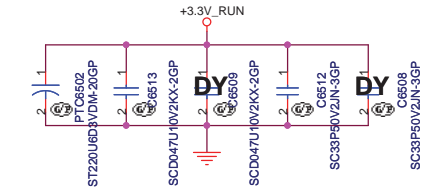
Title
MINICARD(WLAN)/ITP CONN

Size A3	Document Number Vostro Calpella	Rev X01
Date: Monday, January 18, 2010	Sheet 64 of 91	

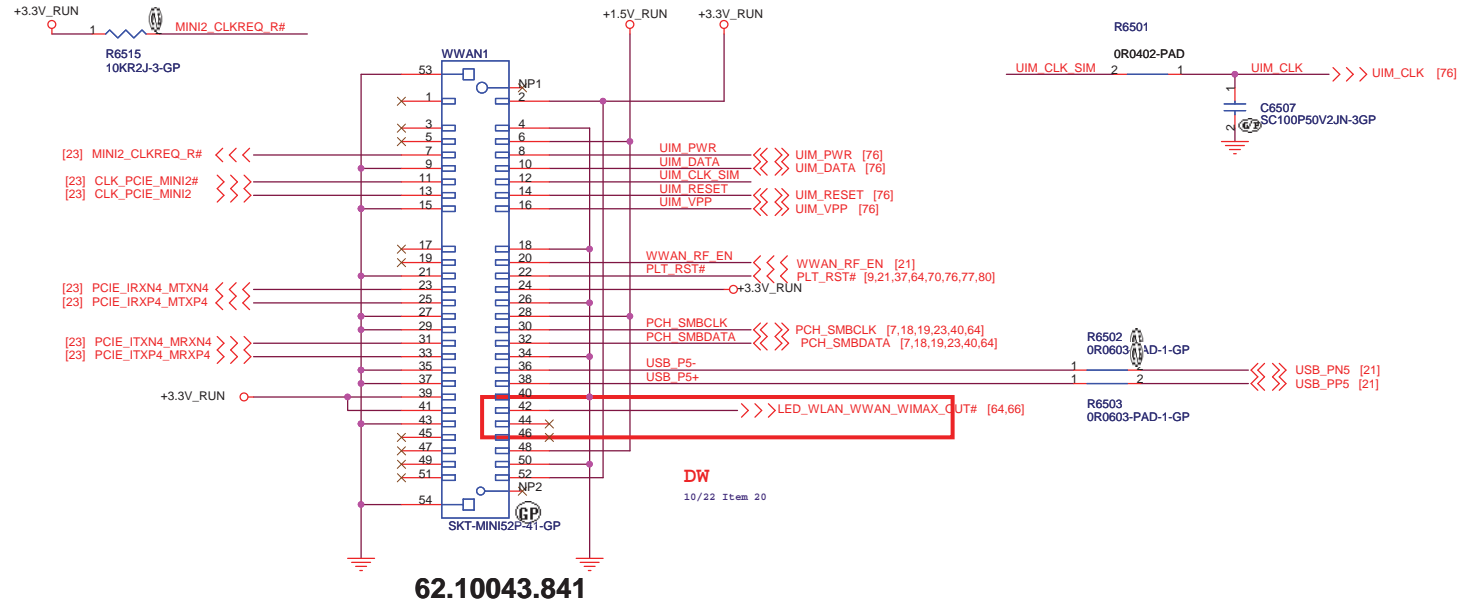
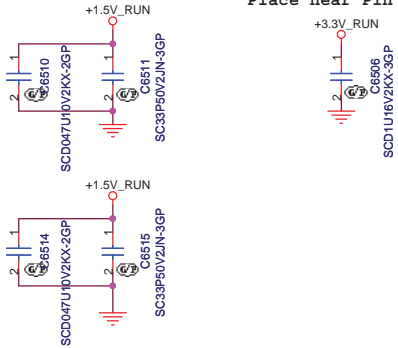
SSID = Wireless

Mini Card Connector(WWAN)

Place near MINI Card CONN



Place near Pin 24



<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

Title: **WWAN Connector**

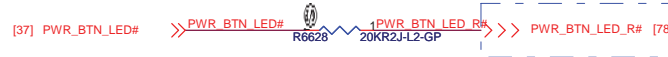
Size A3	Document Number Vostro Calpella	Rev X01
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For LED & Capacity board:

LED Type	Color	Power rail
SCRL LED	White	ALW
CAP LED	White	ALW
NUM LED	White	ALW
PWR BTN LED	White	ALW
SATA ACT LED1	White	RUN
BT ACT LED	White	RUN
WLAN WWAN WIMAX LED	White	RUN

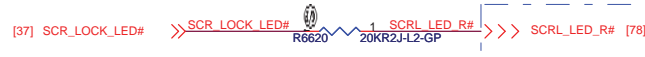
PWR BTN LED

For LED & Capacity board

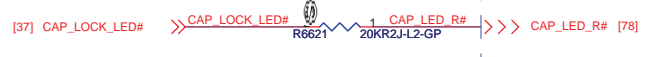


SCRLK LED

For LED & Capacity board:



CAPS LED



NUM LED



Remove BJT to daughter board

Bluetooth LED

For LED & Capacity board:

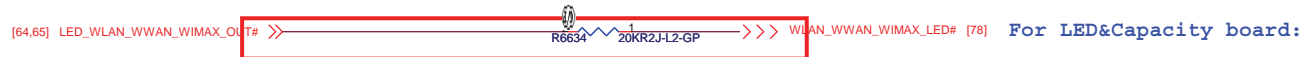


For IO board

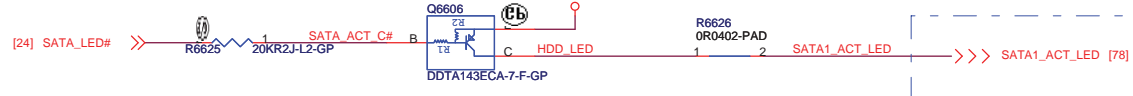
LED Type	Color	Power rail
PWR LED2	White (Multi-color)	ALW
BATTERY LED2	Amber (Multi-color)	ALW
	White (Multi-color)	ALW

WLAN WWAN WIMAX LED

DW
10/22 Item 20

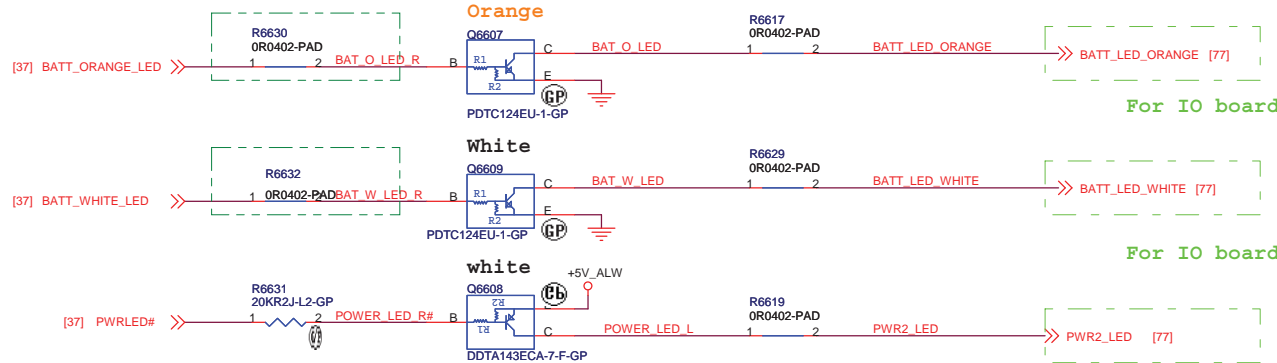


HD LED



Battery & Power LED

DW
12/08 Item 5



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<Core Design>


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Title: **LED**

Size A3	Document Number Vostro Calpella	Rev X01
Date: Monday, January 18, 2010	Sheet 66 of 91	

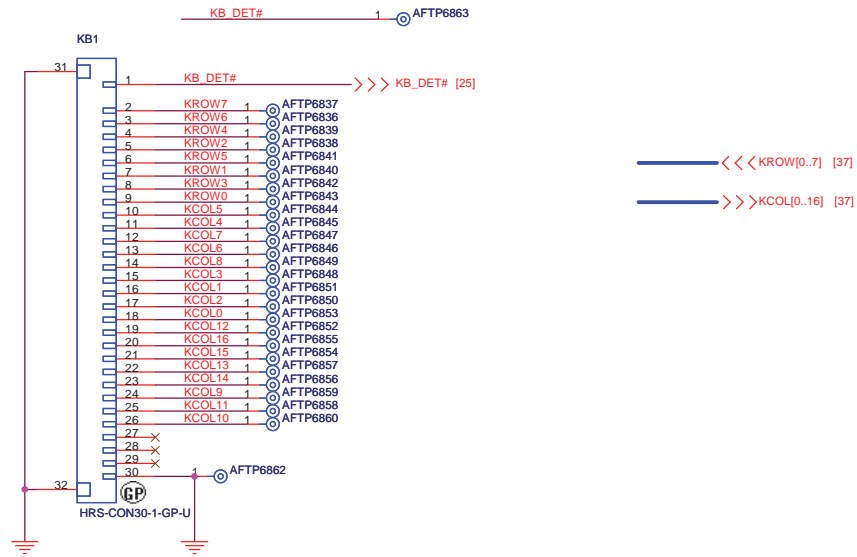
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<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
Custom	Vostro Calpella				X01
Date: Monday, January 18, 2010			Sheet	67	of 91

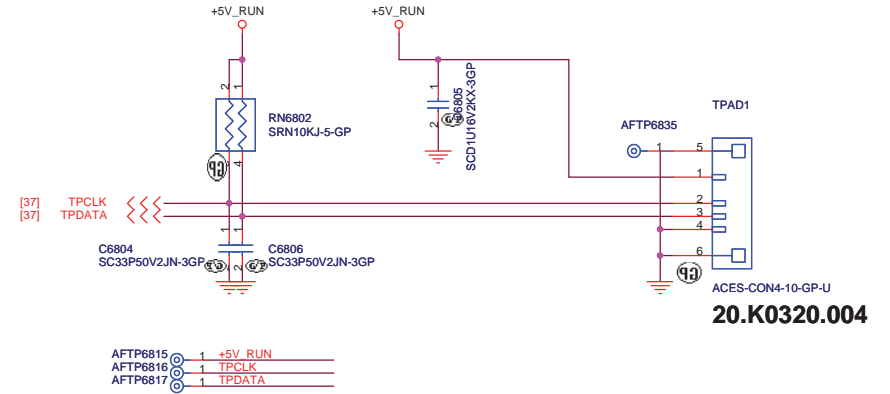
SSID = KBC

Internal Keyboard Connector

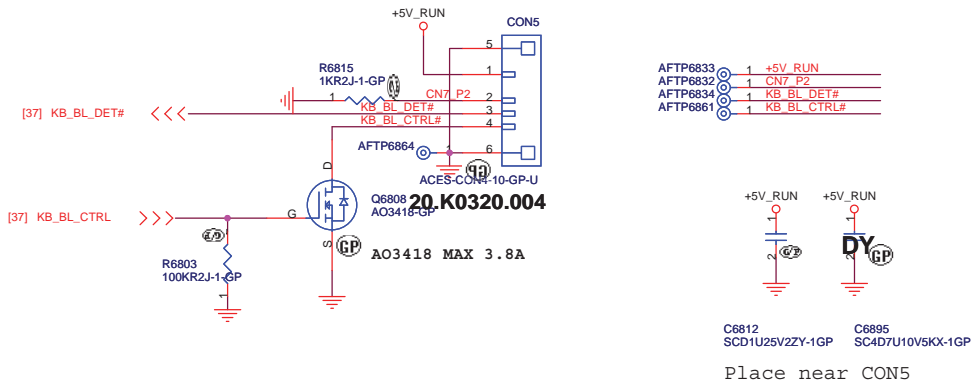


SSID = Touch.Pad

TouchPad Connector



KB Backlight CONN



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<Core Design>

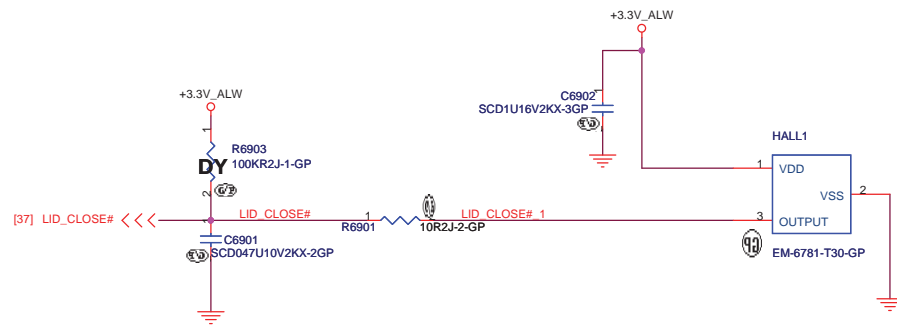
DELL Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title
Keyboard/Touch Pad

Size	Document Number	Rev
Custom	Vostro Calpella	X01

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Hall Sensor Connector

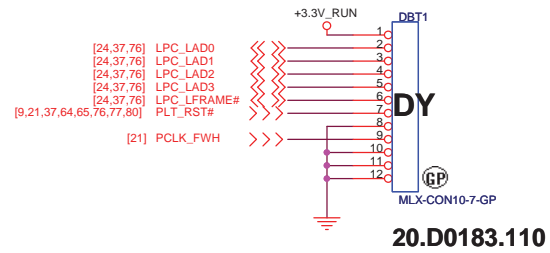


<http://laptop-motherboard-schematic.blogspot.com/>

<Core Design>


 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
Hall sensor		
Size	Document Number	Rev
Custom	Vostro Calpella	X01
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GOLDEN FINGER FOR DEBUG BOARD




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<Core Design>

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Title		
Debug port		
Size	Document Number	Rev
Custom	Vostro Calpella	X01
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<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
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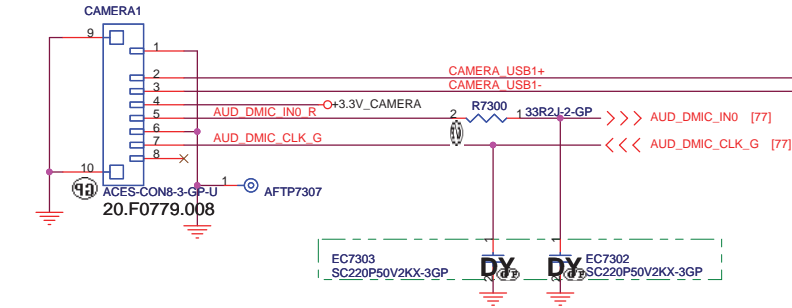
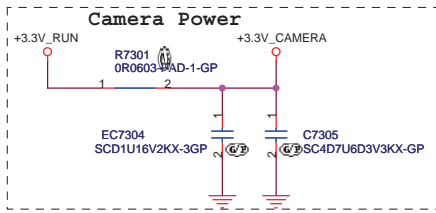
<http://laptop-motherboard-schematic.blogspot.com/>

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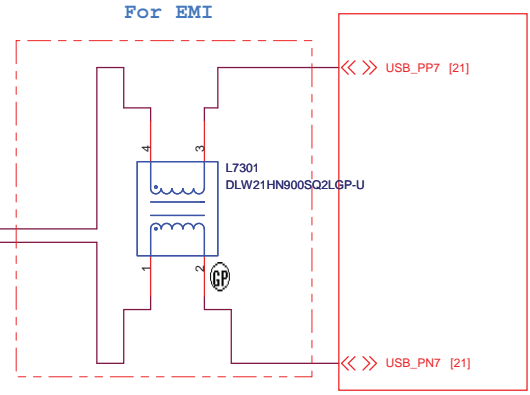
			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title					
(Reserve)					
Size	Document Number				Rev
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SSID = User.Interface

Camera Connector



- AFTP7303 ① AUD_DMIC_IN0 R
- AFTP7304 ① +3.3V_CAMERA
- AFTP7305 ① CAMERA_USB1-
- AFTP7306 ① CAMERA_USB1+



DW
01/18 Item 1

DW
01/06 Item 1
1.co-layout should not be allowed in X-build

DW
12/08 Item 5

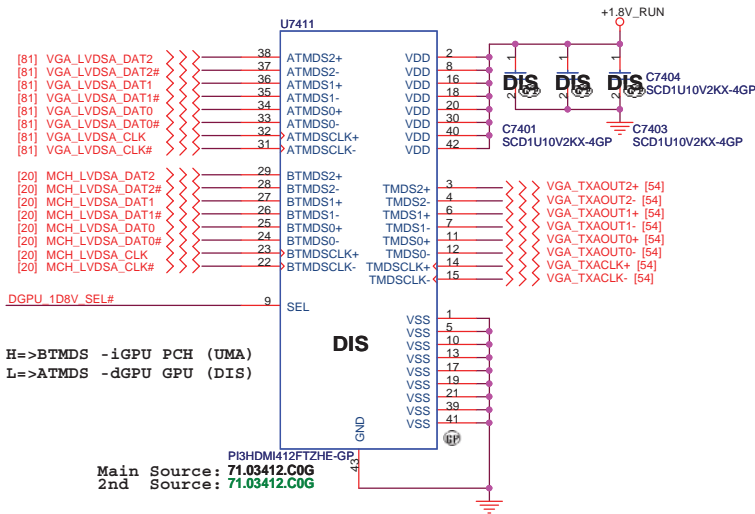
<Core Design>

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Title: **Camera CONN**

Size A3	Document Number	Rev
	Vostro Montevina Discrete	X01
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UMA/DIS LVDS signal select circuit



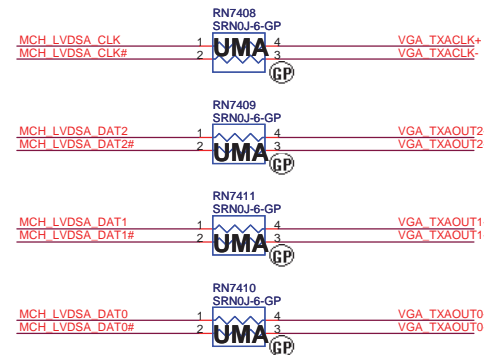
H=>BTMDS -iGPU PCH (UMA)
L=>ATMDS -dGPU GPU (DIS)

Main Source: 71.03412.C0G
2nd Source: 71.03412.C0G

FUNCTION TABLE

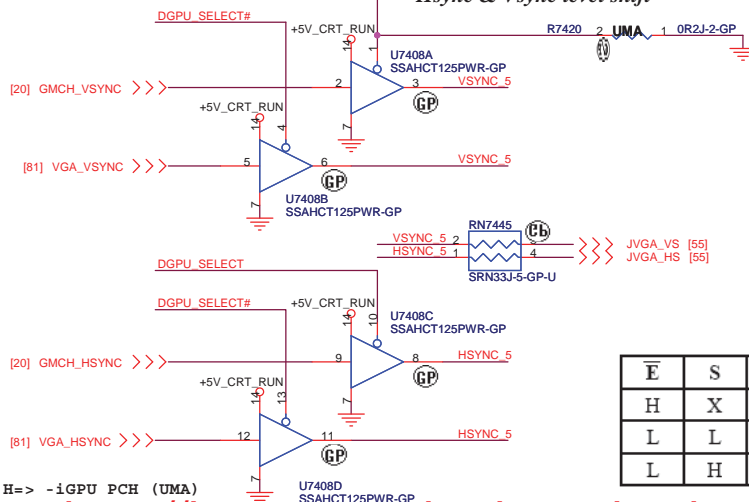
SEL	FUNCTION	OUTPUT
L	TMSn+ = ATMDSn+ TMSn- = ATMDSn- TMSCLK+ = ATMDSCLK+ TMSCLK- = ATMDSCLK- BTMDSn+ = High Impedance BTMDSn- = High Impedance BTMDSCLK+ = High Impedance BTMDSCLK- = High Impedance	TMSn+ TMSn- TMSCLK+ TMSCLK-
H	TMSn+ = BTMDSn+ TMSn- = BTMDSn- TMSCLK+ = BTMDSCLK+ TMSCLK- = BTMDSCLK- ATMDSn+ = High Impedance ATMDSn- = High Impedance ATMDSCLK+ = High Impedance ATMDSCLK- = High Impedance	TMSn+ TMSn- TMSCLK+ TMSCLK-

UMA LVDS signal circuit

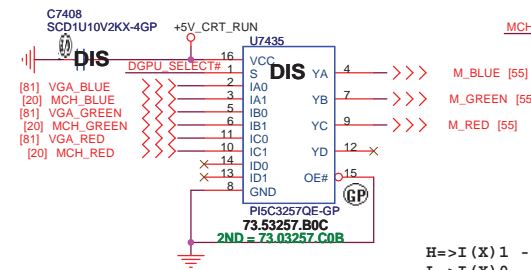


UMA/DIS CRT Hsync/Vsync select circuit

Hsync & Vsync level shift



UMA/DIS CRT signal select circuit



H=>I (X) 1 -iGPU PCH (UMA)
L=>I (X) 0 -dGPU GPU (DIS)

\bar{E}	S	YA	YB	YC	YD	Function
H	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Disable
L	L	IA0	IB0	IC0	ID0	S = 0
L	H	IA1	IB1	IC1	ID1	S = 1

<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.


Title: **Swith-1**

Size: Custom Document Number: **Vostro Calpella** Rev: **X01**

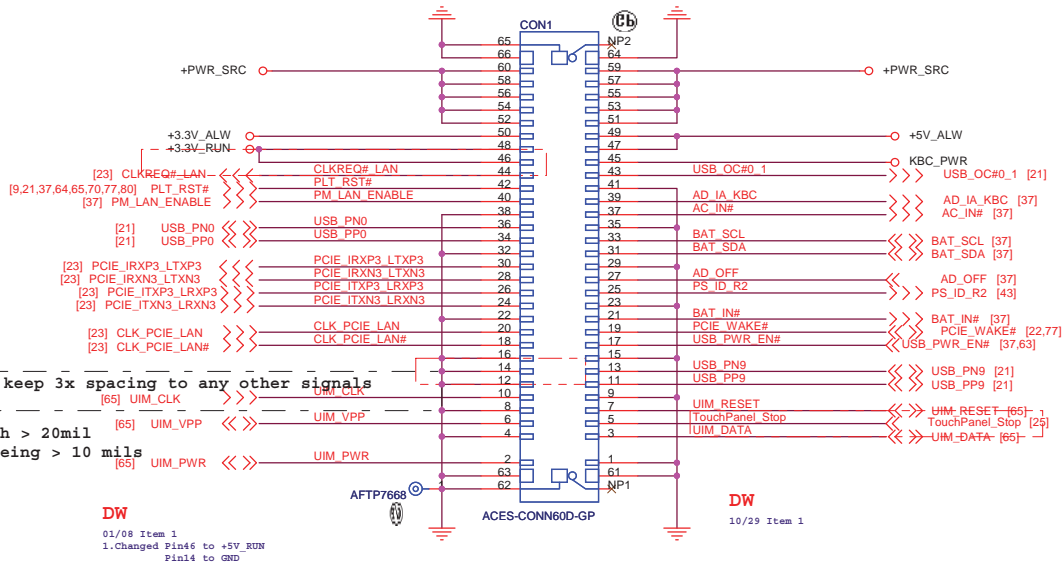
Date: Monday, January 18, 2010 Sheet 74 of 91

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<Core Design>

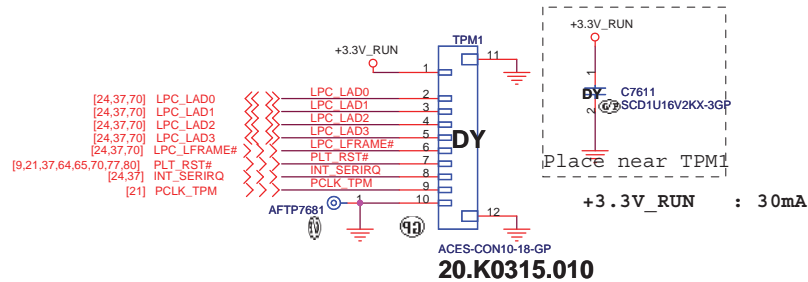
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title		
Reserve		
Size A3	Document Number Vostro Calpella	Rev X01
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DC_IN board CON



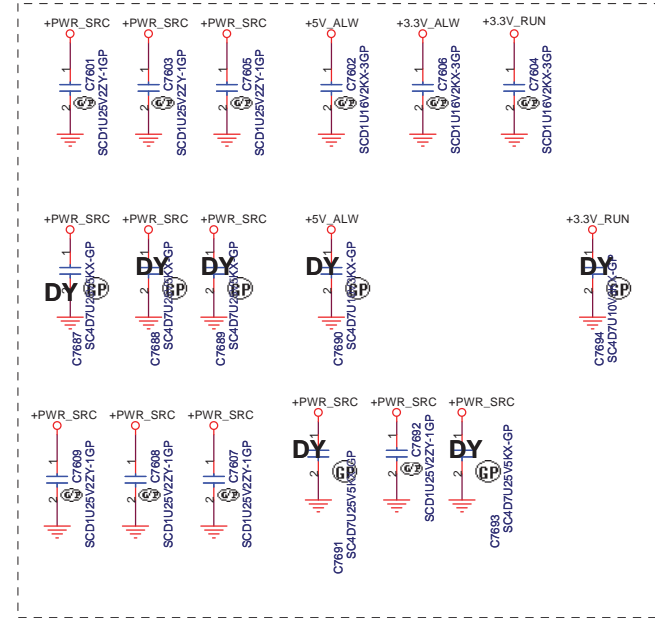
20.F1009.060

TPM board CON



20.K0315.010

Place near CON1



- +5V_ALW : 2000mA
- +3.3V_ALW : 347mA
- +3.3V_RUN/+5V_RUN:80mA (Touch Panel)
- KBC_PWR : < 1mA
- +PWR_SRC : Estimated by using battery 11.1V,85W

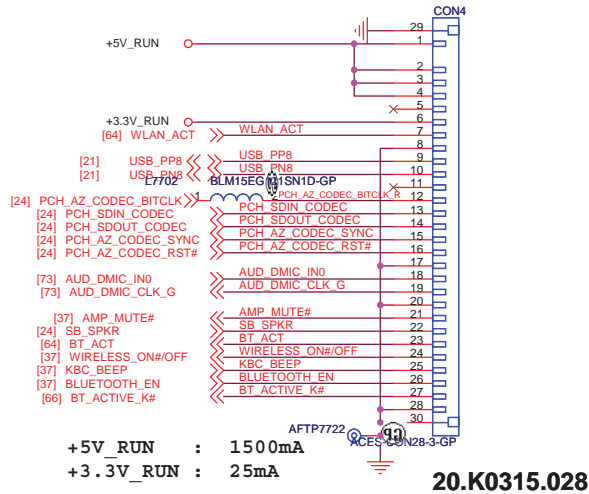
DW
01/08 Item 1
1.Remove DC-IN Board AFTP

<Core Design>

 Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Size	Document Number	Rev
Custom	Vostro Calpella	X01
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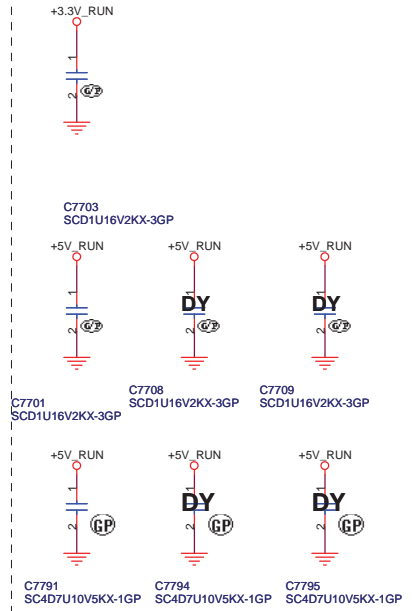
SSID = User.Interface

Audio board CON



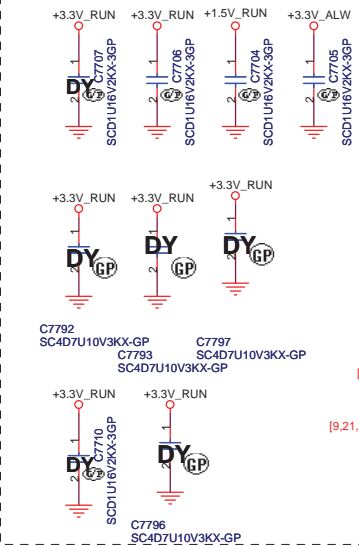
+5V_RUN : 1500mA
+3.3V_RUN : 25mA
20.K0315.028

Place near CON4



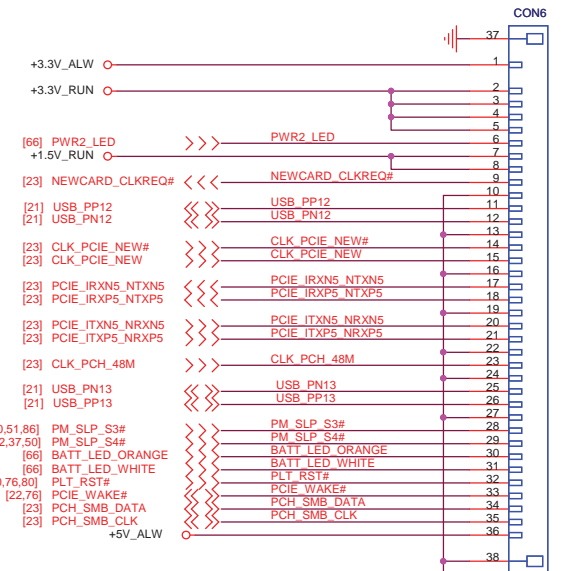
- AFTP7710 1 +5V_RUN
- AFTP7706 1 +3.3V_RUN
- AFTP7709 1 WIRELESS_ON#/OFF
- AFTP7702 1 WLAN_ACT
- AFTP7703 1 BLUETOOTH_EN
- AFTP7704 1 BT_ACTIVE_K#
- AFTP7705 1 BT_ACT
- AFTP7707 1 USB_PP8
- AFTP7708 1 USB_PN8
- AFTP7712 1 PCH_AZ_CODEC_BITCLK_R
- AFTP7713 1 PCH_SDIN_CODEC
- AFTP7714 1 PCH_SDOUT_CODEC
- AFTP7715 1 PCH_AZ_CODEC_SYNC
- AFTP7716 1 PCH_AZ_CODEC_RST#
- AFTP7718 1 SB_SPKR
- AFTP7719 1 KBC_BEEP
- AFTP7720 1 AUD_DMIC_IN0
- AFTP7721 1 AUD_DMIC_CLK_G
- AFTP7723 1 AMP_MUTE#

Place near CON6

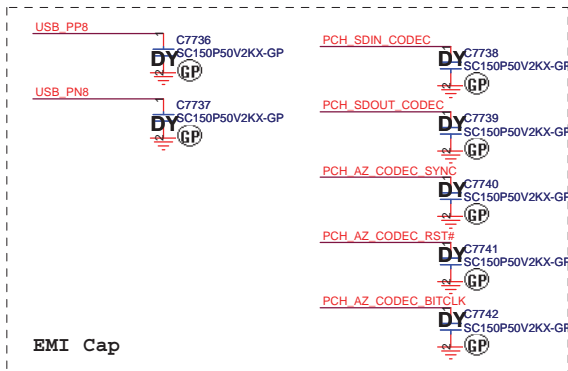


- AFTP7758 1 +3.3V_ALW
- AFTP7757 1 +3.3V_RUN
- AFTP7760 1 +1.5V_RUN
- AFTP7762 1 USB_PN12
- AFTP7759 1 USB_PP12
- AFTP7769 1 NEWCARD_CLKREQ#
- AFTP7768 1 PCH_SMB_CLK
- AFTP7767 1 PCH_SMB_DATA
- AFTP7777 1 PM_SLP_S3#
- AFTP7776 1 PM_SLP_S4#
- AFTP7773 1 BATT_LED_ORANGE
- AFTP7772 1 PWR2_LED
- AFTP7781 1 PLT_RST#
- AFTP7785 1 BATT_LED_WHITE
- AFTP7787 1 +5V_ALW
- AFTP7771 1 CLK_PCIE_NEW#
- AFTP7770 1 CLK_PCIE_NEW
- AFTP7781 1 PCIE_IRXN5_NTXN5
- AFTP7765 1 PCIE_IRXP5_NTXP5
- AFTP7764 1 PCIE_ITXN5_NRXN5
- AFTP7763 1 PCIE_ITXP5_NRXP5
- AFTP7775 1 USB_PN13
- AFTP7766 1 USB_PP13
- AFTP7774 1 PCIE_WAKE#
- AFTP7778 1 CLK_PCH_48M

IO board CON



+1.5V_RUN : 650mA
+3.3V_RUN : 1775mA
+3.3V_ALW : 275mA
+5V_ALW : 60mA
20.K0315.036



EMI Cap

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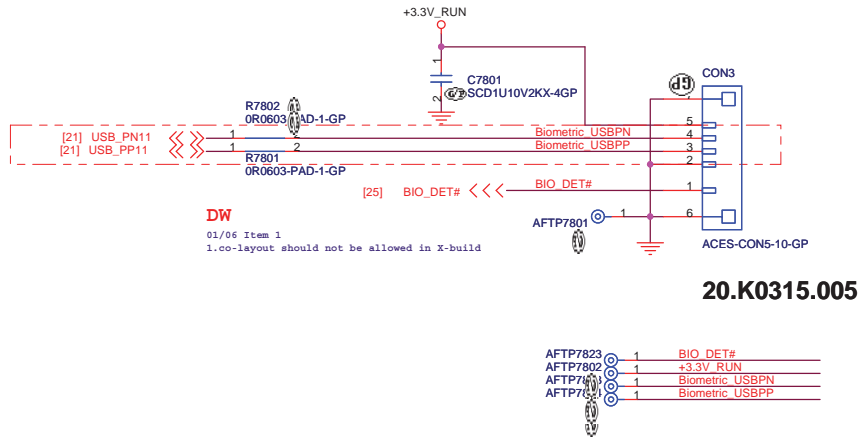
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Title: **Audio BD/IO BD CONN**

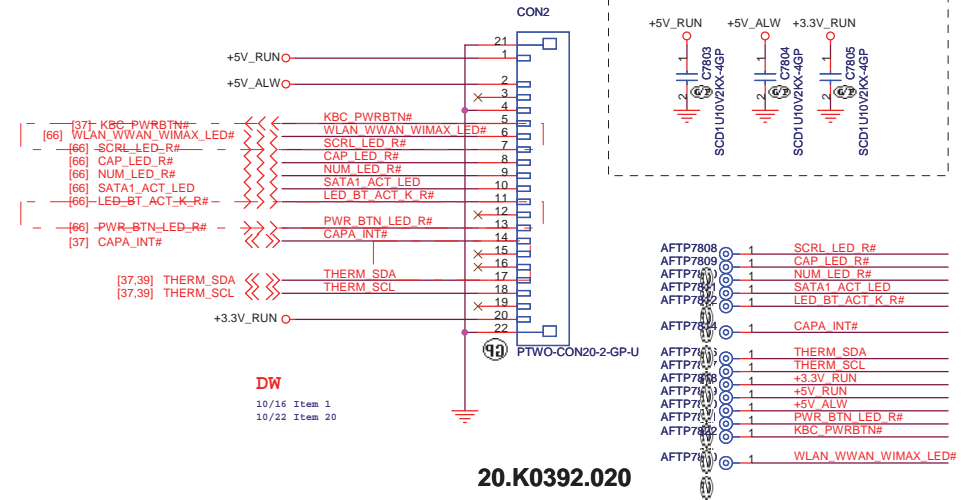
Size: Custom Document Number: **Vostro Montevina Discrete** Rev: **X01**

Date: Monday, January 18, 2010 Sheet 77 of 91

Finger Printer Connector

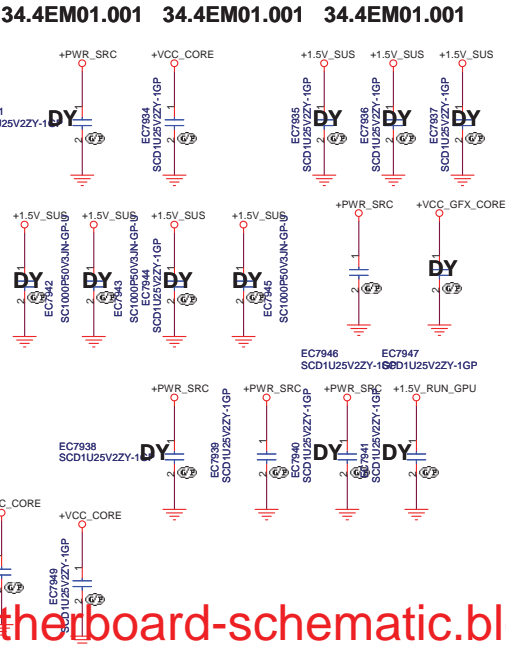
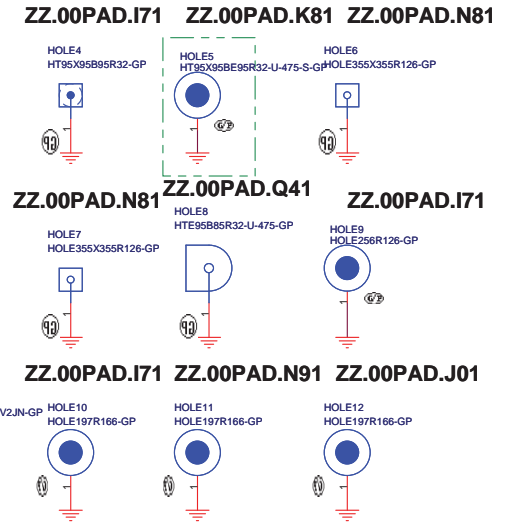
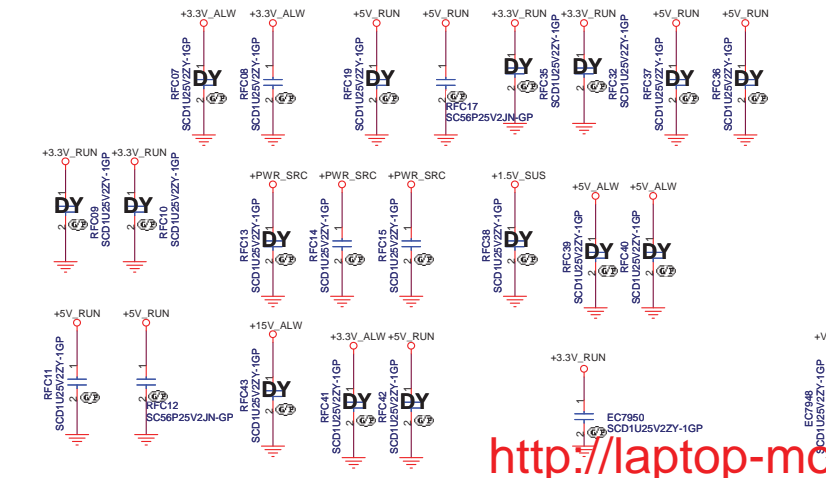
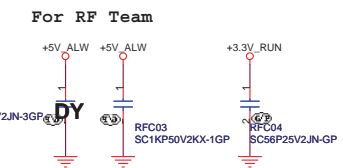
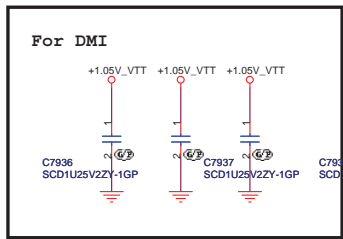
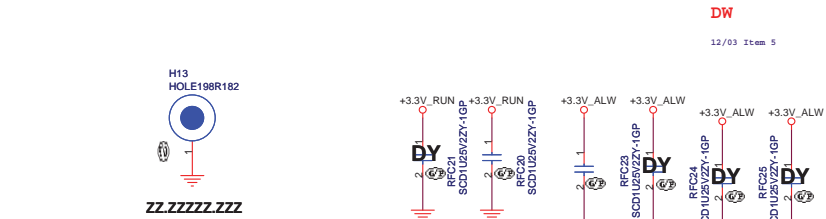
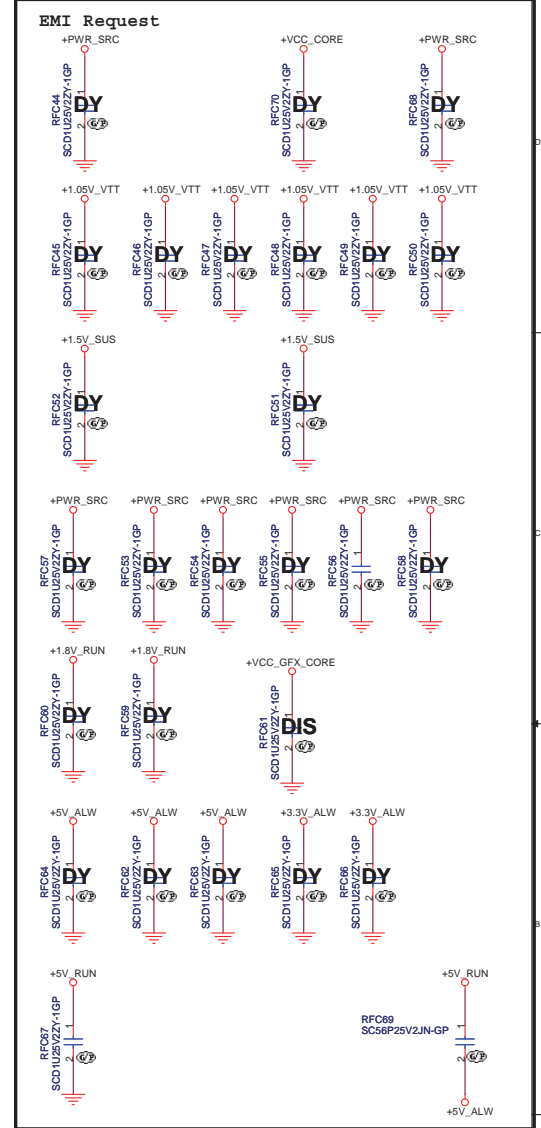
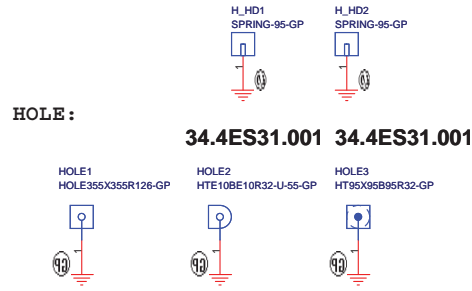
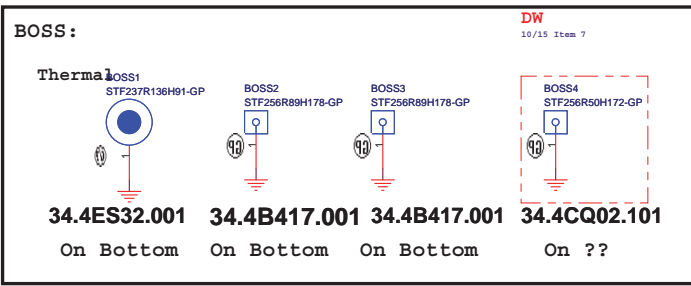


LED&Capacity board CONN



+3.3V_RUN : 3.5mA
 +5V_RUN : 240mA
 +5V_ALW : 80mA

SSID = Mechanical



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Miscellaneous Components

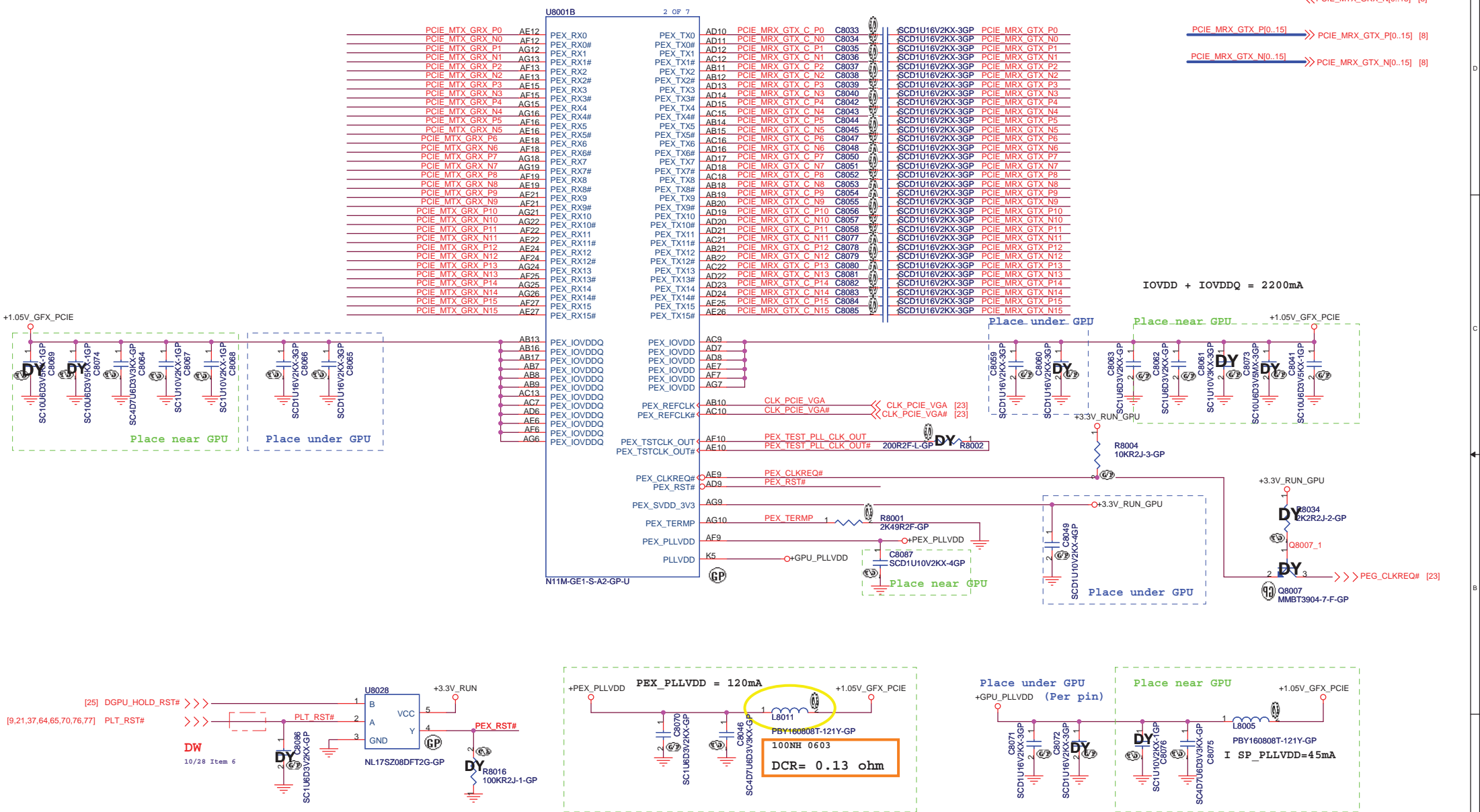
Wistron Calpella

File: [] Drawing No: [] Rev: **X01**

Date: Monday, January 18, 2010 Sheet 79 of 91

SSID = VIDEO

PCIE MTX GRX P[0..15] << PCIE_MTX_GRX_P[0..15] [8]
 PCIE MTX GRX N[0..15] << PCIE_MTX_GRX_N[0..15] [8]
 PCIE MRX GTX P[0..15] >> PCIE_MRX_GTX_P[0..15] [8]
 PCIE MRX GTX N[0..15] >> PCIE_MRX_GTX_N[0..15] [8]



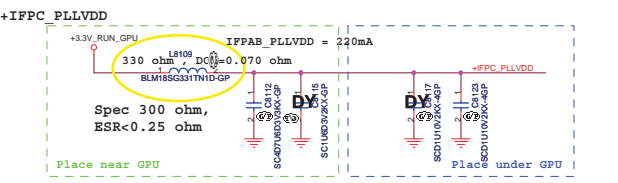
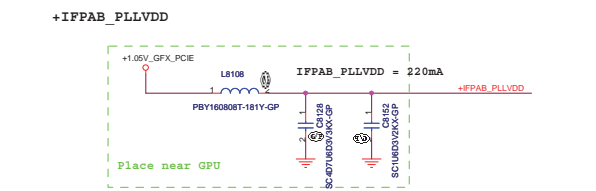
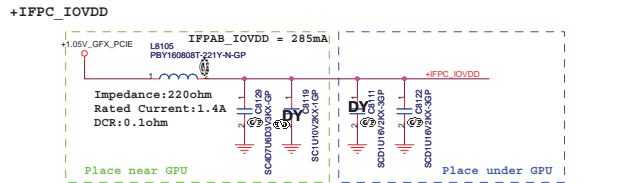
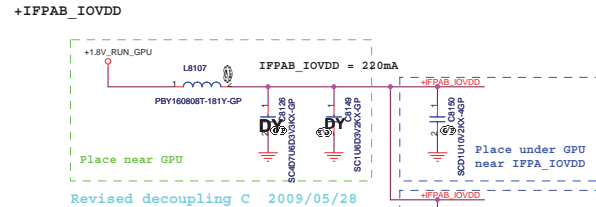
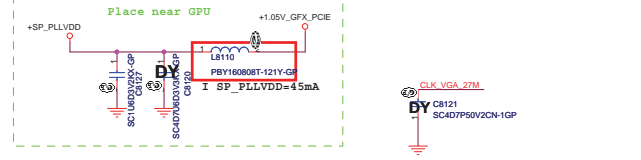
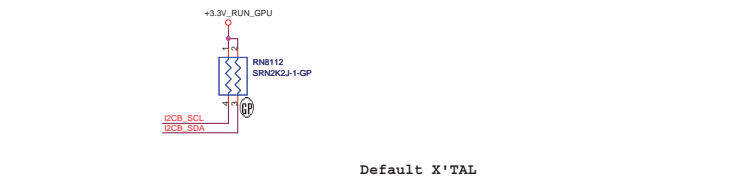
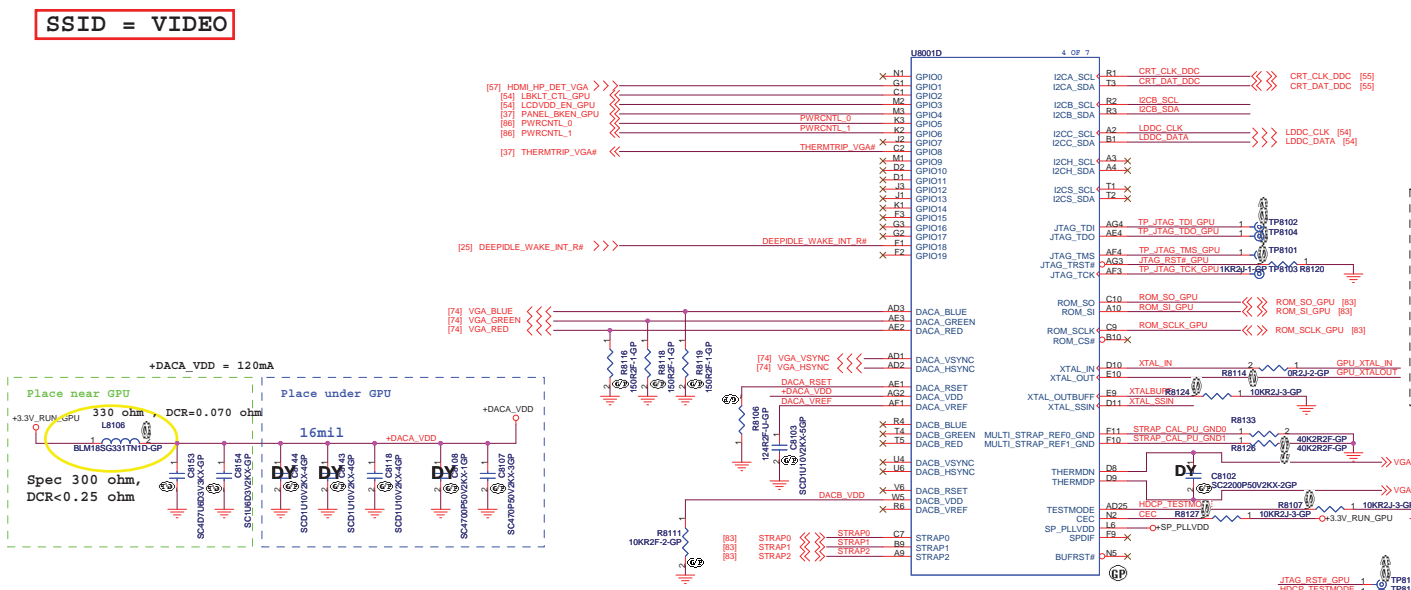
<Core Design>

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Title: **VGA-PCIE/LVDS(1/4)**

Size A3	Document Number	Rev
	Vostro Calpella	X01
Date: Monday, January 18, 2010	Sheet 80 of 91	

SSID = VIDEO



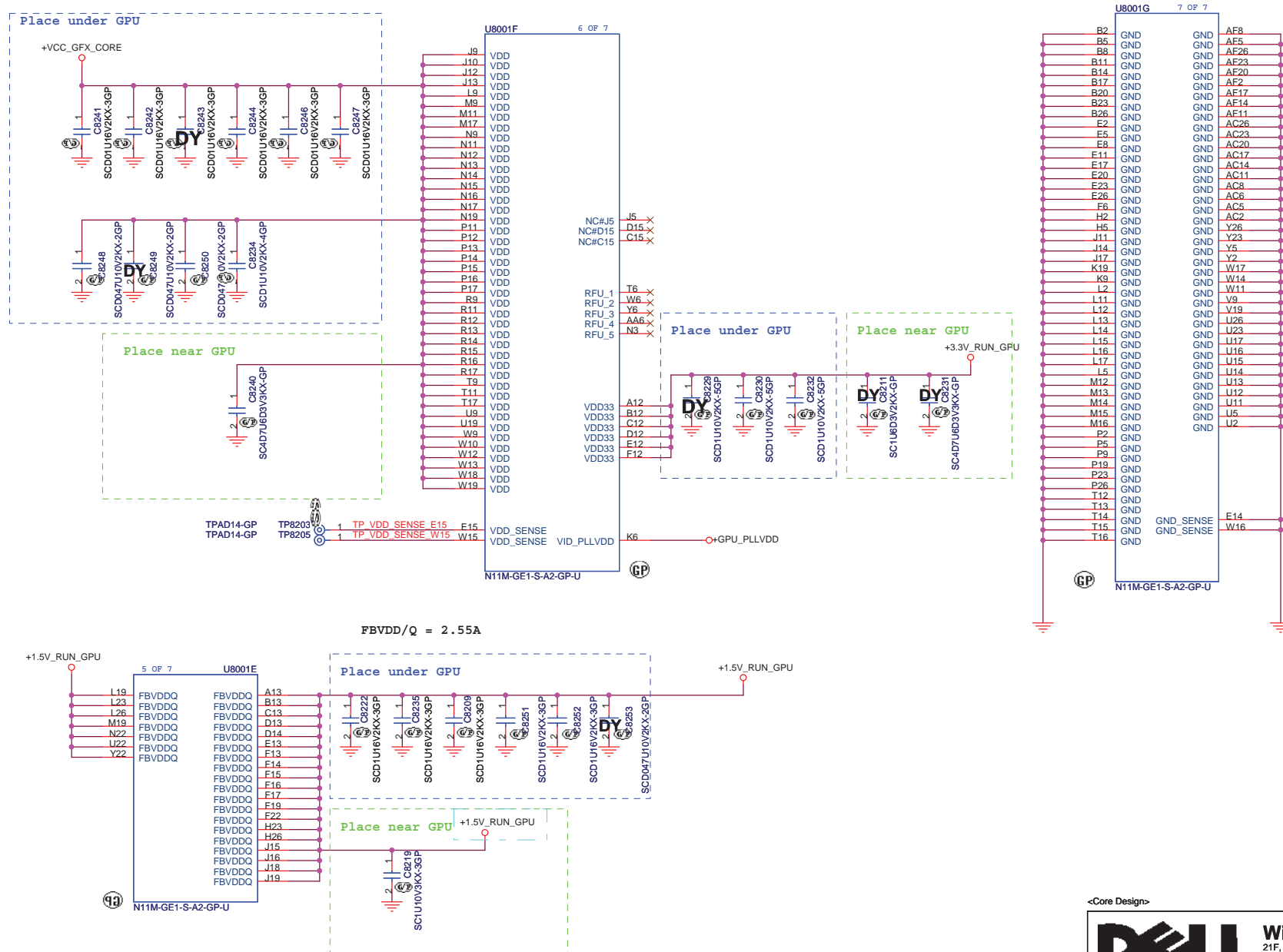
«Core Design»

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21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsien 221, Taiwan, R.O.C.

Title: **VGA-LVDS/CRT/DP PORT**

Size: A4 Document Number: **Vostro Calpella** Rev: **X01**

Date: Monday, January 18, 2010 Sheet: 81 of 91



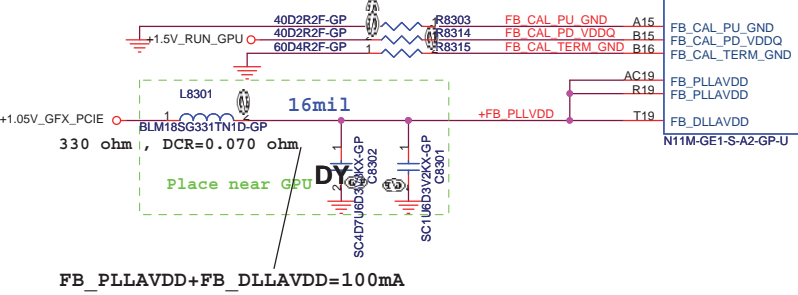
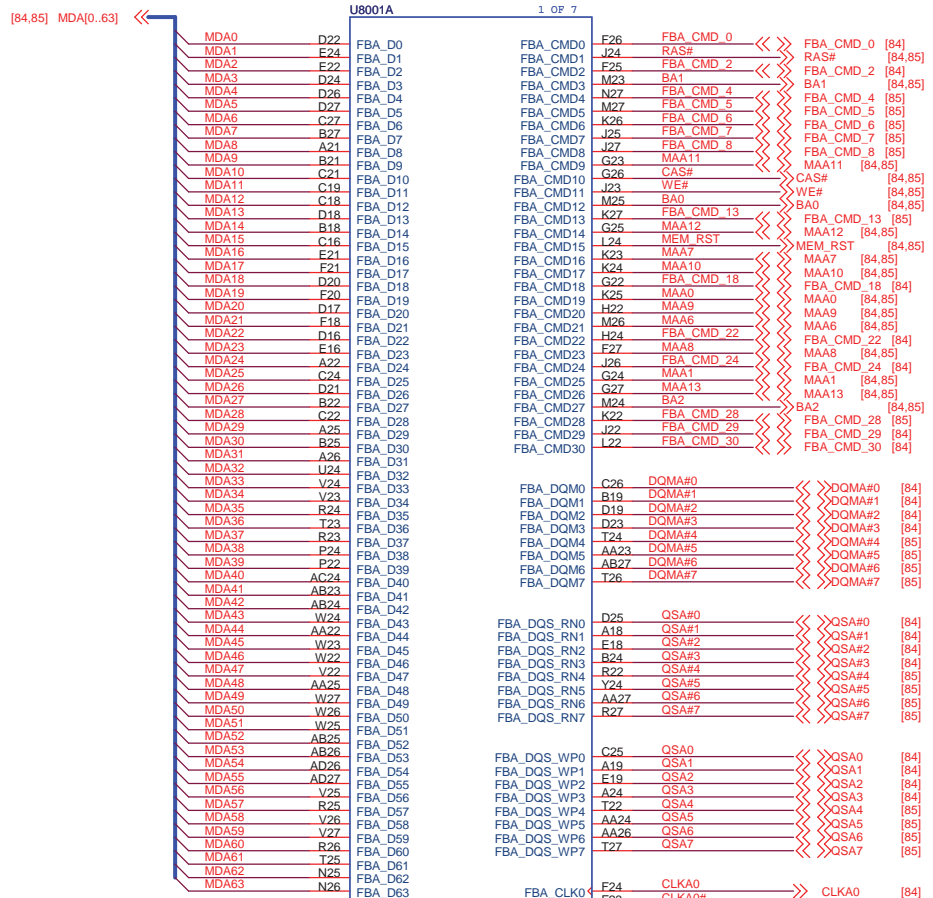
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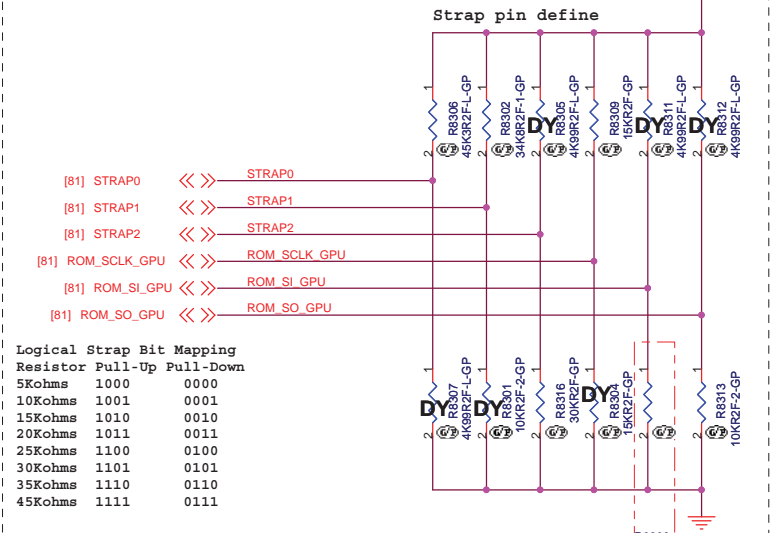
Title: **VGA-POWER/GND(3/4)**

Size A3	Document Number Vostro Calpella	Rev X01
Date: Monday, January 18, 2010	Sheet 82	of 91

SSID = VIDEO



Strap pin resistor need use 1% resistor (NV Design Guide)



Logical Strap Bit Mapping

Resistor Pull-Up	Pull-Down
5Kohms 1000	0000
10Kohms 1001	0001
15Kohms 1010	0010
20Kohms 1011	0011
25Kohms 1100	0100
30Kohms 1101	0101
35Kohms 1110	0110
45Kohms 1111	0111

Strap0	Strap1	Strap2	
USER_BIT0 1	3GIO_PADCFG_LUT_ADR0 0	PCI_DEVID_0 1	DW
USER_BIT1 1	3GIO_PADCFG_LUT_ADR1 1	PCI_DEVID_1 0	01/15 Item 1
USER_BIT2 1	3GIO_PADCFG_LUT_ADR2 1	PCI_DEVID_2 1	
USER_BIT3 1	3GIO_PADCFG_LUT_ADR3 1	PCI_DEVID_3 0	

EDID is used Reserved N11M-GE1 GPU Device ID=0x0A75

ROM_SI_GPU	ROM_SO_GPU	ROM_SCLK_GPU	
RAM_CFG0	VGA_DEVICE 1	PEX_PLL_EN_TERM	0
RAM_CFG1	SMB_ALT_ADDR 0	SLOT_CLK_CONFIG	1
RAM_CFG2	FB_0_BAR_SIZE 0	SUB_VENDOR	0
RAM_CFG3	XCLK_417 0	PCI_DEVID_4	1

Default setting: SAMSUNG sDDR3 64Mx16BIT-->20K pull down (0x0011)

RAM_CFG[3:0]	Config	FB_BUS Width	Definitions
0000			
0001			
0010	64MX16 DDR3 64Bit	Hynix	
0011	64MX16 DDR3 64Bit	Samsung	Default
0100			
0101			
0110			
0111			

If use Hynix sDDR3 64Mx16BIT(0x0010), R8308 change to 15K

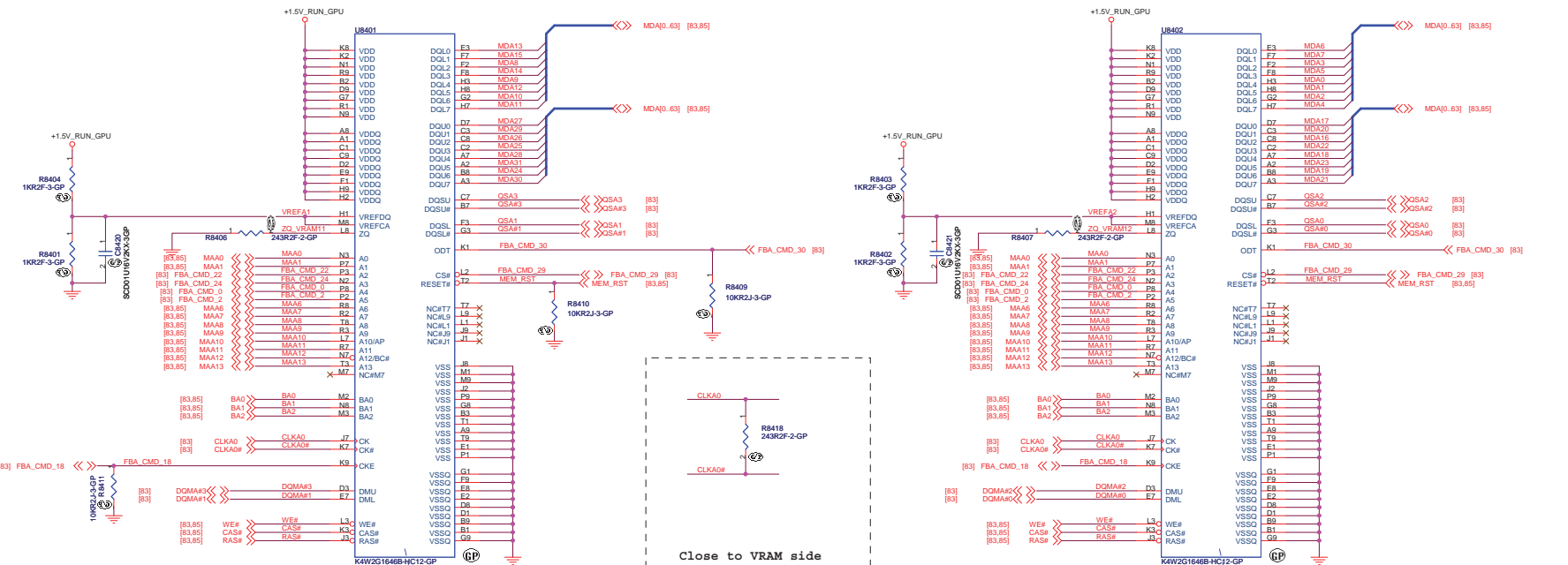
SUB_VENDOR	XCLK_417	PEX_PLL_EN_TERM
0 No VBIOS ROM	0 277MHz(POR)	0 Disable (POR)
1 BIOS ROM present	1 Reserved	1 Enable

3GIO_PADCFG USER[3:0]
 0000 Desktop 1111 Use EDID to detect panel settings
 1110 Notebook (POR)

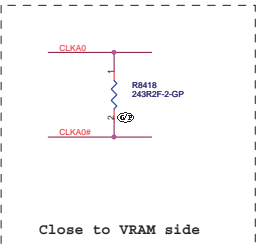
SLOT_CLOCK_CFG
 0 GPU and MCH do not share a common reference clock
 1 GPU and MCH share a common reference clock (POR)



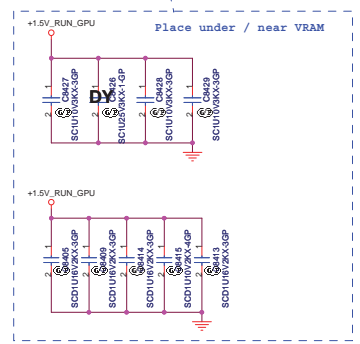
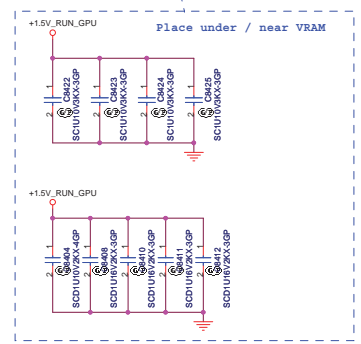
Title		VGA-MEMORY/STRAPS(4/4)	
Size A3	Document Number	Vostro Calpella	
Date: Monday, January 18, 2010	Sheet 83	of	91



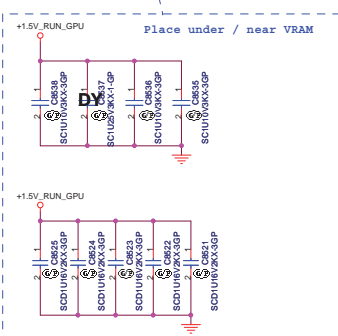
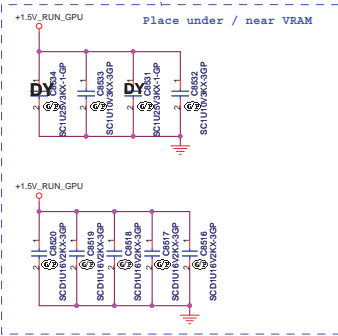
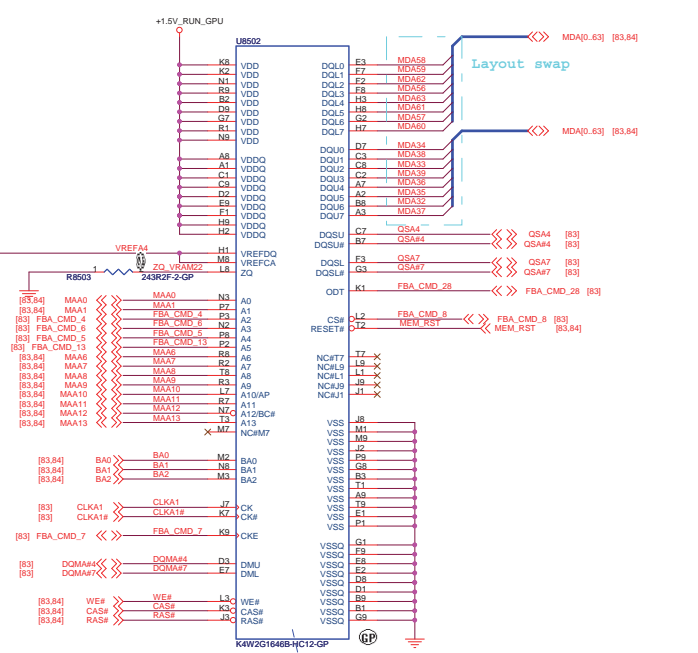
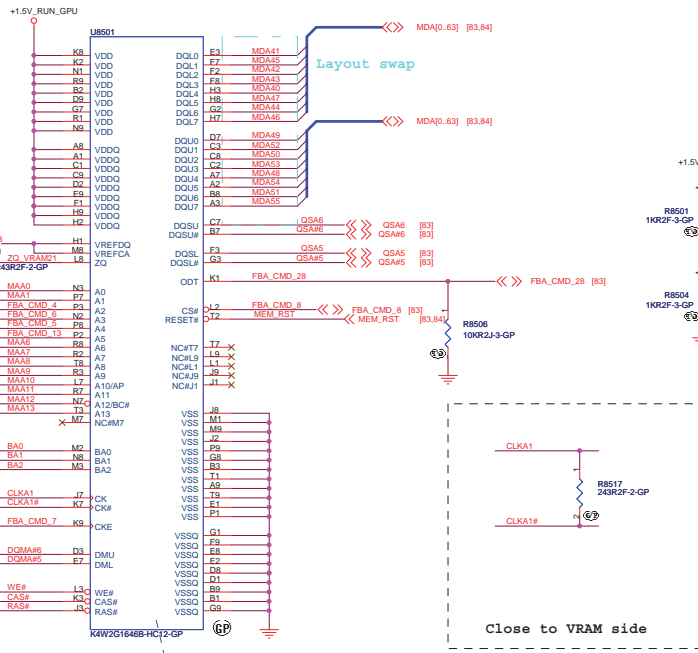
64X16 SAMSUNG K4W1G1646E-HC12 P/N:72.41164.H0U
 64X16 HYNIX H5TQ1G63BFR-12C P/N:72.51G63.C0U



Close to VRAM side

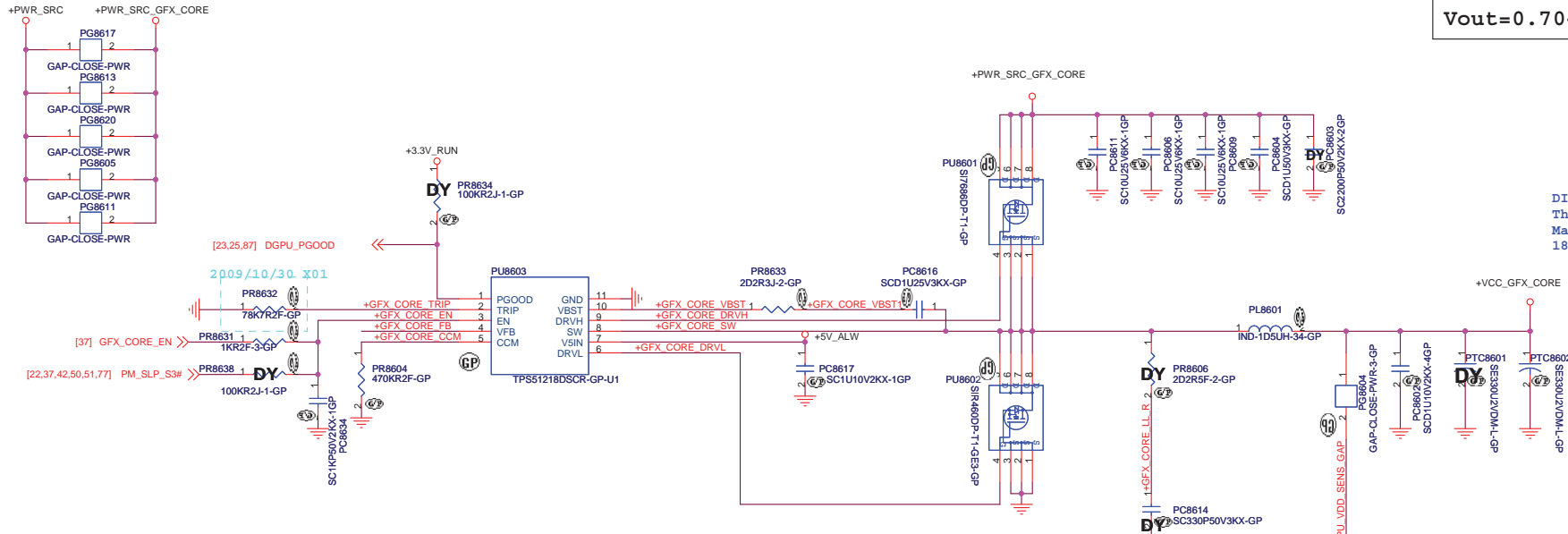


SSID = VIDEO



SSID = PWR.Plane.Regulator_GFX

$$V_{out} = 0.704V * (R1 + R2) / R2$$

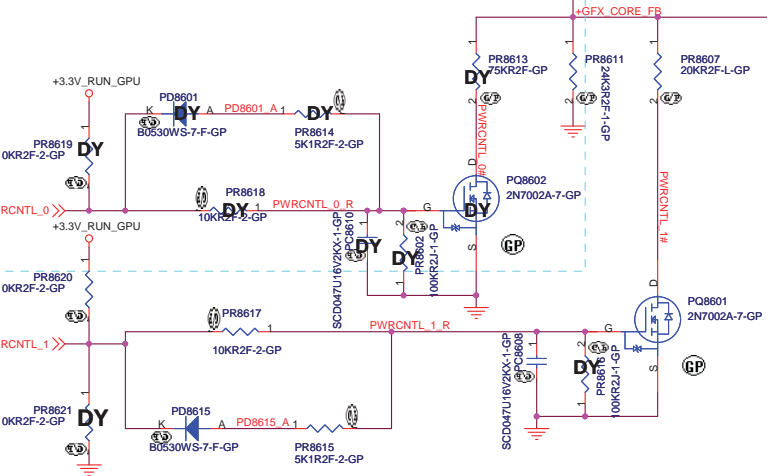


DIS
Thermal Design Current = 12.9A
Max Current = 16.77A
18.45A < OCP < 21.81A

Frequency setting
470K --> 290KHz
200K --> 340KHz
100K --> 380KHz
39K --> 430KHz

PWRCNTL_0	PWRCNTL_1	+VCC_GFX_CORE
L	H	1.03V
L	L	0.85V

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 1.5UH PCMC104T-1R5MN Cynotec DCR:4.2mohm Isat =33Arms 68.1R510.10J
O/P cap: 330U 2V BEF5X0D331ER 9mOhm 3Arms Panasonic/ 79.33719.L01
H/S: SI7686DP/ POWERPAK-8/ 11mOhm/14mOhm@4.5Vgs/ 84.07686.037
L/S: SiR460DP/ POWERPAK-8/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037
Switching freq-->350KHz

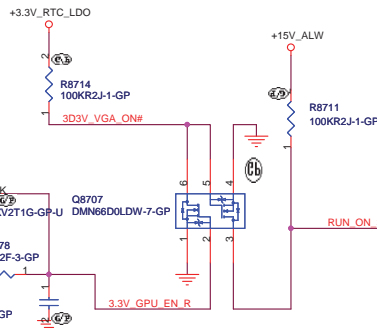


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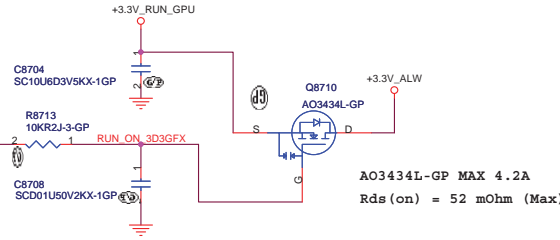
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Title		
TPS51218 +VCC GFX CORE		
Size	Document Number	Rev
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+3.3V_RUN_GPU

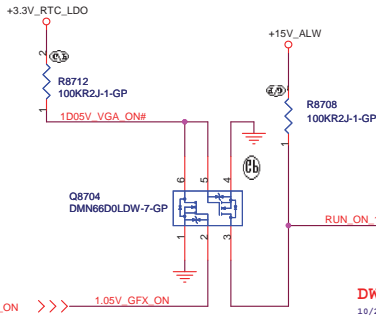


Peak current: 1140 mA
Design current: 798 mA

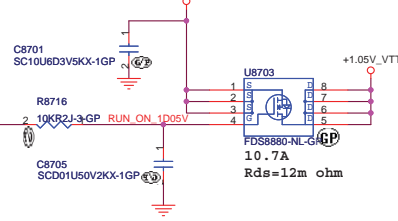


AO3434L-GP MAX 4.2A
Rds(on) = 52 mOhm (Max)

+1.05V_GFX_PCIE:

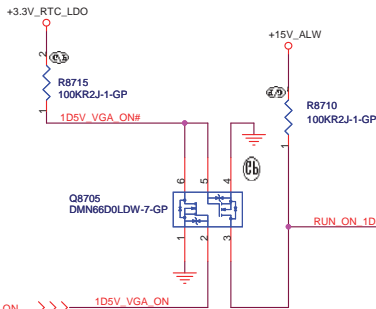


Peak current: 3550 mA
Design current: 2485 mA



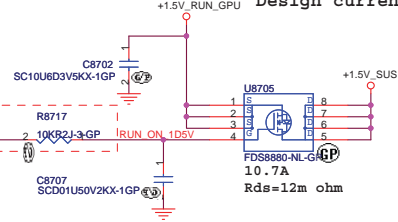
FDS8880-NL-G
10.7A
Rds=12m ohm

+1.5V_RUN_GPU:



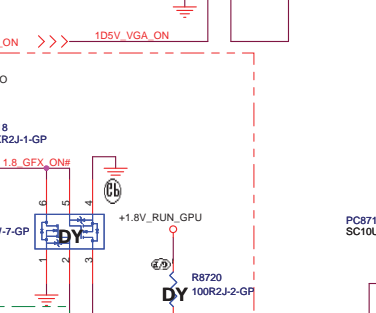
Place near device side(VGA chip),
use 10 mil trace between power
rail and Q8701 Drain

Peak current: 4230 mA
Design current: 2961 mA

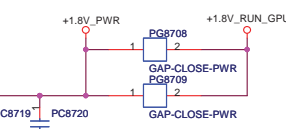
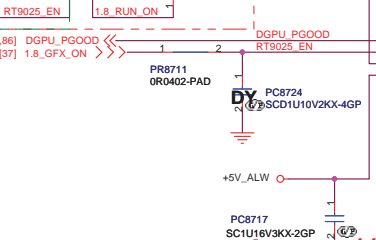


FDS8880-NL-G
10.7A
Rds=12m ohm

+1.8V_RUN_GPU



DIS:
Peak current: 300 mA
Design current: 210 mA



$Vo = 0.8 * (1 + (R1/R2))$

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LDO 1.8V

Date: Monday, January 18, 2010 Sheet 87 of 91

DATE	VERSON	ITEM	PAGE	Modify List	Issue Description	OWNER
2009/10/15	X01	1	25	Swapped Q2515 C,E Pin	For correct.	EE
		2	All	Combine pull-up/down resistors from single to series resistor	For save more part counts	EE
		3	37	Update 10mW circuit.	For DC mode power consumption can be less than 10mW under S5.	EE
		4	22	Add U2213,R2221	Added 3v/5v S5 power good to control resume reset sequence circuit prevent RTC data loss.	EE
		5	51	stuffed PC5105 with 1uF	For power sequencing of +1.8V_RUN , Delay timing	EE
		6	23	Added 25M Crystal	For DCI (DisplayClock_Integration)	EE
		7	79	Added BOSS4	For Steady the thermal module	EE
		9	All	BOSS1 from 34.4W005.001 to 34.4CQ03.101 CON3 from 20.K0315.005 to 20.K0293.006 CON4 from 20.K0315.028 to 20.K0275.028 CON6 from 20.K0315.036 to 20.K0276.036 DM1 from 62.10017.U81 to 62.10017.P31 DM2 from 62.10017.U71 to 62.10017.Q31 HOLE1 from ZZ.00PAD.I71 to ZZ.00PAD.G51 HOLE2 from ZZ.00PAD.K81 to ZZ.00PAD.E11 HOLE3 from ZZ.00PAD.N81 to ZZ.00PAD.D71 HOLE4 from ZZ.00PAD.N81 to ZZ.00PAD.D71 HOLE5 from ZZ.00PAD.K11 to ZZ.00PAD.E11 HOLE6 from ZZ.00PAD.I71 to ZZ.00PAD.G51 HOLE7 from ZZ.00PAD.I71 to ZZ.00PAD.G51 HOLE8 from ZZ.00PAD.N91 to ZZ.00PAD.D31 HOLE9 from ZZ.00PAD.J01 to ZZ.00PAD.D11 LCD1 from 20.F1093.040 to 20.F1555.030 TPAD1 from 20.K0320.004 to 20.K0265.004	For ME request Changed connect PN:	ME
		2009/10/16		1	37,87	Removed CAPA_RST# from Capacity board
				Added Switch Baord Detection circuit	For software request.	EE
2009/10/19		1	77	Reversal CON6 Pin 36 <-> 1 ; 35 <-> 2	For new connect pin define.	EE
		2	9,27	Changed RN907,L2701,L2704	For update components	EE
		3	74	Swapped the RN7408,RN7409,RN7410,RN7411	For Layout request.	EE

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Title: **Change List - EE(1)**

Size: Custom Document Number: **Vostro Calpella** Rev: **X01**

Date: Monday, January 18, 2010 Sheet 88 of 91

DATE	VERSION	ITEM	PAGE	Modify List	Issue Description	OWNER
2009/10/19	X01	1	21,23	Changed EDID_SELECT# pin from PCH_GPIO66 to PCH_GPIO5	For fixed glitch.	EE
2009/10/22		1	All	Swapped resistance	For Layout request.	EE
		2	64,65 66,78	Merge WWAN and WLAN LED	Update SPEC	EE
		3	All	DM1 from 62.10017.U81 to 62.10017.P31 DM2 from 62.10017.U71 to 62.10017.Q31 HOLE5 from ZZ.00PAD.K11 to ZZ.00PAD.K81 TPM1 from 20.K0238.010 to 20.K0315.010 WLAN1 from 20.F1286.052 to 62.10043.841 WWAN1 from 20.F1286.052 to 62.10043.841 Update H13 Footprint	For ME request Changed connect PN	ME
		4	24	X2401 from 82.30001.691 to 82.30001.A81	Update component	EE
		5	9,42 50	Stuff "S3 Power Reduction" circuit reserve component	Update schematic base on test result.	EE
2009/10/27		1	79	Add RFC7907 +5V ALW to GND 33pF Cap Add RFC7908 +5V ALW to GND 0.1uF Cap Add RFC7909 +3.3V RUN to GND 0.1uF Cap		RF
		2	All	Changed power rail netname from +1.5V_CPU to +1.5V_RUN	Merge +1.5V_CPU to +1.5V_RUN ,For CosDown.	EE
2009/10/28		1	42 87	Del U4204,R4213,C4206,R4215,R4217,R4218 Del Q8701,R8709	Remove +1.5V_RUN GPU discharge circuit,base on test result.	EE
		2	26	Add Q8706,R8718,R8720	Reserve +1.8V_RUN GPU discharge circuit,base on test result.	
		3	26	Del U2601,C2629,C2628	Remove reserve circuit +3.3V_CRT_LDO Circuit for LDO Regulators,base on test result.	
		4	25	Del R2602	Remove reserve resistor,For save more part counts	
		5	27	Del R2517	Remove reserve pull-Hi resistors,For not use it	
		6	80	Del R2708	Remove reserve resistor,For save more part counts	
		7	57	Del R8039	Remove reserve resistor,For save more part counts	
2009/10/29		8	37	Add R5773 between +5V_HDMI_C and +5V_HDMI.	dummy D5703 Stuff R5773 ,For save more part counts base on test result.	
		1	25,76	Add SW1	Add mine switch to control PWR_BTN , Only on Sample stage	
2009/12/03	SC	1	24,63 79	Assign PCH_GPIO35 for TouchPanel Stop.. Rename RFC***, USBESATAL Part Referse	Add TouchPanel Stop Pin to control ON/OFF by PCH_GPIO35 Rename Part Referse Ex: USBESATAL to ESATAL for manufactory request	EE
		2	37	Add R3720 damping resistor.	Add damping resistor for signal improvement	EE
		3	37	Add R3703,U3703,C3705	Co-layout MUX and OR gate for BLON to solve white screen issue while iGPU to dGPU.	EE
		4	87	Changed Net Connect	Changed Q8706.2 from 1.8 GFX_ON to RT9025_EN ,For correct.	EE
2009/12/08	SC	5	79	For ME request Changed below connect PN:	Change P/N of "HOLE5" from ZZ.00PAD.K81 to ZZ.00PAD.Q41.	ME
		1	38	Add PR8621 Pull-Lo resistor.	Reserve for control. +VCC_GFX_CORE power rail default to 0.85.	EE
		2	42	Add Q4205,Q4206,R4220,R4221	Added discharge circuit for +5_RUN,+3_RUN.	EE
2010/01/11	X-Build	1	76	Del AFTP7634 ~ 7662; 7664-7667 ;7669;7672;7302	Del AFTP For saved more layout space.	EE
		2	51	PR5102 short ; replacing PC5105 by 10K resistor to GND	prevent PM_SLP_S3# signal rebound	EE
		3	All	Mount EMI_CHOKE or Reserve colse Gap for Differential-Pair	Co-layout should not be allowed in X-build.	EE
		4	23	Del RN2327 , Reserve colse Gap	For saved more layout space.	EE
		5	37,62	Reserve threadhold 2.93V reset IC (74.00690.I7B) in PURE_HW_SHUTDOWN# pin	Reserve For Flash ROM Damaged Issue.	EE
2010/01/18	X-Build	1	21,73	Reserve Pull-Lo resistor for SPI_WP#. Swap Camera USB Port from Port-10 to Port-7	For Camera USB issue	EE

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File: **Change List - EE(2)**

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DATE	VERSION	ITEM	PAGE	Modify List	Issue Description	OWNER
2009/10/19	X01	2	81	Remove R8149	For EMI team request	EMI
			21	PCLK_FWH、CLK_PCI_FB、PCLK_KBC、PCLK_TPM reserve by pass cap		
			23	CLK_PCH_48M reserve by pass cap		
			23	Romove R2350 and C2324		
			37	Romove R3726 and C3704		
			79	Reserve +PWR_SRC to GND cap		
2009/10/22		3	79	Add EC7934 0.1u in +VCC_CORE	For EMI team request	EMI
				Add EC7911 0.1u +1.5V_SUS to GND cap*1		
				Add EC7935,EC7936 0.1u +1.5V_SUS to GND cap*2		
				Add EC7937 0.1u +1.5V_SUS to GND cap*1		
				Add EC7938 0.1u +PWR_SRC to GND cap*1		
				Update TR6304,TR6305 p/n to 68.00201.141		
2009/10/23		4	73	Move EC7302	For EMI team request	EMI
			79	dummy 0.1u x 2 in green area 6135,195 ----EC7939,EC7940		
				dummy 0.1u cap in red area 1755,4435 ----EC7941		
				dummy 1000p in green area 5225,6950----EC7942		
				dummy 1000p in green area 3780,6180----EC7943		
				dummy 104p and 1000p in green area 5385,7010---EC7944,EC7945		
				dummy 0.1u in green area 3400,6300---EC7946		
				dummy 0.1u in green area 1240,4035--EC7947		
			55	add damping 33ohm on R,G,B Singel---R5594,R5595,R5596		
2009/12/08	SC	1	79	mount EC7948,EC7949,EC7934	For RF Team request	RF
2009/12/09	SC	1	73	mount LECM2012H-900QT-GP in L7301	For EMI team request	EMI
		2	24,77	change R2405 from 10 ohm to 56 ohm and mount 120 ohm bead bead p/n:BLM15EG121SN1 L7702		
		3	73	mount 220p cap on EC7302 and EC7303		
		4	79	Add EC7950		

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